## 軍商兩用貨品及技術出口管制清單及一般軍用貨品清單 新、舊版修正對照與翻譯

## 編列說明

- 1. 軍商兩用貨品及技術出口管制清單列入第一項,一般軍用貨品清單列入第二項。
- 2. 本對照表列出下列情況:
  - a. 有增/刪語詞,變更標點符號,且意義有所變更者;
  - b. 舊版無、新版新增之內容;
  - c. 舊版有、新版刪除之內容。
- 3. 本對照表未列出下列情況,但已於檔案中進行修正,與現行公布英文版本一致:
  - a. 英文編輯改變,未改變原有內容意義者;
  - b. 排版方式變更,未改變原有內容意義者;
  - c. 既有版本的錯字與誤植。

## 目錄

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## 第一項:軍商兩用貨品及技術出口管制清單修正對照表

| 修正條目                     | 現行內容 | 擬修正/新增內容            | 現行內容英譯 | 擬修正/新增內容英譯                                       |
|--------------------------|------|---------------------|--------|--|
|                          | 無    | 增加網址無須翻譯 -          |        | (1)https://www.wassenaar.org/                    |
|                          |      |                     |        | (2)http://mtcr.info/?lang=fr                     |
| <i>ል</i> ያ ታጉ <i>ላ</i> ህ |      |                     |        | (3)http://www.nuclearsuppliersgroup.org/index    |
| 一般註解                     |      |                     |        | .php?lang=en                                     |
|                          |      |                     |        | (4)http://www.australiagroup.net/en/index.htm    |
|                          |      |                     |        | 1  |
|                          | 無    | 核能軟體註解 -            |        | NUCLEAR SOFTWARE NOTE (NSN)                      |
|                          |      | (本註解優先於任何第 0 類第 D 節 |        | (This note overrides any control within section  |
|                          |      | 中之管制)               |        | D of Category 0)                                 |
|                          |      | 本清單第0類D節不管制用於已獲     |        | Section D of Category O of this list does not    |
|                          |      | 得出口許可貨品之安裝、操作、維     |        | control "software" which is the minimum          |
|                          |      | 護(檢查)及修理等最低限度"目標    |        | necessary "object code" for the installation,    |
|                          |      | 碼"之"軟體"。            |        | operation, maintenance (checking) or repair of   |
| 核能軟體註                    |      | 核准管制貨品出口,亦同時授權給     |        | those items whose export has been authorised.    |
| 解                        |      | 該最終使用者安裝、操作、維護(檢    |        | The approval of goods for export also authorises |
|                          |      | 查)與修理該貨品所需之最低限度     |        | the export to the same end-user of the minimum   |
|                          |      | "目標碼"。              |        | necessary "object code" for the installation,    |
|                          |      | 說明:核能軟體註解未豁免第5      |        | operation, maintenance (checking) or repair of   |
|                          |      | 類第2部分("資訊安全")所管制    |        | the goods.                                       |
|                          |      | 之"軟體"。              |        | Note: The Nuclear Software Note does not release |
|                          |      |                     |        | "software" specified in Category 5 - Part 2      |
|                          |      |                     |        | ("Information Security").                        |

| 修正條目                | 現行內容                 | 擬修正/新增內容          | 現行內容英譯                              | 擬修正/新增內容英譯  |
|---------------------|----------------------|-------------------|-------------------------------------|---|
|                     | 一般軟體註解               | 一般軟體註解            | GENERAL SOFTWARE NOTE (GSN)         | GENERAL SOFTWARE NOTE (GSN)                       |
|                     | (本註解優先於任何第 0 類至第 9   | (本註解優先於任何第1類至第9   | (This note overrides any control    | (This note overrides any control within section   |
| かた まん 瓜柚 ナナ         | 類第D節中之管制)            | 類第D節中之管制)         | within section D of Categories O to | D of Categories 1 to 9.)                          |
| 一般軟體註 解             | 本清單第 0 類至第 9 類不管制 "軟 | 本清單第1類至第9類不管制"軟   | 9.)                                 | Categories 1 to 9 of this list do not control     |
| P <del>F</del>      | 體"具下列任一特性:           | 體"具下列任一特性:        | Categories 0 to 9 of this list do   | "software" which is any of the following:         |
|                     |                      |                   | not control "software" which is any |   |
|                     |                      |                   | of the following:                   |   |
|                     | 無                    | 區域衛星導航系統          | _                                   | RNSS/ Regional Navigation Satellite System        |
| 字首集合字               | 簡易可程式邏輯元件            | 刪除                | SPLD/Simple Programmable Logic      | _   |
| 與縮寫                 |                      |                   | Device                              |   |
|                     | 無                    | 原子質量單位            | -                                   | u   |
|                     | "自動目標追蹤"(第6類)        | 刪除                | "Automatic target tracking" (6)     | _   |
|                     | "碳纖維預製品"(第1類)        | 刪除                | "Carbon fibre preforms" (1)         | _   |
|                     | "混合"(第1類)            | 刪除                | "Commingled" (1)                    | -   |
|                     | "磨碎"(第1類)            | 刪除                | "Comminution" (1)                   | -   |
|                     | "補償系統"(第6類)主要由非向     | "補償系統" (第6類)主要由非向 | "Compensation systems" (6) consist  | "Compensation systems" (6) consist of the         |
| 專用術語定               | 量感測器與1個或以上參考感測       | 量感測器與1個或以上參考感測    | of the primary scalar sensor, one   | primary scalar sensor, one or more reference      |
| <del>等</del> 用侧 品 足 | 器(如向量磁力計)所組成,同時配     | 器(如"向量磁力計")所組成,同  | or more reference sensors (e.g.,    | sensors (e.g., vector "magnetometers") together   |
| 找                   | 有可減輕平台上剛體旋轉噪音之       | 時配有可減輕平台上剛體旋轉噪    | vector magnetometers) together      | with software that permit reduction of rigid body |
|                     | 軟體。                  | 音之軟體。             | with software that permit           | rotation noise of the platform.                   |
|                     |                      |                   | reduction of rigid body rotation    |   |
|                     |                      |                   | noise of the platform.              |   |
|                     | "複合迴轉工作台"            | 刪除                | "Compound rotary table" (2)         | -   |
|                     | 密碼啟用"(第5類)指任何啟動或     | "密碼啟用"(第5類)指任何專門  | "Cryptographic activation" (5)      | "Cryptographic activation" (5) means any          |

| 修正條目 | 現行內容            | 擬修正/新增內容           | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|------|-----------------|--------------------|-------------------------------------|--|
|      | 啟用一項目密碼之技術,透過該項 | 為啟動或啟用一項目密碼之技      | means any technique that activates  | technique that specifically activates or enables |
|      | 目製造商之安全機制實現,該安全 | 術,透過該項目製造商之機制實     | or enables cryptographic            | cryptographic capability of an item, by means of |
|      | 機制之單一範圍如後任一者:   | 現,該安全機制之單一範圍如後任    | capability of an item, by means of  | a mechanism implemented by the manufacturer of   |
|      |                 | 一者:                | a secure mechanism implemented by   | the item, where this mechanism is uniquely bound |
|      |                 |                    | the manufacturer of the item, where | to any of the following:                         |
|      |                 |                    | this mechanism is uniquely bound to |  |
|      |                 |                    | any of the following:               |  |
|      | "可變形鏡面"         | 刪除                 | "Deformable mirrors" (6)            | -  |
|      | "直接作用液壓成形"      | 刪除                 | "Direct-acting hydraulic            | -  |
|      |                 |                    | pressing" (2)                       |  |
|      | "電子操控相位陣列天線"    | 刪除                 | "Electronically steerable phased    | -  |
|      |                 |                    | array antenna" (5 6)                |  |
|      | "飛行控制光學感應器陣列"   | 刪除                 | "Flight control optical sensor      | _  |
|      |                 |                    | array" (7)                          |  |
|      | "最佳飛行路徑"        | 刪除                 | "Flight path optimisation" (7)      | _  |
|      | "頻率遮罩觸發"        | 刪除                 | "Frequency mask trigger" (3)        | _  |
|      | "頻率合成器"         | 刪除                 | "Frequency synthesiser" (3)         | _  |
|      | "氣體霧化"          | 刪除                 | "Gas Atomisation" (1)               | -  |
|      | "地理分散"          | 刪除                 | "Geographically dispersed" (6)      | _  |
|      | "熱均壓緻密化"        | 刪除                 | "Hot isostatic densification" (2)   | -  |
|      | 無               | "交錯式類比—數位轉換器       | _                                   | "Interleaved Analogue-to-Digital Converter       |
|      |                 | (ADC)" (第3類)係指具有多個 |                                     | (ADC)" (3) means devices that have multiple ADC  |
|      |                 | ADC 單元之設備,其可在不同時   |                                     | units that sample the same analogue input at     |
|      |                 | 間內對相同的類比訊號輸入進行     |                                     | different times such that when the outputs are   |

| 修正條目 | 現行內容             | 擬修正/新增內容            | 現行內容英譯                            | 擬修正/新增內容英譯  |
|------|------------------|---------------------|-----------------------------------|---|
|      |                  | 採樣,當彙總輸出時,類比輸入被     |                                   | aggregated, the analogue input has been           |
|      |                  | 更有效的採樣與以更高採樣率轉      |                                   | effectively sampled and converted at a higher     |
|      |                  | 换。                  |                                   | sampling rate.                                    |
|      | 說明:參照:"化學雷射";"超  | 說明:參照:"化學雷射";"連     | N.B. See also "Chemical laser";   | N.B. See also "Chemical laser";                   |
|      | 高功率雷射";"連續波雷射";  | 續波雷射";"脈衝雷射";"超     | "CW laser";                       | "CW laser";                                       |
|      | "脈衝雷射"; "移轉雷射"。  | 高功率雷射"。             | "Pulsed laser";                   | "Pulsed laser";                                   |
|      |                  |                     | "Super High Power Laser";         | "Super High Power Laser".                         |
|      |                  |                     | "Transfer laser".                 |   |
|      | "資料庫"            | 刪除                  | "Library" (1)                     | -   |
|      | "主儲存體"           | 刪除                  | "Main storage" (4)                | -   |
|      | "機械合金法"          | 刪除                  | "Mechanical Alloying" (1)         | -   |
|      | "熔融抽取"           | 刪除                  | "Melt Extraction" (1)             | -   |
|      | "熔融紡絲"           | 刪除                  | "Melt Spinning" (1)               | -   |
|      | 無                | "多頻道類比—數位轉換器        | -                                 | "Multiple channel Analogue-to-Digital Converter   |
|      |                  | (ADC) "(第3類)係指整合超過1 |                                   | (ADC)" (3) means devices that integrate more than |
|      |                  | 個 ADC 之設備,其設計使每個    |                                   | one ADC, designed so that each ADC has a separate |
|      |                  | ADC 具有單獨的類比輸入。      |                                   | analogue input.                                   |
|      | "類神經電腦"          | 刪除                  | "Neural computer" (4)             | -   |
|      | "光學電腦"           | 刪除                  | "Optical computer" (4)            | -   |
|      | "電漿霧化"           | 刪除                  | "Plasma atomisation" (1)          | _   |
|      | "功率管理"           | 刪除                  | "Power management" (7)            | _   |
|      | "預先分離"(第0、1類)係指為 | "預先分離"(第1類)係指任何為    | "Previously separated" (01) means | "Previously separated" (1) is the application of  |
|      | 增加同位素濃度之先期處理程序。  | 增加同位素濃度之先期處理程序。     | the application of any process    | any process intended to increase the              |
|      |                  |                     | intended to increase the          | concentration of the controlled isotope.          |

| 修正條目 | 現行內容    | 擬修正/新增內容             | 現行內容英譯                          | 擬修正/新增內容英譯   |
|------|---------|----------------------|---------------------------------|--|
|      |         |                      | concentration of the controlled |  |
|      |         |                      | isotope.                        |  |
|      | "主飛行控制" | 刪除                   | "Primary flight control" (7)    | _  |
|      | "即時頻寬"  | 刪除                   | "Real-time bandwidth" (3)       | _  |
|      | "旋轉霧化"  | 刪除                   | "Rotary atomisation" (1)        | _  |
|      | 無       | "採樣率"(第3類)在類比一數位     | -                               | "Sample rate" (3) for an Analogue-to-Digital       |
|      |         | 轉換器(ADC)中指1秒時間中類比    |                                 | Converter (ADC) means the maximum number of        |
|      |         | 輸入所量測到之最大採樣數,除超      |                                 | samples that are measured at the analogue input    |
|      |         | 量採樣 ADCs 之外。對於超量採樣   |                                 | over a period of one second, except for            |
|      |         | ADCs 而言, "採樣率"被視為輸   |                                 | oversampling ADCs. For oversampling ADCs the       |
|      |         | 出字速率。"採樣率"也被稱為採      |                                 | "sample rate" is taken to be its output word rate. |
|      |         | 樣速率,通常以每秒兆採樣數        |                                 | "Sample rate" may also be referred to as sampling  |
|      |         | (MSPS)或每秒千兆採樣數       |                                 | rate, usually specified in Mega Samples Per        |
|      |         | (GSPS),或赫茲(Hz)轉換速率加以 |                                 | Second (MSPS) or Giga Samples Per Second (GSPS),   |
|      |         | 說明。                  |                                 | or conversion rate, usually specified in Hertz     |
|      |         |                      |                                 | (Hz).  |
|      | "穩定時間"  | 刪除                   | "Settling time" (3)             | -  |
|      | 無       | "穩態模式"(第9類)定義引擎運     | _                               | "Steady State Mode" (9) defines engine operation   |
|      |         | 轉條件,當引擎進氣口處周圍空氣      |                                 | conditions, where the engine parameters, such as   |
|      |         | 與壓力恆定時,引擎參數如推力/      |                                 | thrust/power, rpm and others, have no              |
|      |         | 功率、轉速及其他等沒有明顯的波      |                                 | appreciable fluctuations, when the ambient air     |
|      |         | 動。                   |                                 | temperature and pressure at the engine inlet are   |
|      |         |                      |                                 | constant.  |
|      | "噴濺急冷"  | 刪除                   | "Splat Quenching" (1)           | _  |

| 修正條目  | 現行內容                                  | 擬修正/新增內容                              | 現行內容英譯                              | 擬修正/新增內容英譯  |
|-------|---------------------------------------|---------------------------------------|-------------------------------------|---|
|       |                                       | 刪除                                    | "Systolic array computer"           | _   |
|       | 無                                     | "穩定狀態時間"(第6類)(亦被稱                     | -                                   | "Time-to-steady-state registration" (6) (also               |
|       |                                       | 為重力儀響應時間)為受平台干擾                       |                                     | referred to as the gravimeter's response time)              |
|       |                                       | 影響之時間,誘發加速(高頻率雜                       |                                     | is the time over which the disturbing effects of            |
|       |                                       | 訊)之降低。                                |                                     | platform induced accelerations (high frequency              |
|       |                                       |                                       |                                     | noise) are reduced.   |
|       | "脈動陣列電腦"                              | 刪除                                    | "Transfer laser" (6)                | _   |
|       | "真空霧化"                                | 刪除                                    | "Vacuum Atomisation" (1)            | _   |
|       | "可變幾何機翼"                              | 刪除                                    | "Variable geometry airfoils" (7)    | _   |
|       | 1A002 "複合"結構或積層板,                     | 1A002 "複合"結構或積層板,                     | 1A002 "Composite" structures or     | 1A002 "Composite" structures or laminates, as               |
|       | 且具下列任一特性:                             | 如下:                                   | laminates, having any of the        | follows:  |
|       | 說明:參照 1A202、9A010 及                   | 說明:參照 1A202、9A010 及                   | following:                          | N. B. SEE ALSO 1A202, 9A010 and 9A110                       |
|       | 9A110 °                               | 9A110 °                               | N. B. SEE ALSO 1A202, 9A010 and     | a. Made from any of the following:                          |
|       | a. 由 1C010.c.、1C010.d.或               | a. 由以下任一材料構成:                         | 9A110                               | 1. An organic "matrix" and "fibrous or                      |
|       | 1C010.e.所述之有機"基質"與材                   | 1.1C010.c.、1C010.d.所述之有機              | a. Consisting of an organic         | filamentary materials" specified in 1C010.c. or             |
|       | 料構成;或                                 | "基質"與"纖維狀或絲狀材料";                      | "matrix" and materials specified    | 1C010.d.: or  |
| 1A002 | b. 由一金屬或碳 "基質" 構成,                    | 或                                     | in 1C010.c., 1C010.d. or 1C010.e.;  | 2. Prepregs or preforms specified in 1C010.e.;              |
|       | 且具下列任一者:                              | 2. 1C010.e.所述之預浸體或預製                  | or                                  | b. Made from a metal or carbon "matrix", and any            |
|       | 1. 碳"纖維狀或絲狀材料"且具                      | 體;                                    | b. Consisting of a metal or carbon  | of the following:   |
|       | 下列所有特性:                               | b. 由金屬或碳 "基質" 構成,且                    | "matrix", and any of the following: | 1. Carbon "fibrous or filamentary materials"                |
|       | a. "比模數"超過 10.15 × 10 <sup>6</sup> m; | 具下列任一者:                               | 1. Carbon "fibrous or filamentary   | having all of the following:                                |
|       | 及                                     | 1. 碳且具下列所有特性:                         | materials" having all of the        | a. A "specific modulus" exceeding 10,15 $\times$ 10 $^6$ m; |
|       | b. "比抗拉強度" 超過 17.7 × 10 <sup>4</sup>  | a. "比模數"超過 10.15 × 10 <sup>6</sup> m; | following:                          | and   |
|       | m;或                                   | 及                                     | a. A "specific modulus" exceeding   | b. A "specific tensile strength" exceeding 17,7             |

| 修正條目  | 現行內容                    | 擬修正/新增內容                             | 現行內容英譯                                | 擬修正/新增內容英譯                                       |
|-------|-------------------------|--------------------------------------|---------------------------------------|--|
|       | 2.1C010.c.所述之材料。        | b. "比抗拉強度" 超過 17.7 × 10 <sup>4</sup> | $10,15 \times 10^{-6}$ m; and         | $	imes$ 10 $^4$ m; or                            |
|       |                         | m;或                                  | b. A "specific tensile strength"      | 2. Materials specified in 1C010.c.               |
|       |                         | 2.1C010.c.所述之材料。                     | exceeding 17,7 $\times$ 10 $^4$ m; or |  |
|       |                         |                                      | 2. Materials specified in 1C010.c.    |  |
|       | 1B117 可在0至13,326 kPa 範圍 | 1B117 批次混合器具下列所有                     | 1B117 Batch mixers with provision     | 1B117 Batch mixers having all of the following,  |
|       | 之真空狀態下進行混合,且其混合         | 特性,及特別為其設計之零件:                       | for mixing under vacuum in the        | and specially designed components therefor:      |
|       | 槽具有溫度控制性能之批次混合          | a. 設計或改裝可在0至13,326 kPa               | range of zero to 13, 326 kPa and with | a. Designed or modified for mixing under vacuum  |
|       | 器,且具下列所有特性,及為其特         | 範圍之真空狀態下進行混合;                        | temperature control capability of     | in the range of zero to 13,326 kPa:              |
|       | 別設計之零件:                 | b. 混合槽具有温度控制能力;                      | the mixing chamber and having all     | b. Capable of controlling the temperature of the |
|       | a. 總體積容量為 110 公升或以      | c. 體積容量為 110 公升或以上;                  | of the following, and specially       | mixing chamber;                                  |
|       | 上;及                     | 及                                    | designed components therefor:         | c. A total volumetric capacity of 110 litres or  |
| 1B117 | b. 具有至少一個安裝偏離中心之        | d. 具有至少一個偏離中心安裝之                     | a. A total volumetric capacity of     | more; and  |
|       | `混合/揉拌軸´。               | `混合/揉拌軸´。                            | 110 litres or more; and               | d. At least one 'mixing/kneading shaft' mounted  |
|       | 註解:1B117.b.所述之 ~ 混合/捏揉  | 註解:1B117.d.所述之 ~ 混合/捏揉               | b. At least one 'mixing/kneading      | off centre.                                      |
|       | 軸´,並非指粉碎機或刀軸。           | 軸´,並非指粉碎機或刀軸。                        | shaft' mounted off centre.            | Note: In 1B117.d. the term 'mixing/kneading      |
|       |                         |                                      | Note: In 1B117.b. the term            | shaft' does not refer to deagglomerators or      |
|       |                         |                                      | 'mixing/kneading shaft' does not      | knife-spindles.                                  |
|       |                         |                                      | refer to deagglomerators or           |  |
|       |                         |                                      | knife-spindles.                       |  |
|       | 1B118 可在0至13,326 kPa 範圍 | 1B118 連續混合器具下列任一                     | 1B118 Continuous mixers with          | 1B118 Continuous mixers having all of the        |
|       | 之真空狀態下進行混合,且其混合         | 特性,及特別為其設計之零件:                       | provision for mixing under vacuum     | following, and specially designed components     |
| 1B118 | 槽具有溫度控制性能之連續混合          | a. 設計或改裝可在0至13,326 kPa               | in the range of zero to 13,326 kPa    | therefor:  |
|       | 器,且具下列任一特性,及特別為         | 範圍之真空狀態下進行混合;                        | and with a temperature control        | a. Designed or modified for mixing under vacuum  |
|       | 其設計之零件:                 | b. 混合槽具有温度控制能力;                      | capability of the mixing chamber      | in the range of zero to 13,326 kPa;              |

| 修正條目     | 現行內容                   | 擬修正/新增內容               | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|----------|------------------------|------------------------|-------------------------------------|--|
|          | a. 具有 2 個或以上之混合/揉拌     | c. 具下列任一者:             | and having any of the following,    | b. Capable of controlling the temperature of the |
|          | 軸;或                    | 1. 具2個或以上之混合/揉拌軸;      | and specially designed components   | mixing chamber;                                  |
|          | b. 具有可振盪之單一旋轉軸,且       | 或                      | therefor:                           | c. any of the following,:                        |
|          | 軸上及混合槽內壁均有揉拌齒/螺        | 2. 具下列全部者:             | a. Two or more mixing/kneading      | 1. Two or more mixing/kneading shafts; or        |
|          | 栓。                     | a. 具有可振盪之單一旋轉軸,其       | shafts; or                          | 2. All of the following:                         |
|          |                        | 有揉拌齒/螺栓;及              | b. A single rotating shaft which    | a. A single rotating and oscillating shaft with  |
|          |                        | b. 混合槽內壁有揉拌齒/螺栓。       | oscillates and having kneading      | kneading teeth/pins; and                         |
|          |                        |                        | teeth/pins on the shaft as well as  | b. Kneading teeth/pins inside the casing of the  |
|          |                        |                        | inside the casing of the mixing     | mixing chamber.                                  |
|          |                        |                        | chamber.                            |  |
|          | c. 由下列任一材料建構而成:        | c. 由下列任一材料建構而成:        | c. Constructed of either:           | c. Constructed of either:                        |
|          | 1.300 系列不銹鋼,具低含硫量,     | 1. 國際汽車工程師協會(SAE)之     | 1. Stainless steel of the 300       | 1. Stainless steel of the Society of Automotive  |
|          | 且其沃斯田(austenitic)美國材料試 | 300 系列不銹鋼,具低含硫量,且      | series with low sulphur content and | Engineers International (SAE) 300 series with    |
|          | 驗學會(ASTM)(或等效標準)之晶     | 其沃斯田(austenitic)美國材料試驗 | with an austenitic ASTM (or         | low sulphur content and with an austenitic ASTM  |
| 1B228. c | 粒大小為5號或以上者;或           | 學會(ASTM)(或等效標準)之晶粒     | equivalent standard) grain size     | (or equivalent standard) grain size number of 5  |
|          | 2. 兼具低溫且與氫氣相容之同等       | 大小為5或以上者;或             | number of 5 or greater; or          | or greater; or                                   |
|          | 材料;及                   | 2. 兼具低溫且與氫氣(H2)相容之     | 2. Equivalent materials which are   | 2. Equivalent materials which are both cryogenic |
|          |                        | 同等材料;及                 | both cryogenic and H 2 -compatible; | and hydrogen (H 2 )-compatible; and              |
|          |                        |                        | and                                 |  |
| 1B229    | 1B229                  | 刪除                     | 1B229                               | -  |
|          | a. 設計為全部含有相當於2 kg 重    | a. 設計為全部含有相當於 2 公斤     | a. Designed to fully contain an     | a. Designed to fully contain an explosion        |
| 1B234. a | TNT 爆炸威力或以上;及          | 重黄色炸藥(三硝基甲苯/TNT)爆      | explosion equivalent to 2 kg of TNT | equivalent to 2 kg of trinitrotoluene (TNT) or   |
|          |                        | 炸威力或以上;及               | or greater; and                     | greater; and                                     |
| 1B235    | 無                      | 1B235 用於生產氚的組件與零       | -                                   | 1B235 Target assemblies and components for the   |

| 修正條目        | 現行內容                                 | 擬修正/新增內容                 | 現行內容英譯  | 擬修正/新增內容英譯  |
|-------------|--------------------------------------|--------------------------|---|---|
|             |                                      | 件,如下:                    |   | production of tritium as follows:                 |
|             |                                      | a. 含有或由鋰-6 同位素製成之組       |   | a. Target assemblies made of or containing        |
|             |                                      | 件,特別設計用於透過放射生產           |   | lithium enriched in the lithium—6 isotope         |
|             |                                      | 氚,包括插入核子反應器;             |   | specially designed for the production of tritium  |
|             |                                      | b. 為 1B235.a.所述之組件特別設    |   | through irradiation, including insertion in a     |
|             |                                      | 計之零件。                    |   | nuclear reactor;                                  |
|             |                                      | 技術註解:                    |   | b. Components specially designed for the target   |
|             |                                      | 為用於生產氚的組件所特別設計           |   | assemblies specified in 1B235.a.                  |
|             |                                      | 之零件,可能包括鋰顆粒、氚吸氣          |   | Technical Note:                                   |
|             |                                      | 劑與特別塗層襯套。                |   | Components specially designed for target          |
|             |                                      |                          |   | assemblies for the production of tritium may      |
|             |                                      |                          |   | include lithium pellets, tritium getters, and     |
|             |                                      |                          |   | specially-coated cladding.                        |
|             | 1C001 特別設計用於吸收電磁                     | 1C001 特別設計用於吸收電磁         | 1C001 Materials specially designed              | 1C001 Materials specially designed for absorbing  |
|             | 波,或本質上即為導電性聚合物材                      | 輻射,或本質上即為導電性聚合物          | for use as absorbers of                         | electromagnetic radiation, or intrinsically       |
| 1C001       | 料,如下:                                | 材料,如下:                   | electromagnetic waves, or                       | conductive polymers, as follows:                  |
|             |                                      |                          | intrinsically conductive                        |   |
|             |                                      |                          | polymers, as follows:                           |   |
|             | b. 吸收頻率超過 1.5 × 10 <sup>14</sup> Hz, | b. 對可見光而言為不透明之材          | b. Materials for absorbing                      | b. Materials not transparent to visible light and |
|             | 但小於 3.7 × 10 <sup>14</sup> Hz 之材料,且  | 料,其特別設計用於吸收波長超過          | frequencies exceeding 1, $5 \times 10^{-14}$ Hz | specially designed for absorbing near-infrared    |
| 1C001.b     | 對可見光不具穿透性者;                          | 810 nm 但小於 2,000 nm(頻率超過 | but less than 3, $7 \times 10^{-14}$ Hz and not | radiation having a wavelength exceeding 810 nm    |
|             |                                      | 150 THz 但小於 370 THz)的近紅  | transparent to visible light;                   | but less than 2000 nm (frequencies exceeding 150  |
|             |                                      | 外線輻射;                    |   | THz but less than 370 THz);                       |
| 1C002. c. 2 | 2. 在受控制之環境中,以下列任                     | 2. 在受控制之環境中,以下列任         | 2. Made in a controlled environment             | 2. Made in a controlled environment by any of the |

| 修正條目           | 現行內容             | 擬修正/新增內容          | 現行內容英譯                             | 擬修正/新增內容英譯   |
|----------------|------------------|-------------------|------------------------------------|--|
|                | 一程序製造:           | 一程序製造:            | by any of the following processes: | following processes:                                       |
|                | a. "真空霧化";       | a. `真空霧化´;        | a. "Vacuum atomisation";           | a. 'Vacuum atomisation';                                   |
|                | b. "氣體霧化";       | b. ` 氣體霧化´;       | b. "Gas atomisation";              | b. 'Gas atomisation';                                      |
|                | c. "旋轉霧化";       | c. `旋轉霧化´;        | c. "Rotary atomisation";           | c. 'Rotary atomisation';                                   |
|                | d. "噴濺急冷";       | d. ` 噴濺急冷´;       | d. "Splat quenching";              | d. 'Splat quenching';                                      |
|                | e. "熔融紡絲"及"磨碎";  | e. `熔融紡絲´及`磨碎´;   | e. "Melt spinning" and             | e. 'Melt spinning' and 'comminution';                      |
|                | f. "熔融抽取"及"磨碎";  | f. `熔融抽取´及`磨碎´;   | "comminution";                     | f. 'Melt extraction' and 'comminution';                    |
|                | g. "機械合金法";或     | g. `機械合金法´;或      | f. "Melt extraction" and           | g. 'Mechanical alloying'; or                               |
|                | h. "電漿霧化";及      | h. `電漿霧化´;及       | "comminution";                     | h. 'Plasma atomisation'; and                               |
|                |                  |                   | g. "Mechanical alloying"; or       |  |
|                |                  |                   | h. "Plasma atomisation"; and       |  |
|                | 3. 在受控制之環境中,以下列任 | 3. 在受控制之環境中,以下列任  | 3. Produced in a controlled        | 3. Produced in a controlled environment by any             |
|                | 一程序製造:           | 一程序製造:            | environment by any of the          | of the following:  |
| 1C002. D. 3    | a. "噴濺急冷";       | a. `噴濺急冷´;        | following:                         | a. 'Splat quenching';                                      |
| 10002. D. 0    | b. "熔融紡絲";或      | b. `熔融紡絲´;或       | a. "Splat quenching";              | b. 'Melt spinning'; or                                     |
|                | c. "熔融抽取"。       | c. `熔融抽取´。        | b. "Melt spinning"; or             | c. 'Melt extraction'.                                      |
|                |                  |                   | c. "Melt extraction".              |  |
|                | 無                | 技術註解:             | -                                  | Technical Notes:   |
|                |                  | 1. `真空霧化´係指迅速釋放溶  |                                    | 1. 'Vacuum atomisation' is a process to reduce             |
| 10000 北佐       |                  | 解之氣體,使其暴露於真空裝置    |                                    | a molten stream of metal to droplets of a diameter         |
| 1C002 技術<br>註解 |                  | 中,而將熔融流動之金屬變為粒狀   |                                    | of 500 $\mu\mathrm{m}$ or less by the rapid evolution of a |
| 红件             |                  | 熔滴直徑 500 微米或以下之處理 |                                    | dissolved gas upon exposure to a vacuum.                   |
|                |                  | 程序。               |                                    | 2. 'Gas atomisation' is a process to reduce a              |
|                |                  | 2. ~氣體霧化~係指以高壓氣流  |                                    | molten stream of metal alloy to droplets of 500            |

| 修正條目 | 現行內容 | 擬修正/新增內容          | 現行內容英譯 | 擬修正/新增內容英譯   |
|------|------|-------------------|--------|--|
|      |      | 將熔流之金屬合金變為微粒直徑    |        | $\mu \mathrm{m}$ diameter or less by a high pressure gas |
|      |      | 500 微米或以下之處理程序。   |        | stream.  |
|      |      | 3. `旋轉霧化`係指以離心力將  |        | 3. 'Rotary atomisation' is a process to reduce           |
|      |      | 一束或一池液態金屬減為粒狀熔    |        | a stream or pool of molten metal to droplets to          |
|      |      | 滴直徑 500 微米或以下之處理程 |        | a diameter of 500 $\mu\mathrm{m}$ or less by centrifugal |
|      |      | 序。                |        | force.   |
|      |      | 4. `噴濺急冷`係指將金屬熔流  |        | 4. 'Splat quenching' is a process to 'solidify           |
|      |      | 衝擊冷凍塊而`快速凝固`使形    |        | rapidly'a molten metal stream impinging upon a           |
|      |      | 成片狀產品之處理程序。       |        | chilled block, forming a flake-like product.             |
|      |      | 5. `熔融紡絲`係指以金屬熔液  |        | 5. 'Melt spinning' is a process to 'solidify             |
|      |      | 流衝擊旋轉之冷凍塊,形成片狀、   |        | rapidly'a molten metal stream impinging upon a           |
|      |      | 带狀或棒狀產物之`快速凝固´    |        | rotating chilled block, forming a flake, ribbon          |
|      |      | 處理程序。             |        | or rod-like product.                                     |
|      |      | 6. `磨碎´指利用壓碎或研磨方  |        | 6. 'Comminution' is a process to reduce a                |
|      |      | 式將物質縮小成為粒子之處理程    |        | material to particles by crushing or grinding.           |
|      |      | 序。                |        | 7. 'Melt extraction' is a process to 'solidify           |
|      |      | 7. `熔融抽取″係指`快速凝   |        | rapidly' and extract a ribbon-like alloy product         |
|      |      | 固 及抽取帶狀合金產物之處理    |        | by the insertion of a short segment of a rotating        |
|      |      | 程序,將一小截冷凍´塊旋轉插入   |        | chilled block into a bath of a molten metal alloy.       |
|      |      | 熔融金屬合金槽以抽取帶狀合金。   |        | 8. 'Mechanical alloying' is an alloying process          |
|      |      | 8. `機械合金法´係指由機械衝  |        | resulting from the bonding, fracturing and               |
|      |      | 擊方式將元素及主體合金粉末,經   |        | rebonding of elemental and master alloy powders          |
|      |      | 過結合、破碎及再結合之合金處理   |        | by mechanical impact. Non-metallic particles may         |
|      |      | 程序。藉由添加適當的粉末,非金   |        | be incorporated in the alloy by addition of the          |

| 修正條目     | 現行內容                            | 擬修正/新增內容                        | 現行內容英譯                             | 擬修正/新增內容英譯   |
|----------|---------------------------------|---------------------------------|------------------------------------|--|
|          |                                 | 屬粒子可結合至合金中。                     |                                    | appropriate powders.   |
|          |                                 | 9. `電漿原子化´係指在惰性氣                |                                    | 9. 'Plasma atomisation' is a process to reduce                 |
|          |                                 | 體環境中利用電漿炬將熔融或固                  |                                    | a molten stream or solid metal to droplets of 500              |
|          |                                 | 態金屬減低成為500μm或以下之                |                                    | $\mu  \mathrm{m}$ diameter or less, using plasma torches in an |
|          |                                 | 微滴之處理程序。                        |                                    | inert gas environment.   |
|          |                                 | 10. `快速凝固`係指在冷卻率                |                                    | 10. 'Solidify rapidly' is a process involving the              |
|          |                                 | 超過1,000K/s下,使熔態物質凝              |                                    | solidification of molten material at cooling                   |
|          |                                 | 固之處理程序。                         |                                    | rates exceeding 1 000 K/sec.                                   |
|          | d. "纖維或絲狀材料":                   | d. "纖維或絲狀材料":                   | d. "Fibrous or filamentary         | d. "Fibrous or filamentary materials", having                  |
|          | 1. 由下列任一者組成:                    | a. 1C008.a.所述之聚醚醯亞胺;或           | materials", having any of the      | any of the following:  |
|          | a. 1C008.a.所述之聚醚醯亞胺;或           | b. 1C008.d.至 1C008.f.所述之材       | following:                         | 1. Composed of any of the following:                           |
|          | b. 1C008.d.至 1C008.f.所述之材       | 料;或;                            | 1. Composed of any of the          | a. Polyetherimides specified in 1C008.a.; or                   |
|          | 料;或;                            | 2. 由 1C010.d.1.a.或 1C010.d.1.b. | following:                         | b. Materials specified in 1C008.d. to 1C008.f.;                |
|          | 2. 由 1C010.d.1.a.或 1C010.d.1.b. | 所述之材料所組成,且與                     | a. Polyetherimides specified in    | or   |
|          | 所述之材料所組成,且與                     | 1C010.a.、1C010.b.或 1C010.c.所    | 1C008. a.; or                      | 2. Composed of materials specified in                          |
| 1C010. d | 1C010.a.、1C010.b.或 1C010.c.所    | 述之其他纖維`混合´者;                    | b. Materials specified in 1C008.d. | 1C010.d.1.a. or 1C010.d.1.b. and 'commingled'                  |
|          | 述之其他纖維 "混合" 者;                  | 技術註解:                           | to 1C008.f.; or                    | with other fibres specified in 1C010.a.,                       |
|          |                                 | "混合"指熱塑性纖維絲與強化纖                 | 2. Composed of materials specified | 1C010.b. or 1C010.c.;  |
|          |                                 | 維絲之混合,以生產完全纖維型態                 | in 1C010.d.1.a. or 1C010.d.1.b.    | Technical Note:  |
|          |                                 | 之強化纖維"基質"混合物。                   | and "commingled" with other fibres | 'Commingled' is filament to filament blending of               |
|          |                                 |                                 | specified in 1C010.a., 1C010.b. or | thermoplastic fibres and reinforcement fibres in               |
|          |                                 |                                 | 1C010. c.;                         | order to produce a fibre reinforcement "matrix"                |
|          |                                 |                                 |                                    | mix in total fibre form.                                       |
| 1C010.e  | e. 完全或部分以樹脂浸漬或以瀝                | e. 完全或部分以樹脂浸漬或以瀝                | e. Fully or partially              | e. Fully or partially resin-impregnated or                     |

| 修正條目         | 現行內容                        | 擬修正/新增內容                    | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|--------------|-----------------------------|-----------------------------|-------------------------------------|--|
|              | 青浸漬之"纖維或絲狀材料"(預             | 青浸漬之"纖維或絲狀材料"(預             | resin-impregnated or                | pitch-impregnated "fibrous or filamentary        |
|              | 浸體)、鍍金屬或鍍碳之 "纖維狀            | 浸體)、鍍金屬或鍍碳之 "纖維狀            | pitch-impregnated "fibrous or       | materials" (prepregs), metal or carbon-coated    |
|              | 或絲狀材料" (預製品)以及"碳            | 或絲狀材料" (預製品)以及 ~ 碳          | filamentary materials"              | "fibrous or filamentary materials" (preforms) or |
|              | 纖維預製品",符合下列所有條              | 纖維預製品 , 符合下列所有條             | (prepregs), metal or carbon-coated  | 'carbon fibre preforms', having all of the       |
|              | 件:                          | 件:                          | "fibrous or filamentary materials"  | following:                                       |
|              |                             |                             | (preforms) or "carbon fibre         |  |
|              |                             |                             | preforms", having all of the        |  |
|              |                             |                             | following:                          |  |
|              | 註解1:鍍金屬或鍍碳之"纖維狀             | 註解1:鍍金屬或鍍碳之"纖維狀             | Note 1: Metal or carbon-coated      | Note 1: Metal or carbon-coated "fibrous or       |
|              | 或絲狀材料"(預製品)和非樹脂或            | 或絲狀材料"(預製品)和非樹脂或            | "fibrous or filamentary materials"  | filamentary materials" (preforms) or 'carbon     |
| 1C010. e. 2. | 瀝青浸漬之 "碳纖維預製品",由            | 瀝青浸漬之`碳纖維預製品´,由             | (preforms) or "carbon fibre         | fibre preforms', not impregnated with resin or   |
| 註解 1         | 1C010.a.、1C010.b.及1C010.c.所 | 1C010.a.、1C010.b.及1C010.c.所 | preforms", not impregnated with     | pitch, are specified by "fibrous or filamentary  |
| 工件 1         | 述之"纖維狀或絲狀材料"說明;             | 述之"纖維狀或絲狀材料"說明;             | resin or pitch, are specified by    | materials" in 1C010.a., 1C010.b. or 1C010.c.     |
|              |                             |                             | "fibrous or filamentary materials"  |  |
|              |                             |                             | in 1C010.a., 1C010.b. or 1C010.c.   |  |
|              | 技術註解:                       | 技術註解:                       | Technical Note:                     | Technical Notes:                                 |
|              | 1C010.e.所述材料的`動態機械          | 1. "碳纖維預製品"指在"基質"           | The 'Dynamic Mechanical Analysis    | 1. 'Carbon fibre preforms' are an ordered        |
|              | 性分析玻璃轉換溫度(DMA               | 導入形成"複合材料"之前,佈或             | glass transition temperature (DMA   | arrangement of uncoated or coated fibres         |
| 1C010.e.技    | Tg) ´,需採用 ASTM D 7028-07    | 未塗佈之纖維為了組成一個架構              | Tg)' for materials specified by     | intended to constitute a framework of a part     |
| 術註解          | 所述方法,或等效國家標準,使用             | 之有序整齊排列。                    | 1C010.e. is determined using the    | before the "matrix" is introduced to form a      |
|              | 乾燥測試樣本進行測定。若為熱固             | 2.1C010.e.所述材料的`動態機械        | method described in ASTM D 7028-07, | "composite".                                     |
|              | 性材料,該乾燥測試樣本之固化程             | 性分析玻璃轉換溫度(DMA               | or equivalent national standard,    | 2. The 'Dynamic Mechanical Analysis glass        |
|              | 度至少達到 ASTM E 2160-04 或等     | Tg) ´,需採用 ASTM D 7028-07    | on a dry test specimen. In the case | transition temperature (DMATg)' for materials    |
|              | 效國家標準所定義之90%。               | 所述方法,或等效國家標準,使用             | of thermoset materials, degree of   | specified in 1C010.e. is determined using the    |

| 修正條目           | 現行內容              | 擬修正/新增內容                | 現行內容英譯                            | 擬修正/新增內容英譯  |
|----------------|-------------------|-------------------------|-----------------------------------|---|
|                |                   | 乾燥測試樣本進行測定。若為熱固         | cure of a dry test specimen shall | method described in ASTM D 7028-07, or equivalent |
|                |                   | 性材料,該乾燥測試樣本之固化程         | be a minimum of 90% as defined by | national standard, on a dry test specimen. In the |
|                |                   | 度至少達到 ASTM E 2160-04 或等 | ASTM E 2160-04 or equivalent      | case of thermoset materials, degree of cure of    |
|                |                   | 效國家標準所定義之90%。           | national standard.                | a dry test specimen shall be a minimum of 90 %    |
|                |                   |                         |                                   | as defined by ASTM E 2160-04 or equivalent        |
|                |                   |                         |                                   | national standard.                                |
| 1C111. a. 4. c | c. N,N 二烯丙基聯胺(CAS | c. N,N-二烯丙基聯胺(CAS       | c. N, N diallylhydrazine (CAS     | c. N,N-Diallylhydrazine (CAS 5164-11-4);          |
| 10111. a. 4. C | 5164-11-4);       | 5164-11-4);             | 5164-11-4);                       |   |
|                | 無                 | 7. 除軍用貨品管制以外之 4,5 二     | -                                 | 7. 4,5 diazidomethyl-2-methyl-1,2,3-triazole      |
| 1C111. c. 7    |                   | 叠氮甲基-2-甲基-1,2,3-三唑      |                                   | (iso-DAMTR), other than that specified in the     |
|                |                   | (iso-DAMTR);            |                                   | Military Goods Controls.                          |
|                | 無                 | d. 除軍用貨品管制以外之`凝膠        | -                                 | d. 'Gel propellants', other than that specified   |
|                |                   | 推進劑 , 其專門配置用於 飛         |                                   | in the Military Goods Controls, specifically      |
|                |                   | 彈~。                     |                                   | formulated for use in 'missiles'.                 |
|                |                   | 技術註解:                   |                                   | Technical Notes:                                  |
|                |                   | 1.1C111.d.中之`凝膠推進劑´     |                                   | 1. In 1C111.d. a 'gel propellant' is a fuel or    |
| 1C111. d       |                   | 指燃料或氧化劑配方使用凝膠           |                                   | oxidiser formulation using a gellant such as      |
| 10111. u       |                   | 劑,如矽酸鹽、高嶺土(黏土)、碳        |                                   | silicates, kaolin (clay), carbon or any           |
|                |                   | 或任何聚合型凝膠。               |                                   | polymeric gellant.                                |
|                |                   | 2. 在 1C111.d.所定義之 ~ 飛   |                                   | 2. In 1C111.d. a'missile' means complete rocket   |
|                |                   | 彈´,是指航程或射程超過300         |                                   | systems and unmanned aerial vehicle systems       |
|                |                   | km 的完整火箭系統及無人飛行載        |                                   | capable of a range exceeding 300 km.              |
|                |                   | 具系統。                    |                                   |   |
| 1C118.a        | a. 具下列所有特性:       | a. 具下列所有特性:             | a. Having all of the following    | a. Having all of the following characteristics:   |

| 修正條目      | 現行內容  | 擬修正/新增內容  | 現行內容英譯                             | 擬修正/新增內容英譯  |
|-----------|---|---|------------------------------------|---|
|           | 1. 含鉻重量百分比為 17.0 %至                                     | 1. 含鉻重量百分比為 17%至 23.0                                   | characteristics:                   | 1. Containing 17, 0 - 23, 0 % by weight of chromium |
|           | 23.0%,及含鎳重量百分比為 4.5                                     | %,及含鎳重量百分比為4.5%至  | 1. Containing 17,0 - 23,0 weight   | and 4,5 - 7,0 % by weight of nickel;                |
|           | %至 7.0 %;   | 7.0 % ;   | percent chromium and 4,5 - 7,0     | 2. Having a titanium content of greater than 0, 10  |
|           | 2. 含鈦重量百分比為 0.10 %以                                     | 2. 含鈦重量百分比為 0.10 %以                                     | weight percent nickel;             | % by weight; and                                    |
|           | 上;及   | 上;及   | 2. Having a titanium content of    | 3. A ferritic-austenitic microstructure (also       |
|           | 3. 鐵素體-奧氏體鋼微結構(亦稱                                       | 3. 鐵素體-奧氏體鋼微結構(亦稱                                       | greater than 0,10 weight percent;  | referred to as a two-phase microstructure) of       |
|           | 雙相微結構),其中含奧氏體鋼之   | 雙相微結構),其中體積百分比至   | and                                | which at least 10 % by volume (according to ASTM    |
|           | 體積百分比至少為10%(依ASTM                                       | 少為 10 % (依 ASTM 標準                                      | 3. A ferritic-austenitic           | E-1181-87 or national equivalents) is austenite;    |
|           | 標準 E-1181-87 或等效國家標                                     | E-1181-87 或等效國家標準)為奧                                    | microstructure (also referred to   | and   |
|           | 準);及  | 氏體鋼之;及  | as a two-phase microstructure) of  |   |
|           |   |   | which at least 10 percent is       |   |
|           |   |   | austenite by volume (according to  |   |
|           |   |   | ASTM E-1181-87 or national         |   |
|           |   |   | equivalents); and                  |   |
| 1C350. 64 | 無   | 64. 二乙胺(109-89-7);                                      | _                                  | 64. Diethylamine (109-89-7);                        |
| 1C350, 65 | 無   | 65. N,N-二異丙基胺基乙硫醇酸鹽                                     | -                                  | 65. N, N-Diisopropylaminoethanethiol                |
| 10000.00  |   | (41480-75-5) 。  |                                    | hydrochloride (41480-75-5).                         |
|           | 註解1:對出口至 "聯合國禁止化  | 註解1:對出口至 "聯合國禁止化  | Note 1: For exports to "States not | Note 1: For exports to "States not Party to the     |
|           | 學武器公約之非會員國",1C350                                       | 學武器公約之非會員國",1C350                                       | Party to the Chemical Weapons      | Chemical Weapons Convention", 1C350 does not        |
| 1C350 註解  | 不管制含有1種或以上  | 不管制含有1種或以上  | Convention", 1C350 does not        | control "chemical mixtures" containing one or       |
|           | 1C350.1 \cdot .3 \cdot .5 \cdot .11 \cdot .12 \cdot .13 | 1C350.1 \cdot .3 \cdot .5 \cdot .11 \cdot .12 \cdot .13 | control "chemical mixtures"        | more of the chemicals specified in entries          |
|           | · .17 · .18 ·21 · .22 · .26 · .27                       | · .17 · .18 ·21 · .22 · .26 · .27                       | containing one or more of the      | 1C350.1, .3, .5, .11, .12, .13, .17, .18, .21       |
|           | · .28 · .31 · .32 · .33 · .34 · .35 ·                   | · .28 · .31 · .32 · .33 · .34 · .35 ·                   | chemicals specified in entries     | , .22, .26, .27, .28, .31, .32, .33, .34, .35       |
|           | .36、.54、.55、.56、.57 及.63 所述                             | .36、.54、.55、.56、.57、.63 及.65                            | 1C350.1, .3, .5, .11, .12, .13,    | , .36, .54, .55, .56, .57, 63 and .65 in which      |

| 修正條目         | 現行內容  | 擬修正/新增內容  | 現行內容英譯                                   | 擬修正/新增內容英譯                                       |
|--------------|---|---|--|--|
|              | 化學品之"化學品混合物",惟化   | 所述化學品之"化學品混合物",   | . 17, . 18, . 21, . 22, . 26, . 27, . 2  | no individually specified chemical constitutes   |
|              | 學品混合物中所含上列管制化學  | 惟化學品混合物中所含上列管制  | 8, .31, .32, .33, .34, .35, .36,         | more than 10 % by the weight of the mixture.     |
|              | 品個別成分之重量百分比不超過  | 化學品個別成分之重量百分比不  | .54, .55, .56, .57 and .63 in which      | Note 2: For exports to "States Party to the      |
|              | 10 % 。  | 超過 10%。   | no individually specified chemical       | Chemical Weapons Convention", 1C350 does not     |
|              | 註解2:對出口至"聯合國禁止化   | 註解2:對出口至"聯合國禁止化   | constitutes more than 10% by the         | control "chemical mixtures" containing one or    |
|              | 學武器公約之會員國",1C350不                                       | 學武器公約之會員國",1C350不                                       | weight of the mixture.                   | more of the chemicals specified in entries       |
|              | 管制含有1種或以上   | 管制含有1種或以上   | Note 2: For exports to "States           | 1C350.1, .3, .5, .11, .12, .13, .17, .18, .21    |
|              | 1C350.1 \cdot .3 \cdot .5 \cdot .11 \cdot .12 \cdot .13 | 1C350.1 \cdot .3 \cdot .5 \cdot .11 \cdot .12 \cdot .13 | Party to the Chemical Weapons            | , .22, .26, .27, .28, .31, .32, .33, .34, .35    |
|              | · .17 · .18 · .21 ·22 · .26 · .27                       | · .17 · .18 · .21 · .22 · .26 · .27                     | Convention", 1C350 does not              | , .36, .54, .55, .56, .57, .63 and .65 in which  |
|              | · .28 · .31 · .32 · .33 · .34 · .35 ·                   | · .28 · .31 · .32 · .33 · .34 · .35 ·                   | control "chemical mixtures"              | no individually specified chemical constitutes   |
|              | .36、.54、.55、.56、.57 及.63 所述                             | .36、.54、.55、.56、.57、.63 及.65                            | containing one or more of the            | more than 30 % by the weight of the mixture.     |
|              | 化學品之"化學品混合物",惟化   | 所述化學品之"化學品混合物",   | chemicals specified in entries           |  |
|              | 學品混合物中所含上列管制化學  | 惟化學品混合物中所含上列管制  | 1C350.1, .3, .5, .11, .12, .13,          |  |
|              | 品個別成分之重量百分比不超過  | 化學品個別成分之重量百分比不  | .17, .18, .21, .22, .26, .27, .2         |  |
|              | 30 % 。  | 超過30%。  | 8, .31, .32, .33, .34, .35, .36,         |  |
|              |   |   | . 54, . 55, . 56, . 57 and . 63 in which |  |
|              |   |   | no individually specified chemical       |  |
|              |   |   | constitutes more than 30% by the         |  |
|              |   |   | weight of the mixture.                   |  |
|              | 無   | 註解:志賀毒素大腸桿菌(STEC)                                       | -  | Note: Shiga toxin producing Escherichia coli     |
| 1C351. c. 19 |   | 別名包括腸出血性大腸桿菌  |  | (STEC) includes inter alia enterohaemorrhagic E. |
| ita<br>注解    |   | (EHEC)、產志賀毒素大腸桿菌  |  | coli (EHEC), verotoxin producing E. coli (VTEC)  |
| <u>計工円午</u>  |   | (VTEC)或志賀樣毒素大腸桿菌  |  | or verocytotoxin producing E. coli (VTEC).       |
|              |   | (VTEC) ∘  |  |  |

| 修正條目  | 現行內容                            | 擬修正/新增內容                 | 現行內容英譯                             | 擬修正/新增內容英譯                                      |
|-------|---------------------------------|--------------------------|------------------------------------|---|
| 1C352 | 1C352                           | 刪除                       | 1C352                              | _   |
|       | 1C353 遺傳因子及經基因改造                | 1C353 、遺傳因子、及經、基         | 1C353 Genetic elements and         | 1C353 'Genetic elements' and                    |
|       | 之有機體,如下:                        | 因改造之有機體 ,如下:             | genetically modified organisms, as | 'genetically-modified organisms', as follows:   |
|       | a. 經基因改造之有機體或遺傳因                | a. 任何`基因改造之有機體´          | follows:                           | a. Any 'genetically-modified organism' which    |
|       | 子,含有與致病性有關之核酸序                  | 含有,或`遺傳因子´為其編碼下          | a. Genetically modified organisms  | contains, or 'genetic element' that codes for,  |
|       | 列,且該致病性係源自於                     | 列任一者:                    | or genetic elements that contain   | any of the following:                           |
|       | 1C351.a.、1C351.c.、1C351.e.或     | 1.1C351.a. 或1C354.a.中任何病 | nucleic acid sequences associated  | 1. Any gene or genes specific to any            |
|       | 1C354 所述之有機體;                   | 毒之基因。                    | with pathogenicity of organisms    | virusspecified in 1C351.a. or 1C354.a.          |
|       | b. 經基因改造之有機體或遺傳因                | 2.1C351.c. 或1C354.b.中之任何 | specified in 1C351.a., 1C351.c.,   | 2. Any gene or genes specific to bacterium      |
|       | 子,含1C351.d.所述"毒素"或其             | 細菌之基因,或1C351.e.或         | 1C351. e. or 1C354;                | specified in 1C351.c. or 1C354.b. or fungus     |
|       | "毒素次單位"之核酸序列編碼。                 | 1C354.c.中任何真菌之基因,其具      | b. Genetically modified organisms  | specified in 1C351.e. or 1C354.c., and which is |
|       | 技術註解:                           | 下列任一特性:                  | or genetic elements that contain   | any of the following:                           |
| 1C353 | 1. 基因改造生物體,包括遺傳物                | a. 自身或通過轉譯或轉譯產品重         | nucleic acid sequences coding for  | a. In itself or through its transcribed or      |
|       | 質(核酸序列)已被改變之生物                  | 現對人類、動物或植物健康的顯著          | any of the "toxins" specified in   | translated products represents a significant    |
|       | 體,其非通過天然存在的方式如交                 | 傷害,或;                    | 1C351.d. or "sub-units of toxins"  | hazard to human, animal or plant health, or     |
|       | 配或自然重組,及包括全部或部分                 | b. 能夠 ` 賦予或增強致病性 ´ ,     | thereof.                           | b. Could 'endow or enhance pathogenicity', or   |
|       | 由人為產生者;                         | 或                        | Technical Notes:                   | 3. Any "toxins" specified in 1C351.d. or        |
|       | 1C353 (續)                       | 3. 任何 1C351.d.中之"毒素"或    | 1. Genetically-modified organisms  | "sub-units of toxins" therefor.                 |
|       | 2. 遺傳因子包括染色體、基因體                | 其"毒素次單位"。                | includes organisms in which the    | Technical Notes:                                |
|       | 組、質體、轉位子及載體,不論其                 | 技術註解:                    | genetic material (nucleic acid     | 1. 'Genetically-modified organisms' include     |
|       | 為經改造或未經改造者,或全部或                 | 1. `基因改造之有機體´包括通         | sequences) has been altered in a   | organisms in which the nucleic acid sequences   |
|       | 部分化學合成者。                        | 過特意之分子操作產生或改變核           | way that does not occur naturally  | have been created or altered by deliberate      |
|       | 3. 與 1C351.a.、1C351.c.、1C351.e. | 酸序列的有機體。                 | by mating and/or natural           | molecular manipulation.                         |
|       | 或 1C354 所述微生物之致病性有              | 2. `遺傳因子´包括染色體,基         | recombination, and encompasses     | 2. 'Genetic elements' include inter alia        |

| 修正條目 | 現行內容               | 擬修正/新增內容                           | 現行內容英譯                             | 擬修正/新增內容英譯                                       |
|------|--------------------|------------------------------------|------------------------------------|--|
|      | 關核酸序列,係指清單所列"微生    | 因組,質體,轉座子,載體和含有                    | those produced artificially in     | chromosomes, genomes, plasmids, transposons,     |
|      | 物"之特定序列,而該序列:      | 可修復的核酸片段的非活化有機                     | whole or in part.                  | vectors and inactivated organisms containing     |
|      | a. 本身或透過其轉錄或轉譯之產   | 體,無論其經基因改造或是未改                     | 2. Genetic elements include inter  | recoverable nucleic acid fragments, whether      |
|      | 品對人類、動物或植物健康會構成    | 造,或是全部或部分由化學合成。                    | alia chromosomes, genomes,         | genetically modified or unmodified, or           |
|      | 顯著危害;或             | 就控制遺傳因子目的而言,由非活                    | plasmids, transposons, and vectors | chemically synthesized in whole or in part. For  |
|      | b. 已知可增強受管制微生物、以   | 化有機體而來的核酸、病毒或樣                     | whether genetically modified or    | the purposes of the genetic elements control,    |
|      | 嵌入或其他方式與受管制微生物     | 品,若非活化與製備材料為預期或                    | unmodified, or chemically          | nucleic acids from an inactivated organism,      |
|      | 結合之其他有機體之能力,以致對    | 已知可促進核酸的分離,純化,擴                    | synthesized in whole or in part.   | virus, or sample are considered recoverable if   |
|      | 人類、動物或植物健康造成嚴重損    | 增,檢測或鑑定,則可認定其為可                    | 3. Nucleic acid sequences          | the inactivation and preparation of the material |
|      | 害。                 | 回收。                                | associated with the pathogenicity  | is intended or known to facilitate isolation,    |
|      | 註解:除類志賀毒素或其子單位之    | 3. ` 賦予或增強致病性 ´ 之定義                | of any of the "microorganisms"     | purification, amplification, detection, or       |
|      | 核酸序列外,1C353 不管制與腸出 | 為插入或整合核酸序列可能刻意                     | specified in 1C351.a., 1C351.c.,   | identification of nucleic acids.                 |
|      | 血性大腸桿菌、O157 血清型及其  | 引發有機物受體疾病或死亡的能                     | 1C351.e. or 1C354 means any        | 3. 'Endow or enhance pathogenicity' is defined   |
|      | 他產生類志賀毒素之血清型之致     | 力。其可能包括以下方面的轉變:                    | sequence specific to the specified | as when the insertion or integration of the      |
|      | 病性有關之核酸序列。         | 病毒性、傳播性、穩定性、感染途                    | "microorganism" that:              | nucleic acid sequence or sequences is/are likely |
|      |                    | 徑、寄主範圍、再現性、逃避或抑                    | a. In itself or through its        | to enable or increase a recipient                |
|      |                    | 制宿主免疫力之能力,以及對於醫                    | transcribed or translated products | organism' sability to be used to deliberately    |
|      |                    | 學防疫措施或檢測的抵抗力。                      | represents a significant hazard to | cause disease or death. This might include       |
|      |                    | 註解:1C353 不管制血清型志賀毒                 | human, animal or plant health; or  | alterations to, inter alia: virulence,           |
|      |                    | 素大腸桿菌 O26、O45、O103、                | b. Is known to enhance the ability | transmissibility, stability, route of            |
|      |                    | O104 · O111 · O121 · O145 · O157 · | of a specified "microorganism", or | infection, host range, reproducibility, ability  |
|      |                    | 以及其他與腸出血性大腸桿菌、                     | any other organism into which it   | to evade or suppress host immunity, resistance   |
|      |                    | O157 血清型及其他產生類志賀毒                  | may be inserted or otherwise       | to medical countermeasures, or detectability.    |
|      |                    | 素之血清型之致病性有關之核酸                     | integrated, to cause serious harm  | Note: 1C353 does not control nucleic acid        |

| 修正條目             | 現行內容                  | 擬修正/新增內容                | 現行內容英譯                              | 擬修正/新增內容英譯  |
|------------------|-----------------------|-------------------------|-------------------------------------|---|
|                  |                       | 序列。                     | to humans, animals or plant health. | sequences of shiga toxin producing Escherichia    |
|                  |                       |                         | Note: 1C353 does not control        | coli of serogroups 026, 045, 0103, 0104, 0111,    |
|                  |                       |                         | nucleic acid sequences associated   | 0121, 0145, 0157, and other shiga toxin producing |
|                  |                       |                         | with the pathogenicity of           | serogroups, other than those genetic elements     |
|                  |                       |                         | enterohaemorrhagic Escherichia      | coding forshiga toxin, or for its subunits.       |
|                  |                       |                         | coli, serotype 0157 and other       |   |
|                  |                       |                         | verotoxin producing strains, other  |   |
|                  |                       |                         | than those coding for the           |   |
|                  |                       |                         | verotoxin, or for its sub-units.    |   |
|                  | 6. N,N-二烷基[甲基、乙基或丙基   | 6. N,N-二烷基[甲基、乙基或丙基     | 6. N, N-Dialkyl [methyl, ethyl or   | 6. N, N-Dialkyl [methyl, ethyl or propyl (normal  |
|                  | (正構或異構)]胺基乙硫醇及其質      | (正構或異構)]胺基乙硫醇及其質        | propyl (normal or iso)]             | or iso)] aminoethane-2-thiols and corresponding   |
|                  | 子化鹽類,但 1C350 所述之 N,N- | 子化鹽類,但 1C350 所述之 N,N-   | aminoethane-2-thiols and            | protonated salts, other than                      |
| 1C. 450. b. 6    | 二異丙基-β-胺基乙硫醇除外;       | 二異丙基-β-胺基乙硫醇            | corresponding protonated salts,     | N, N-Diisopropyl-(beta)-aminoethane thiol         |
| 10. 450. D. 0    |                       | (5842-07-9)與 N,N-二異丙基胺基 | other than                          | (5842-07-9) and N, N-                             |
|                  |                       | 乙硫醇酸鹽(41480-75-5)除外;    | N, N-Diisopropyl-(beta)-aminoetha   | Diisopropylaminoethanethiol hydrochloride         |
|                  |                       |                         | ne thiol which is specified in      | (41480-75-5) which are specified in 1C350;        |
|                  |                       |                         | 1C350;                              |   |
|                  | 註解:2A001 不管制經製造商依     | 註解:2A001 不管制經製造商依       | Note: 2A001 does not control balls  | Note: 2A001 does not control balls with           |
| 2A001 註解         | ISO 3290 標示之公差為等級 5 或 | ISO 3290 標示之公差為等級 5(或   | with tolerances specified by the    | tolerances specified by the manufacturer in       |
| ZAUUI 註牌         | 較次級之滾珠。               | 其他等效國家標準),或較次級之         | manufacturer in accordance with     | accordance with ISO 3290 as grade 5 (or national  |
|                  |                       | 滾珠。                     | ISO 3290 as grade 5 or worse.       | equivalents) or worse.                            |
| 2B001.a註         | 註解2:2B001.a. 不管制僅限棒材  | 註解2:2B001.a. 不管制僅限棒材    | Note 2: 2B001.a. does not control   | Note 2: 2B001.a. does not control bar machines    |
| 2D001.a 註<br>解 2 | 直通進料加工,其可加工之棒材最       | 直通進料加工,其可加工之棒材最         | bar machines (Swissturn), limited   | (Swissturn), limited to machining only bar feed   |
| <u>門午 </u>       | 大直徑小於或等於 42 mm,且不     | 大直徑小於或等於 42 mm,且不       | to machining only bar feed thru, if | thru, if maximum bar diameter is equal to or less |

| 修正條目           | 現行內容                    | 擬修正/新增內容                | 現行內容英譯                              | 擬修正/新增內容英譯  |
|----------------|-------------------------|-------------------------|-------------------------------------|---|
|                | 具加裝夾頭能之走心式車床            | 具加裝夾頭能之走心式車床            | maximum bar diameter is equal to or | than 42 mm and there is no capability of mounting   |
|                | (Swissturn)。此類機器可能具有加   | (Swissturn)。此類機器可能具有加   | less than 42 mm and there is no     | chucks. Machines may have drilling or milling       |
|                | 工零件直徑小於 42 mm 之鑽孔及/     | 工零件直徑小於 42 mm 之鑽孔或      | capability of mounting chucks.      | capabilities for machining parts with diameters     |
|                | 或銑削功能。                  | 銑削功能。                   | Machines may have drilling and/or   | less than 42 mm.                                    |
|                |                         |                         | milling capabilities for machining  |   |
|                |                         |                         | parts with diameters less than 42   |   |
|                |                         |                         | mm.                                 |   |
|                | b.3個或3個以上之軸可同時協調        | b.3個或4個軸可同時協調進行         | b. Three or more axes which can be  | b. Three or four axes which can be coordinated      |
| 2B001. c. 1. b | 進行"輪廓控制";或              | "輪廓控制";或                | coordinated simultaneously for      | simultaneously for "contouring control"; or         |
|                |                         |                         | "contouring control"; or            |   |
|                | 2B006 尺度檢驗或測量系統、設       | 2B006 尺度檢驗或測量系統、設       | 2B006 Dimensional inspection or     | 2B006 Dimensional inspection or measuring           |
|                | 備與"電子組件",如下:            | 備、定為回饋單元及"電子組件",        | measuring systems, equipment and    | systems, equipment, position feedback units and     |
|                | a. 電腦控制或"數值控制"之座        | 如下:                     | "electronic assemblies", as         | "electronic assemblies", as follows:                |
|                | 標測量機具(CMM),依據 ISO       | a. 電腦控制或"數值控制"之座        | follows:                            | a. Computer controlled or "numerical controlled"    |
|                | 10360-2 (2009)標準測試,在該機  | 標測量機具(CMM),依據 ISO       | a. Computer controlled or           | Coordinate Measuring Machines (CMM), having a       |
|                | 具操作範圍內之任何一點進行測          | 10360-2:2009 標準測試,在該機具  | "numerically controlled"            | three dimensional (volumetric) maximum              |
| 2B006          | 試時(亦即在軸的長度以內),其3        | 操作範圍內之任何一點進行測試          | Coordinate Measuring Machines       | permissible error of length measurement (E          |
| 20000          | 維(體積)最大可容許長度量測誤         | 時(亦即在軸的長度以內),其3維        | (CMM), having a three dimensional   | 0,MPE) at any point within the operating range      |
|                | 差(E0,MPE)等於或小於(優於)(1.7  | (體積)最大可容許長度量測誤差         | (volumetric) maximum permissible    | of the machine (i.e., within the length of axes)    |
|                | +L/1,000) μm(L 係以 mm 為單 | (E0,MPE)等於或小於(優於)(1.7+  | error of length measurement (E      | equal to or less (better) than (1,7 + L/1 000)      |
|                | 位之可量測長度);               | L/1,000) μm(L 係以 mm 為單位 | 0, MPE ) at any point within the    | $\mu$ m (L is the measured length in mm), according |
|                | 技術註解:                   | 之可量測長度);                | operating range of the machine      | to ISO 10360-2:2009;                                |
|                | 製造商規格上所訂定最精確座標          | 技術註解:                   | (i.e., within the length of axes)   | Technical Note:                                     |
|                | 測量機具(CMM)組態(如下列項        | 製造商規格上所訂定最精確座標          | equal to or less (better) than (1,7 | The E 0, MPE of the most accurate configuration     |

| 修正條目 | 現行內容                      | 擬修正/新增內容                   | 現行內容英譯  | 擬修正/新增內容英譯   |
|------|---------------------------|----------------------------|---|--|
|      | 目之最佳者:探針、針頭長度、運           | 測量機具(CMM)組態(如下列項           | + L/1 000) $\mu\mathrm{m}$ (L is the measured | of the CMM specified by the manufacturer (e.g.,        |
|      | 動參數及環境),並具有"所有可           | 目之最佳者:探針、針頭長度、運            | length in mm), according to ISO               | best of the following: probe, stylus length,           |
|      | 補償機制"者,其最大可容許長度           | 動參數及環境),並具有"所有可            | 10360-2 (2009);                               | motion parameters, environment) and with "all          |
|      | 量測誤差(E0,MPE)須達到           | 補償機制"者,其最大可容許長度            | Technical Note:                               | compensations available" shall be compared to          |
|      | 1.7+L/1,000 μm之門檻。        | 量測誤差(E0,MPE)須達到            | The E 0, MPE of the most accurate             | the 1,7+L/1 000 $\mu\mathrm{m}$ threshold.             |
|      | 說明:參照 2B206。              | 1.7+L/1,000 μm之門檻。         | configuration of the CMM specified            | N. B. SEE ALSO 2B206.                                  |
|      | b. 直線位移及角位移測量儀器,          | 說明:參照 2B206。               | by the manufacturer (e.g., best of            | b. Linear displacement measuring instruments or        |
|      | 如下所列:                     | b. 線性位移測量儀器或系統、線           | the following: probe, stylus                  | systems, linear position feedback units, and           |
|      | 1. 具下列任一特性之`直線位           | 性定位回饋單元及"電子組件",            | length, motion parameters,                    | "electronic assemblies", as follows:                   |
|      | 移 测量儀器:                   | 如下:                        | environment) and with "all                    | Note: Interferometer and optical-encoder               |
|      | 註解:內含有"雷射"之干涉儀與           | 註解:內含有"雷射"之干涉儀與            | compensations available" shall be             | measuring systems containing a "laser" are only        |
|      | 光編碼器位移測量系統僅由              | 光編碼器位移測量系統僅由               | compared to the 1,7 + L/1 000 $\mu\mathrm{m}$ | specified in 2B006.b.3 and 2B206.c.                    |
|      | 2B006.b.1.c.與 2B206.c.管制。 | 2B006.b.3.與 2B206.c.管制。    | threshold.                                    | 1. 'Non-contact type measuring systems' with a         |
|      | 技術註解:                     | 1. 量測範圍達到 0.2 mm 時, "解     | N. B. SEE ALSO 2B206.                         | "resolution" equal to or less (better) than 0,2        |
|      | 2B006.b.1.所述之`直線位移´係      | 析度″等於或小於(優於)0.2 μm         | b. Linear and angular displacement            | $\mu\mathrm{m}$ within a measuring range up to 0,2 mm; |
|      | 指測量探針和被測量物之間距離            | 之`非接觸式測量系統´;               | measuring instruments, as follows:            | Technical Note:  |
|      | 之變動。                      | 技術註解:                      | 1. 'Linear displacement' measuring            | For the purposes of 2B006.b.1. 'non-contact type       |
|      | a. 量測範圍在 0.2 mm 以內時, "解   | 2B006.b.1.所述之`非接觸式測量       | instruments having any of the                 | measuring systems' are designed to measure the         |
|      | 析度"等於或小於(優於)0.2 μm        | 系統 ,其設計用於測量探針或被            | following:                                    | distance between the probe and measured object         |
|      | 之非接觸式測量系統;                | 測量物在運動時,兩者沿著單一向            | Note: Interferometer and                      | along a single vector, where the probe or              |
|      | b. 具下列所有特性之線性電壓差          | 量之間的距離。                    | optical-encoder displacement                  | measured object is in motion.                          |
|      | 動轉換器(LVDT)系統:             | 2. 總 "準確度(或稱 "精度")" 小      | measuring systems containing a                | 2. Linear position feedback units specially            |
|      | 1. 具有下列任一者:               | 於(優於)(800+(600 x L/1,000)) | "laser" are only controlled in                | designed for machine tools and having an overall       |
|      | a. LVDTs 其`全部作業範圍´至       | nm(L 等於以 mm 為單位之可量測        | 2B006.b.1.c. and 2B206.c.                     | "accuracy" less (better) than (800 + (600 $\times$ L/1 |

| 修正條目 | 現行內容                    | 擬修正/新增內容                  | 現行內容英譯                               | 擬修正/新增內容英譯  |
|------|-------------------------|---------------------------|--------------------------------------|---|
|      | 多且包含±5 mm 時,量測0至~全      | 長度)之線性定位回饋單元;             | Technical Note:                      | 000)) nm (L equals effective length in mm);       |
|      | 部作業範圍一,其"線性度"等於         | 3. 測量系統具下列全部特性:           | For the purpose of 2B006.b.1.        | 3. Measuring systems having all of the following: |
|      | 或小於(優於)0.1%;或           | a. 含有一"雷射";               | 'linear displacement' means the      | a. Containing a "laser";                          |
|      | b. LVDTs 其`全部作業範圍´大     | b. 整個量測範圍內之 "解析度"         | change of distance between the       | b. A "resolution" over their full scale of 0,200  |
|      | 於±5 mm 時,量測0至5 mm,其     | 為 0.2 nm 或以下(優於); 及       | measuring probe and the measured     | nm or less (better); and                          |
|      | "線性度"等於或小於(優於)0.1       | c.在 20 ±0.01 ℃溫度下測量 30    | object.                              | c. Capable of achieving a "measurement            |
|      | %;及                     | 秒,經補償空氣折射率後,在量測           | a. Non-contact type measuring        | uncertainty" equal to or less (better) than (1,6  |
|      | 2. 在標準周圍環境測試室溫±1 K      | 範圍內的任何一點,能實現"量測           | systems with a "resolution" equal    | + L/2 000) nm (L is the measured length in mm)    |
|      | 下,每日之漂移等於或小於(優於)        | 不準度″等於或小於(優於)(1.6+        | to or less (better) than 0,2 $\mu$ m | at any point within a measuring range, when       |
|      | 0.1%;                   | L/2,000) nm (L 係以 mm 為單位測 | within a measuring range up to 0, 2  | compensated for the refractive index of air and   |
|      | 技術註解:                   | 得之長度);或                   | mm;                                  | measured over a period of 30 seconds at a         |
|      | 就 2B006.b.1.b.目的, `全部作業 | 4. 為提供 2B006.b.3.所列系統回    | b. Linear Variable Differential      | temperature of 20± 0,01 °C; or                    |
|      | 範圍「為LVDT全部可能之直線         | 饋能力而特別設計之"電子組             | Transformer (LVDT) systems having    | 4. "Electronic assemblies" specially designed to  |
|      | 位移的一半。舉例來說,LVDTs        | 件";                       | all of the following:                | provide feedback capability in systems specified  |
|      | 其`全部作業範圍´至多且包含          | c. 特別為機械工具或角度位移測          | 1. Having any of the following:      | in 2B006.b.3.;                                    |
|      | ±5 mm 時,能量測之全部可能直       | 量儀器設計之旋轉定位回饋單             | a. "Linearity" equal to or less      | c. Rotary position feedback units specially       |
|      | 線位移為 10 mm。             | 元,具有角度位置 "準確度(或稱          | (better) than 0,1 % measured from    | designed for machine tools or angular             |
|      | 2B006 (續)               | "精度")"小於(優於) 0.9 arcsec   | 0 to the 'full operating range',     | displacement measuring instruments, having an     |
|      | c. 如下之測量系統:             | 者;                        | for LVDTs with a 'full operating     | angular position "accuracy" equal to or less      |
|      | 1. 含有一"雷射";及            | 註解:2B006.c.不管制光學儀器,       | range' up to and including ± 5 mm;   | (better) than 0,9 second of arc;                  |
|      | 2. 整個量測範圍內之 "解析度"       | 如自動準直儀使用準直光(例如            | or                                   | Note: 2B006.c. does not control optical           |
|      | 為 0.2 nm 或以下(較優); 及     | "雷射"光)用於偵測鏡面角度位           | b. "Linearity" equal to or less      | instruments, such as autocollimators, using       |
|      | 3.在 20 ±0.01 ℃溫度下測量 30  | 移。                        | (better) than 0,1 % measured from    | collimated light (e.g. "laser" light) to detect   |
|      | 秒,經補償空氣折射率後,在量測         | d. 藉由測量光散射以測量表面粗          | 0 to 5 mm for LVDTs with a 'full     | angular displacement of a mirror.                 |

| 修正條目 | 現行內容                      | 擬修正/新增內容               | 現行內容英譯                               | 擬修正/新增內容英譯                                      |
|------|---------------------------|------------------------|--------------------------------------|---|
|      | 範圍內的任何一點,能實現"量測           | 糙度(包括表面缺陷) ,其靈敏度       | operating range' greater than ± 5    | d. Equipment for measuring surface roughness    |
|      | 不準度″等於或小於(優於)(1.6+        | 為 0.5nm 或以下(優於)者。      | mm; and                              | (including surface defects), by measuring       |
|      | L/2,000) nm (L 係以 mm 為單位測 | 註解: 2B006 包含除 2B001 管制 | 2. Drift equal to or less (better)   | optical scatter with a sensitivity of 0,5 nm or |
|      | 得之長度);或                   | 外之可用作測量機具之工具機,其        | than 0,1 % per day at a standard     | less (better).                                  |
|      | d. 為提供 2B006.b.1.c.所列系統回  | 規格如符合或超過測量機具功能         | ambient test room temperature ±1 K;  | Note: 2B006 includes machine tools, other than  |
|      | 授能力而特別設計之"電子組             | 所列之標準,即受管制。            | Technical Note:                      | those specified in 2B001, that can be used as   |
|      | 件";                       |                        | For the purposes of 2B006.b.1.b.,    | measuring machines if they meet or exceed the   |
|      | 註解:2B006.b.1.不管制測量干涉      |                        | 'full operating range' is half of    | criteria specified for the measuring machine    |
|      | 儀系統,其具有不使用回授技術之           |                        | the total possible linear            | function.                                       |
|      | 自動控制系統,並利用"雷射"以           |                        | displacement of the LVDT. For        |   |
|      | 測量工具機、尺度檢驗機具或類似           |                        | example, LVDTs with a 'full          |   |
|      | 設備之滑動誤差。                  |                        | operating range' up to and           |   |
|      | 2. 角度位置 "準確度(或稱 "精        |                        | including ± 5 mm can measure a total |   |
|      | 度")"等於或小於(優於)0.00025°     |                        | possible linear displacement of 10   |   |
|      | 之角位移測量儀器;                 |                        | mm.                                  |   |
|      | 註解:2B006.b.2.不管制如自動準      |                        | c. Measuring systems having all of   |   |
|      | 直儀之光學儀器,該儀器乃利用準           |                        | the following:                       |   |
|      | 直光(如"雷射"光)偵測鏡子之角          |                        | 1. Containing a "laser";             |   |
|      | 位移。                       |                        | 2. A "resolution" over their full    |   |
|      | c. 藉由測量不同角度之光散射以          |                        | scale of 0,200 nm or less (better);  |   |
|      | 量測表面粗糙度(包括表面缺             |                        | and                                  |   |
|      | 陷),且其靈敏度為 0.5nm 或以下       |                        | 3. Capable of achieving a            |   |
|      | (更優)者。                    |                        | "measurement uncertainty" equal to   |   |
|      | 註解:2B006 包含除 2B001 管制     |                        | or less (better) than (1,6 + L/2     |   |

| 修正條目 | 現行內容            | 擬修正/新增內容 | 現行內容英譯                              | 擬修正/新增內容英譯 |
|------|-----------------|----------|-------------------------------------|------------|
|      | 外之可用作測量機具之工具機,其 |          | 000) nm (L is the measured length   |            |
|      | 規格如符合或超過測量機具功能  |          | in mm) at any point within a        |            |
|      | 所列之標準,即受管制。     |          | measuring range, when compensated   |            |
|      |                 |          | for the refractive index of air and |            |
|      |                 |          | measured over a period of 30        |            |
|      |                 |          | seconds at a temperature of 20 ±    |            |
|      |                 |          | 0,01 °C; or                         |            |
|      |                 |          | d. "Electronic assemblies"          |            |
|      |                 |          | specially designed to provide       |            |
|      |                 |          | feedback capability in systems      |            |
|      |                 |          | specified in 2B006.b.1.c.;          |            |
|      |                 |          | Note: 2B006.b.1. does not control   |            |
|      |                 |          | measuring interferometer systems,   |            |
|      |                 |          | with an automatic control system    |            |
|      |                 |          | that is designed to use no feedback |            |
|      |                 |          | techniques, containing a "laser"    |            |
|      |                 |          | to measure slide movement errors of |            |
|      |                 |          | machine-tools, dimensional          |            |
|      |                 |          | inspection machines or similar      |            |
|      |                 |          | equipment.                          |            |
|      |                 |          | 2. Angular displacement measuring   |            |
|      |                 |          | instruments having an angular       |            |
|      |                 |          | position "accuracy" equal to or     |            |
|      |                 |          | less (better) than 0,00025 o;       |            |

| 修正條目     | 現行內容            | 擬修正/新增內容 | 現行內容英譯                              | 擬修正/新增內容英譯   |
|----------|-----------------|----------|-------------------------------------|--------------|
|          |                 |          | Note: 2B006.b.2. does not control   |              |
|          |                 |          | optical instruments, such as        |              |
|          |                 |          | autocollimators, using collimated   |              |
|          |                 |          | light (e.g., "laser" light) to      |              |
|          |                 |          | detect angular displacement of a    |              |
|          |                 |          | mirror.                             |              |
|          |                 |          | c. Equipment for measuring surface  |              |
|          |                 |          | roughness (including surface        |              |
|          |                 |          | defects), by measuring optical      |              |
|          |                 |          | scatter with a sensitivity of 0,5   |              |
|          |                 |          | nm or less (better).                |              |
|          |                 |          | Note: 2B006 includes machine        |              |
|          |                 |          | tools, other than those specified   |              |
|          |                 |          | by 2B001, that can be used as       |              |
|          |                 |          | measuring machines if they meet or  |              |
|          |                 |          | exceed the criteria specified for   |              |
|          |                 |          | the measuring machine function.     |              |
|          | a. 於全3維影像處理或全3維 | a. 刪除;   | a. Capable in real time of full     | a. Not used; |
|          | `背景分析´時,可即時產生或修 |          | three-dimensional image             |              |
|          | 改"程式",或可產生或修改數值 |          | processing or full                  |              |
| 2B007. a | 程式資料;           |          | three-dimensional 'scene            |              |
|          |                 |          | analysis' to generate or modify     |              |
|          |                 |          | "programs" or to generate or modify |              |
|          |                 |          | numerical program data;             |              |

| 修正條目  | 現行內容                       | 擬修正/新增內容           | 現行內容英譯                               | 擬修正/新增內容英譯  |
|-------|----------------------------|--------------------|--------------------------------------|---|
|       | 2B008 專為工具機或尺度檢驗           | 2B008 專為工具機特別設計之   | 2B008 Assemblies or units,           | 2B008 'Compound rotary tables' and "tilting       |
|       | 或測量系統及設備所特別設計之             | `複合迴轉工作台`及`擺動式     | specially designed for machine       | spindles", specially designed for machine tools,  |
|       | 組件或單元,如下:                  | 主軸 ,如下:            | tools, or dimensional inspection     | as follows:                                       |
|       | a. 總 "準確度(或稱 "精度")" 小      | a. 刪除;             | or measuring systems and             | a. Not used;                                      |
|       | 於(優於)(800+(600 × L/1,000)) | b. 刪除;             | equipment, as follows:               | b. Not used;                                      |
|       | nm(L 等於以 mm 為單位之可量測        | c. `複合迴轉工作台´具下列所   | a. Linear position feedback units    | c. 'Compound rotary tables' having all of the     |
|       | 長度)之線性定位回饋單元;              | 有特性:               | having an overall "accuracy" less    | following:  |
|       | 說明:"雷射"系統,參照               | 1. 設計用於機械工具車削、銑削   | (better) than (800 + (600 × L/1      | 1. Designed for machine tools for turning,        |
|       | 2B006.b.1.c.、2B006.b.1.d.與 | 或研磨;及              | 000)) nm (L equals the effective     | milling or grinding; and                          |
|       | 2B206.c.之註解。               | 2. 具 2 個旋轉軸設計用於同時協 | length in mm);                       | 2. Two rotary axes designed to be coordinated     |
|       | b. "準確度(或稱 "精度")" 小於       | 調進行"輪廓控制";         | N.B. For "laser" systems see also    | simultaneously for "contouring control";          |
| 2B008 | (優於)0.00025°之旋轉定位回饋單       | 技術註解:              | 2B006. b. 1. c., 2B006. b. 1. d. and | Technical Note:                                   |
| 20000 | 元;                         | `複合迴轉工作台´指可使工作     | 2В206. с.                            | A' compound rotary table' is a table allowing the |
|       | 說明:"雷射"系統,參照 2B006.b.2.    | 物件在2個非平行軸線上旋轉與     | b. Rotary position feedback units    | workpiece to rotate and tilt about two            |
|       | 註解。                        | 傾斜之工作台。            | having an "accuracy" less (better)   | non-parallel axes                                 |
|       | 註解: 2B008.a.與 2B008.b.管制項  | d. `擺動式主軸´具下列所有特   | than 0,00025 o ;                     | d. "Tilting spindles" having all of the           |
|       | 目,其設計為回饋控制測定之位置            | 性:                 | N.B. For "laser" systems see also    | following:  |
|       | 資訊,包括感應式元件、刻度尺、            | 1. 設計用於機械工具車削、銑削   | Note to 2B006, b. 2.                 | 1. Designed for machine tools for turning,        |
|       | 紅外線系統或"雷射"系統。              | 或研磨;及              | Note: 2B008.a. and 2B008.b.          | milling or grinding; and                          |
|       | c. 依據製造商之規範,能提升工           | 2. 設計用於同時協調進行 "輪廓  | control units, which are designed    | 2. Designed to be coordinated simultaneously for  |
|       | 具機等級達到或超越2B指定等級            | 控制";               | to determine the positioning         | "contouring control".                             |
|       | 之"複合迴轉工作台"及"擺動式            |                    | information for feedback control,    |   |
|       | 主軸"。                       |                    | such as inductive type devices,      |   |
|       |                            |                    | graduated scales, infrared systems   |   |

| 修正條目    | 現行內容                | 擬修正/新增內容            | 現行內容英譯                               | 擬修正/新增內容英譯                                       |
|---------|---------------------|---------------------|--------------------------------------|--|
|         |                     |                     | or "laser" systems.                  |  |
|         |                     |                     | c. "Compound rotary tables" and      |  |
|         |                     |                     | "tilting spindles", capable of       |  |
|         |                     |                     | upgrading, according to the          |  |
|         |                     |                     | manufacturer's specifications,       |  |
|         |                     |                     | machine tools to or above the        |  |
|         |                     |                     | levels specified in 2B.              |  |
|         | 2B109 除2B009所述以外之流動 | 2B109 除2B009所述以外之流動 | 2B109 Flow-forming machines, other   | 2B109 Flow-forming machines, other than those    |
|         | 成型機,及特別設計之零件,如      | 成型機,其可"生產"用於"飛彈"    | than those specified in 2B009, and   | specified in 2B009, usable in the "production"   |
|         | 下:                  | 之推進器零件及設備(例如馬達殼     | specially designed components as     | of propulsion components and equipment (e.g.     |
|         | 說明:參照 2B209。        | 體、級間結構),及特別設計之零     | follows:                             | motor cases and interstages) for "missiles", and |
|         | a. 具下列所有特性之流動成型     | 件,如下:               | N. B. SEE ALSO 2B209.                | specially designed components as follows:        |
|         | 機:                  | 說明:參照 2B209。        | a. Flow-forming machines having      | N. B. SEE ALSO 2B209.                            |
|         | 1. 依據製造商的技術規格,可裝    | a. 具下列所有特性之流動成型     | all of the following:                | a. Flow-forming machines having all of the       |
| 2B109   | 置"數值控制"單元或電腦控制單     | 機:                  | 1. According to the manufacturer's   | following:                                       |
| ZD109   | 元,甚至並未裝置此等控制單元      | 1. 本身已配備,或依據製造商的    | technical specification, can be      | 1. Equipped with, or according to the            |
|         | 者;及                 | 技術規格,其可裝置"數值控制"     | equipped with "numerical control"    | manufacturer's technical specification are       |
|         | 2. 具有 2 個軸以上,且可同時協  | 單元或電腦控制單元; 及        | units or a computer control, even    | capable of being equipped with "numerical        |
|         | 調進行"輪廓控制"。          | 2. 具有 2 個軸以上,且可同時協  | when not equipped with such units;   | control" units or computer control; and          |
|         |                     | 調進行"輪廓控制"。          | and                                  | 2. More than two axes which can be coordinated   |
|         |                     |                     | 2. With more than two axes which can | simultaneously for "contouring control".         |
|         |                     |                     | be coordinated simultaneously for    |  |
|         |                     |                     | "contouring control".                |  |
| 2B120.a | a. 2 軸或以上;          | a. 2 個或 2 個以上的軸;    | a. Two axes or more;                 | a. Two or more axes;                             |

| 修正條目     | 現行內容                       | 擬修正/新增內容                    | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|----------|----------------------------|-----------------------------|-------------------------------------|--|
| 2B121.a  | a. 2 軸或以上;及                | a. 2 個或 2 個以上的軸;及           | a. Two axes or more; and            | a. Two or more axes; and                         |
|          | 2B122 能提供加速度超過 100 g       | 2B122 能提供加速度大於 100 g        | 2B122 Centrifuges capable of        | 2B122 Centrifuges capable of imparting           |
|          | 之離心機,設計或改裝能容納滑環            | 之離心機,設計或改裝能容納滑環             | imparting accelerations above 100   | accelerations greater than 100 g and designed or |
|          | 或積體非接觸設備,能傳輸電力及            | 或積體非接觸設備,能傳輸電力及             | g and designed or modified to       | modified to incorporate slip rings or integrated |
| 2B122    | 訊號資訊,或同時傳輸兩者。              | 訊號資訊,或同時傳輸兩者。               | incorporate slip rings or           | non-contact devices capable of transferring      |
| ZD1 ZZ   |                            |                             | integrated non-contact devices      | electrical power, signal information, or both.   |
|          |                            |                             | capable of transferring electrical  |  |
|          |                            |                             | power, signal information, or       |  |
|          |                            |                             | both.                               |  |
|          | 技術註解:                      | 技術註解:                       | Technical Note:                     | Technical Note:                                  |
|          | 工具機機型之定位精度聲明級等             | 工具機機型之定位精度聲明等級              | Stated positioning accuracy levels  | Stated positioning accuracy levels derived under |
|          | 可用以下程序遵照 ISO               | 可用以下程序遵照 ISO                | derived under the following         | the following procedures from measurements made  |
|          | 230-2:1988 ,或同效之國家標準       | 230-2:1988 ,或同效之國家標準        | procedures from measurements made   | according to ISO 230-2:1988 (1) or national      |
|          | (若有提供)並經國家權責單位同            | (若有提供)並經國家權責單位同             | according to ISO 230-2:1988 (1)     | equivalents may be used for each machine tool    |
|          | 意下,以取代個別之機器測試。測            | 意下,以取代個別之機器測試。測             | or national equivalents may be used | model if provided to, and accepted by, national  |
| 2B201 技術 | 定定位精度方法如下:                 | 定定位精度方法如下:                  | for each machine tool model if      | authorities instead of individual machine tests. |
| 註解       | a.選擇同型號之機器5台進行評            | a.選擇同型號之機器5台進行評             | provided to, and accepted by,       | Determination of stated positioning accuracy:    |
| 山八叶      | 量;                         | 量;                          | national authorities instead of     | a. Select five machines of a model to be         |
|          | b.依 ISO 230-2:1988 (1)測量線性 | b.依 ISO 230-2:1988(1,2)測量線性 | individual machine tests.           | evaluated;                                       |
|          | 軸;                         | 軸;                          | Determination of stated             | b. Measure the linear axis accuracies according  |
|          | c.測定每一台機器之定位精度             | c.測定每一台機器之定位精度              | positioning accuracy:               | to ISO 230-2:1988 ( 1 );                         |
|          | (A)。計算精度值之方式記載於            | (A)。計算精度值之方式記載於             | a. Select five machines of a model  | c. Determine the accuracy values (A) for each    |
|          | ISO 230-2:1988 (1) 標準內;    | ISO 230-2:1988(1,2) 標準內;    | to be evaluated;                    | axis of each machine. The method of calculating  |
|          | d.測定每一軸之平均定位精度             | d.測定每一軸之平均定位精度              | b. Measure the linear axis          | the accuracy value is described in the ISO       |

| 修正條目 | 現行內容                          | 擬修正/新增內容                      | 現行內容英譯  | 擬修正/新增內容英譯   |
|------|-------------------------------|-------------------------------|---|--|
|      | 值。此平均值即為此機型之每一軸               | 值。此平均值即為此機型之每一軸               | accuracies according to ISO                   | 230-2:1988 ( 1 ) standard;                                 |
|      | (^Ax ^Ay…) 定位精度之聲明值;          | (^Ax ^Ay…) 定位精度之聲明值;          | 230-2:1988 ( 1 );                             | d. Determine the average accuracy value of each            |
|      | e.由於 2B201 涉及每一線性軸,因          | e.由於 2B201 涉及每一線性軸,因          | c. Determine the accuracy values              | axis. This average value becomes the stated                |
|      | 此有多少線性軸即有多少個定位                | 此有多少線性軸即有多少個定位                | (A) for each axis of each machine.            | positioning accuracy of each axis for the model            |
|      | 精度聲明值                         | 精度聲明值;                        | The method of calculating the                 | (Âx Ây···);  |
|      | f.若一機器型號之任一軸其定位               | f.若一機器型號之任一軸其定位               | accuracy value is described in the            | e. Since Item 2B201 refers to each linear axis,            |
|      | 精度聲明值雖不在 2B201.a.、            | 精度聲明值雖不在 2B201.a.、            | ISO 230-2:1988 ( 1 ) standard;                | there will be as many stated positioning accuracy          |
|      | 2B201.a.或 2B201.c.管制內,但研      | 2B201.a.或 2B201.c.規範中,但研      | d. Determine the average accuracy             | values as there are linear axes;                           |
|      | 磨型機器依 ISO 230-2:1988 (1)測     | 磨型機器依 ISO 230-2:1988(1,2)測    | value of each axis. This average              | f. If any axis of a machine tool not specified             |
|      | 得之定位精度聲明值等於或小於                | 得之定位精度聲明值等於或小於                | value becomes the stated                      | in 2B201.a., 2B201.b. or 2B201.c. has a stated             |
|      | (優於)6 µm、銑削及車削型機器             | (優於)6 µm、銑削及車削型機器             | positioning accuracy of each axis             | positioning accuracy of 6 $\mu\mathrm{m}$ or better (less) |
|      | 依 ISO 230-2:1988 (1)測得之定位     | 依 ISO 230-2:19881,2 測得之定位     | for the model (Âx Ây);                        | for grinding machines, and 8 $\mu$ m or better (less)      |
|      | 精度聲明值等於或小於(優於)8               | 精度聲明值等於或小於(優於)8               | e. Since Item 2B201 refers to each            | for milling and turning machines, both according           |
|      | μm者,則製造商必須每18個月               | μm者,則製造商必須每18個月               | linear axis, there will be as many            | to ISO 230-2:1988 (1), then the builder should             |
|      | 再確認一次其精度等級。                   | 再確認一次其精度等級。                   | stated positioning accuracy values            | be required to reaffirm the accuracy level once            |
|      | (1)製造商測量定位精度標準係用              | (1)製造商測量定位精度標準係用              | as there are linear axes;                     | every eighteen months.                                     |
|      | ISO230-2:1997 或 ISO230-2:2006 | ISO230-2:1997 或 ISO230-2:2006 | f. If any axis of a machine tool not          | (1) Manufacturers calculating positioning                  |
|      | 應諮詢成員國權責單位。                   | 應諮詢成員國權責單位。                   | controlled by 2B201.a., 2B201.b.              | accuracy in accordance with ISO 230-2:1997 or              |
|      | (2)本管制項目之定位精度標準係              | (2)本管制項目之定位精度標準係              | or 2B201.c. has a stated                      | 2006 should consult the competent authorities of           |
|      | 採 ISO230-2:2006, 其與           | 採 ISO230-2:2006,其與            | positioning accuracy of 6 $\mu \mathrm{m}$ or | the Member State in which they are established.            |
|      | ISO230-2:1988 相同,換算比率約        | ISO230-2:1988 相同,換算比率約        | better (less) for grinding                    |  |
|      | 為 4:3。                        | 為 4:3。                        | machines, and 8 $\mu\mathrm{m}$ or better     |  |
|      |                               |                               | (less) for milling and turning                |  |
|      |                               |                               | machines, both according to ISO               |  |

| 修正條目        | 現行內容                      | 擬修正/新增內容                    | 現行內容英譯                                   | 擬修正/新增內容英譯  |
|-------------|---------------------------|-----------------------------|--|---|
|             |                           |                             | 230-2:1988 (1), then the builder         |   |
|             |                           |                             | should be required to reaffirm the       |   |
|             |                           |                             | accuracy level once every eighteen       |   |
|             |                           |                             | months.                                  |   |
|             |                           |                             | (1) Manufacturers calculating            |   |
|             |                           |                             | positioning accuracy in accordance       |   |
|             |                           |                             | with ISO 230-2:1997 or 2006 should       |   |
|             |                           |                             | consult the competent authorities        |   |
|             |                           |                             | of the Member State in which they        |   |
|             |                           |                             | are established.                         |   |
|             | b. 具下列任一特性之研磨用工具          | b. 具下列任一特性之研磨用工具            | b. Machine tools for grinding,           | b. Machine tools for grinding, having any of the            |
|             | 機:                        | 機:                          | having any of the following              | following characteristics:                                  |
|             | 1. 依照 ISO 230-2:1988 或等效國 | 1. 依照 ISO 230-2:1988(1,2)或等 | characteristics:                         | 1. Positioning accuracies with "all                         |
|             | 家標準,在"所有補償機制"下沿           | 效國家標準,在"所有補償機制"             | 1. Positioning accuracies with           | compensations available" equal to or less                   |
| 2B201. b. 1 | 任一線性軸之定位精度等於或小            | 下沿任一線性軸之定位精度等於              | "all compensations available"            | (better) than 4 $\mu\mathrm{m}$ according to ISO 230-2:1988 |
|             | 於(優於)4 μm;                | 或小於(優於)4 µm;                | equal to or less (better) than 4 $\mu$ m | (1) or national equivalents along any linear                |
|             |                           |                             | according to ISO 230-2:1988 (1)          | axis;   |
|             |                           |                             | or national equivalents along any        |   |
|             |                           |                             | linear axis;                             |   |
|             | b. 無 Z 軸或 W 軸之工模研磨機,      | b. 無 Z 軸或 W 軸之工模研磨機,        | b. Jig grinders that do not have a       | b. Jig grinders that do not have a z-axis or a              |
| 2B201, b, 3 | 且依照 ISO 230-2:1988 或等效國   | 且依照 ISO 230-2:1988(1,2)或等效  | z-axis or a w-axis with an overall       | w-axis with an overall positioning accuracy less            |
| 主解 b        | 家標準,其總定位精確度小於(優           | 國家標準,其總定位精確度小於              | positioning accuracy less (better)       | (better) than 4 $\mu\mathrm{m}$ according to ISO 230-2:1988 |
| ₩ AT U      | 於)4 μm。                   | (優於)4 μm。                   | than 4 $\mu$ m according to ISO          | (1) or national equivalents.                                |
|             |                           |                             | 230-2:1988 1 or national                 |   |

| 修正條目        | 現行內容                        | 擬修正/新增內容                    | 現行內容英譯                                      | 擬修正/新增內容英譯   |
|-------------|-----------------------------|-----------------------------|---|--|
|             |                             |                             | equivalents.                                |  |
|             | 2.標準溫度和標準壓力情況下,在            | 2. 標準溫度和標準壓力下,能夠            | 2. Maintaining, for at least 12             | 2. Capable of maintaining, for at least 12 hours,    |
|             | ±1 K 溫度下保持至少 12 小時,全        | 在±1 K (± 1°C)溫度下維持至少        | hours, at a temperature of ± 1 K            | at a temperature of ± 1 K (± 1 °C); around a         |
|             | 部如下:                        | 12 小時,具下列所有特性:              | around a standard temperature and           | standard temperature and standard pressure, all      |
|             | a. "解析度"在全尺度情况下等            | a. "解析度"在全尺度情况下等            | standard pressure, all of the               | of the following:                                    |
|             | 於或優於 0,1 μm; 及              | 於或優於 0,1 μm; 及              | following:                                  | a. A "resolution" over their full scale of 0,1       |
| 2B206. c. 2 | b. "量測不準度"等於或小於(優           | b. "量測不準度"等於或小於(優           | a. A "resolution" over their full           | $\mu$ m or better; and                               |
| ZDZ00. C. Z | 於) (0,2 + L/2,000) μm (L 係以 | 於) (0,2 + L/2,000) μm (L 係以 | scale of 0,1 $\mu\mathrm{m}$ or better; and | b. With a "measurement uncertainty" equal to or      |
|             | mm 為單位之可量測長度)。              | mm 為單位之可量測長度)。              | b. With a "measurement                      | better (less) than (0,2 + L/2 000) $\mu$ m (L is the |
|             |                             |                             | uncertainty" equal to or better             | measured length in mm).                              |
|             |                             |                             | (less) than (0, 2 + L/2 000) $\mu$ m (L     |  |
|             |                             |                             | is the measured length in                   |  |
|             |                             |                             | millimeters).                               |  |
|             | 無                           | d. 線性電壓差動轉換器(LVDT)          | _   | d. Linear variable differential transformer          |
|             |                             | 系統具下列兩項特性:                  |   | (LVDT) systems having both of the following          |
|             |                             | 技術註解:                       |   | characteristics:                                     |
|             |                             | 就 2B206.d.之目的而言, 線性位        |   | Technical Note:                                      |
|             |                             | 移「指量測探針與被測物體間之              |   | For the purpose of 2B206.d. 'linear                  |
| 2B206. d    |                             | 距離變化 。                      |   | displacement' means the change of distance           |
|             |                             | 1. 具下列任一特性:                 |   | between the measuring probe and the measured         |
|             |                             | a. 操作範圍達到 5 mm 的 LVDT,      |   | object.  |
|             |                             | 在0至全部操作範圍內測量之"線             |   | 1. Having any of the following:                      |
|             |                             | 性度"等於或小於(優於) 0.1%;或         |   | a. "Linearity" equal to or less (better) than 0, 1   |
|             |                             | b. 操作範圍超過 5 mm 的            |   | % measured from 0 to the full operating range,       |

| 修正條目  | 現行內容   | 擬修正/新增內容                                      | 現行內容英譯   | 擬修正/新增內容英譯   |
|-------|--|---|--|--|
|       |  | LVDT,在0至5mm操作範圍內                              |  | for LVDTs with an operating range up to 5 mm; or   |
|       |  | 測量之 "線性度" 等於或小於(優                             |  | b. "Linearity" equal to or less (better) than 0, 1 |
|       |  | 於) 0.1%;                                      |  | % measured from 0 to 5 mm for LVDTs with an        |
|       |  | 2. 在標準周圍環境測試室溫±1                              |  | operating range greater than 5 mm; and             |
|       |  | K(± 1°C)下,每日之漂移等於或                            |  | 2. Drift equal to or better (less) than 0,1% per   |
|       |  | 小於(優於) 0.1%;                                  |  | day at a standard ambient test room temperature    |
|       |  |   |  | ± 1 K (± 1 °C).                                    |
|       | 2B227 真空或其他控制氣壓冶金                            | 2B227 真空或其他控制氣壓冶金                             | 2B227 Vacuum or other controlled                           | 2B227 Vacuum or other controlled atmosphere        |
|       | 熔爐及鑄造爐,及相關設備,如                               | 熔爐及鑄造爐,及相關設備,如                                | atmosphere metallurgical melting                           | metallurgical melting and casting furnaces and     |
|       | 下:   | 下:  | and casting furnaces and related                           | related equipment as follows:                      |
|       | a. 具下列 2 項特性之電弧再熔爐                           | a.電弧再熔爐、電弧熔爐與電弧熔                              | equipment as follows:                                      | a. Arc remelt furnaces, arc melt furnaces and arc  |
|       | 及鑄造爐:  | 煉及鑄造爐,具下列2項特性:                                | a. Arc remelt and casting furnaces                         | melt and casting furnaces having both of the       |
|       | 1. 可消耗之電極容量介於 1,000                          | 1. 可消耗之電極容量介於 1,000                           | having both of the following                               | following characteristics:                         |
|       | cm <sup>3</sup> 至20,000 cm <sup>3</sup> 之間;及 | cm <sup>3</sup> 至 20,000 cm <sup>3</sup> 之間;及 | characteristics:   | 1. Consumable electrode capacities between 1 000   |
|       | 2. 可於熔化溫度超過 1,973                            | 2. 可於熔化溫度超過 1,973                             | 1. Consumable electrode capacities                         | cm $^3$ and 20 000 cm $^3$ ; and                   |
| 2B227 | K(1,700°C)下操作;                               | K(1,700°C)下操作;                                | between 1 000 cm <sup>3</sup> and 20 000 cm <sup>3</sup> ; | 2. Capable of operating with melting               |
|       | b. 具下列 2 項特性之電子束熔爐                           | b. 電子束熔爐、電漿原子化熔爐                              | and  | temperatures above 1 973 K (1 700 °C);             |
|       | 及電漿原子化及熔爐:                                   | 及電漿熔爐,具下列2項特性:                                | 2. Capable of operating with                               | b. Electron beam melting furnaces, plasma          |
|       | 1. 功率為 50 kW 或以上;及                           | 1. 功率為 50 kW 或以上;及                            | melting temperatures above 1 973 K                         | atomization furnaces and plasma melting            |
|       | 2. 可於熔化溫度超過 1,473                            | 2. 可於熔化溫度超過 1,473                             | (1 700 °C);  | furnaces, having both of the following             |
|       | K(1,200°C)下操作。                               | K(1,200 °C)下操作。                               | b. Electron beam melting furnaces                          | characteristics:                                   |
|       |  |   | and plasma atomization and melting                         | 1. A power of 50 kW or greater; and                |
|       |  |   | furnaces, having both of the                               | 2. Capable of operating with melting               |
|       |  |   | following characteristics:                                 | temperatures above 1 473 K (1 200 °C);             |

| 修正條目      | 現行內容                  | 擬修正/新增內容              | 現行內容英譯                              | 擬修正/新增內容英譯  |
|-----------|-----------------------|-----------------------|-------------------------------------|---|
|           |                       |                       | 1. A power of 50 kW or greater; and |   |
|           |                       |                       | 2. Capable of operating with        |   |
|           |                       |                       | melting temperatures above 1 473 K  |   |
|           |                       |                       | (1 200 °C);                         |   |
| 2B350.a 說 | 無                     | 說明:用於預製維修組件,參閱        | -                                   | N.B. For prefabricated repair assemblies, see     |
| 明         |                       | 2B350.k. °            |                                     | 2B350. k.   |
| 2B350.c 說 | 無                     | 說明:用於預製維修組件,參閱        | -                                   | N.B. For prefabricated repair assemblies, see     |
| 明         |                       | 2B350.k. °            |                                     | 2B350. k.   |
|           | 無                     | k. 預製維修組件之金屬表面,其      | -                                   | k. Prefabricated repair assemblies having         |
|           |                       | 與處理化學品直接接觸,由鉭或鉭       |                                     | metallic surfaces that come in direct contact     |
|           |                       | 合金製造,以及為其專門設計之零       |                                     | with the chemical(s) being processed which are    |
|           |                       | 件:                    |                                     | made from tantalum or tantalum alloys as follows, |
|           |                       | 1. 設計用於機械性連結 2B350.a. |                                     | and specially designed components therefor:       |
| 2B350. k  |                       | 所述之玻璃襯裏反應容器或反應        |                                     | 1. Designed for mechanical attachment to          |
|           |                       | 器;或                   |                                     | glass-lined reaction vessels or reactors          |
|           |                       | 2. 設計用於機械性連結 2B350.c. |                                     | specified in 2B350.a.; or                         |
|           |                       | 所述之玻璃襯裏儲槽、容器或接收       |                                     | 2. Designed for mechanical attachment to          |
|           |                       | 器。                    |                                     | glass-lined storage tanks, containers or          |
|           |                       |                       |                                     | receivers specified in 2B350.c.                   |
|           | 2B351 除 1A004 所述以外之毒性 | 2B351 除 1A004 所述以外之毒性 | 2B351 Toxic gas monitoring systems  | 2B351 Toxic gas monitors and monitoring systems   |
|           | <b>氣體監控系統,以及其專用偵測</b> | 氣體監控器與監控系統,以及其專       | and their dedicated detecting       | and their dedicated detecting components, other   |
| 2B351     | 器,與為此用途之偵測器、感測器       | 用偵測器,與為此用途之偵測器、       | components, other than those        | than those specified in 1A004, as follows; and    |
|           | 設備,以及可替換之感測器卡匣:       | 感測器設備,以及可替換之感測器       | specified in 1A004, as follows; and | detectors; sensor devices; and replaceable        |
|           |                       | 卡匣:                   | detectors; sensor devices; and      | sensor cartridges therefor:                       |

| 修正條目  | 現行內容                       | 擬修正/新增內容                   | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|-------|----------------------------|----------------------------|-------------------------------------|--|
|       |                            |                            | replaceable sensor cartridges       |  |
|       |                            |                            | therefor:                           |  |
|       | 2B352 可用於處理生物材料之設          | 2B352 生物製造及處理設備,如          | 2B352 Equipment capable of use in   | 2B352 Biological manufacturing and handling      |
|       | 備,如下:                      | 下:                         | handling biological materials, as   | equipment, as follows:                           |
|       | a. 防護設施與相關設備,如下:           | a. 防護設施與相關設備,如下:           | follows:                            | a. Containment facilities and related equipment  |
|       | 1. 防護級別為 P3、P4 之完全防護       | 1. 防護級別為 P3、P4 之完全防護       | a. Containment facilities and       | as follows:                                      |
|       | 設施(BL3, BL4, L3, L4) , 記載於 | 設施(BL3, BL4, L3, L4) , 記載於 | related equipment as follows:       | 1. Complete containment facilities that meet the |
|       | 世界衛生組織實驗室生物安全手             | 世界衛生組織實驗室生物安全手             | 1. Complete containment facilities  | criteria for P3 or P4 (BL3, BL4, L3, L4)         |
|       | 冊(第三版,日內瓦,2004年)。          | 冊(第三版,日內瓦,2004年)。          | that meet the criteria for P3 or P4 | containment as specified in the WHO Laboratory   |
|       | 2. 為在固定安裝於 2B352.a.管制      | 2. 為在固定安裝於 2B352.a.所述      | (BL3, BL4, L3, L4) containment as   | Biosafety Manual (3 rd edition Geneva, 2004);    |
|       | 之防護設施而設計的設備,如下:            | 防護設施而設計之設備,如下:             | specified in the WHO Laboratory     | 2. Equipment designed for fixed installation in  |
|       | a.雙門穿越式消毒高壓滅菌器;            | a.雙門穿越式消毒高壓滅菌器;            | Biosafety Manual (3 rd edition      | containment facilities specified in 2B352.a., as |
| 2B352 | b.呼吸空氣服裝消毒淋浴系統;            | b.呼吸空氣服裝消毒淋浴系統;            | Geneva, 2004);                      | follows:   |
| ZD00Z | c.機械式密封或充氣式密封門;            | c.機械式密封或充氣式密封門;            | 2. Equipment designed for fixed     | a. Double-door pass-through decontamination      |
|       | b. 發酵器及零件,如下:              | b. 發酵器及零件,如下:              | installation in containment         | autoclaves;                                      |
|       | 1. 發酵器能夠培養"微生物",           | 1. 發酵器能夠培養"微生物",           | facilities controlled in 2B352.a.,  | b. Breathing air suit decontamination showers;   |
|       | 或活細胞用於生產病毒或毒素,其            | 或活細胞用於生產病毒或毒素,其            | as follows:                         | c. Mechanical-seal or inflatable-seal            |
|       | 不需藉由噴霧劑之傳播,且其總容            | 不需藉由噴霧劑之傳播,且其內部            | a. Double-door pass-through         | walkthrough doors;                               |
|       | 量為20公升或以上;                 | 總容量為20公升或以上;               | decontamination autoclaves;         | b. Fermenters and components as follows:         |
|       | 2. 設計用於 2B352.b.1.之發酵器     | 2. 設計用於 2B352.b.1.所述之發     | b. Breathing air suit               | 1. Fermenters capable of cultivation of          |
|       | 零件,如下:                     | 酵器零件,如下:                   | decontamination showers;            | "microorganisms" or of live cells for the        |
|       |                            |                            | c. Mechanical-seal or               | production of viruses or toxins, without the     |
|       |                            |                            | inflatable-seal walkthrough         | propagation of aerosols, having a total internal |
|       |                            |                            | doors;                              | volume of 20 litres or more;                     |

| 修正條目     | 現行內容               | 擬修正/新增內容          | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|----------|--------------------|-------------------|-------------------------------------|--|
|          |                    |                   | b. Fermenters and components as     | 2. Components designed for fermenters specified  |
|          |                    |                   | follows:                            | in 2B352.b.1. as follows:                        |
|          |                    |                   | 1. Fermenters capable of            |  |
|          |                    |                   | cultivation of "microorganisms" or  |  |
|          |                    |                   | of live cells for the production of |  |
|          |                    |                   | viruses or toxins, without the      |  |
|          |                    |                   | propagation of aerosols, having a   |  |
|          |                    |                   | total capacity of 20 litres or      |  |
|          |                    |                   | more;                               |  |
|          |                    |                   | 2. Components designed for          |  |
|          |                    |                   | fermenters in 2B352.b.1. as         |  |
|          |                    |                   | follows:                            |  |
|          | 無                  | i.核酸組合與合成裝置,部分或全  | _                                   | i. Nucleic acid assemblers and synthesisers,     |
|          |                    | 自動,設計用於產生長度超過1.5  |                                     | which are partly or entirely automated, and      |
| 2B352. i |                    | 千鹼基對(kbp)的連續性核酸,其 |                                     | designed to generate continuous nucleic acids    |
|          |                    | 單次運行的錯誤率低於 5%。    |                                     | greater than 1,5 kilobases in length with error  |
|          |                    |                   |                                     | rates less than 5 % in a single run.             |
|          | 2E003 其他"技術",如下:   | 2E003 其他"技術",如下:  | 2E003 Other "technology", as        | 2E003 Other "technology", as follows:            |
|          | a. "開發"互動式繪圖之"技術", | a. 刪除;            | follows:                            | a. Not used;                                     |
|          | 以製作或修改其零件加工程式,作    | b. 金屬加工製造程序 "技術", | a. "Technology" for the             | b. "Technology" for metal-working manufacturing  |
| 2E003    | 為"數值控制"單元之整合部分。    | 如下:               | "development" of interactive        | processes, as follows:                           |
|          | b. 金屬加工製造程序"技術",   | 1. 用以設計專為下列任一程序而  | graphics as an integrated part in   | 1. "Technology" for the design of tools, dies or |
|          | 如下:                | 特別設計之工具、模具或夾具之    | "numerical control" units for       | fixtures specially designed for any of the       |
|          | 1. 用以設計專為下列任一程序而   | "技術":             | preparation or modification of      | following processes:                             |

| 修正條目 | 現行內容              | 擬修正/新增內容          | 現行內容英譯                            | 擬修正/新增內容英譯                                      |
|------|-------------------|-------------------|-----------------------------------|---|
|      | 特別設計之工具、模具或夾具之    | a. "超塑性成形";       | part programs;                    | a. "Superplastic forming";                      |
|      | "技術":             | b. "擴散結合";或       | b. "Technology" for metal-working | b. "Diffusion bonding"; or                      |
|      | a. "超塑性成形";       | c. `直接作用液壓成形´;    | manufacturing processes, as       | c. 'Direct-acting hydraulic pressing';          |
|      | b. "擴散結合";或       | 2. 包含於下列程序方法或參數,  | follows:                          | 2. Technical data consisting of process methods |
|      | c. "直接作用液壓成形";    | 且用於控制之技術資料:       | 1. "Technology" for the design of | or parameters as listed below used to control:  |
|      | 2. 包含於下列程序方法或參數,  | a. 鋁合金、鈦合金或 "超合金" | tools, dies or fixtures specially | a. "Superplastic forming" of aluminium alloys,  |
|      | 且用於控制之技術資料:       | 之 "超塑性成形":        | designed for any of the following | titanium alloys or "superalloys":               |
|      | a. 鋁合金、鈦合金或 "超合金" | 1. 表面預處理;         | processes:                        | 1. Surface preparation;                         |
|      | 之"超塑性成形":         | 2. 應變率;           | a. "Superplastic forming";        | 2. Strain rate;                                 |
|      | 1. 表面預處理;         | 3. 温度;            | b. "Diffusion bonding"; or        | 3. Temperature;                                 |
|      | 2. 應變率;           | 4. 壓力;            | c. "Direct-acting hydraulic       | 4. Pressure;                                    |
|      | 3. 温度;            | b. "超合金"或鈦合金之"擴散  | pressing";                        | b. "Diffusion bonding" of "superalloys" or      |
|      | 4. 壓力;            | 結合":              | 2. Technical data consisting of   | titanium alloys:                                |
|      | b. "超合金"或鈦合金之"擴散  | 1. 表面預處理;         | process methods or parameters as  | 1. Surface preparation;                         |
|      | 結合":              | 2. 温度;            | listed below used to control:     | 2. Temperature;                                 |
|      | 1. 表面預處理;         | 3. 壓力;            | a. "Superplastic forming" of      | 3. Pressure;                                    |
|      | 2. 温度;            | c. 鋁合金或鈦合金之`直接作用  | aluminium alloys, titanium alloys | c. 'Direct-acting hydraulic pressing'of         |
|      | 3. 壓力;            | 液壓成形 二            | or "superalloys":                 | aluminium alloys or titanium alloys:            |
|      | c. 鋁合金或鈦合金之 "直接作用 | 1. 壓力;            | 1. Surface preparation;           | 1. Pressure;                                    |
|      | 液壓成形":            | 2. 循環時間;          | 2. Strain rate;                   | 2. Cycle time;                                  |
|      | 1. 壓力;            | d. 鈦合金、鋁合金或 "超合金" | 3. Temperature;                   | d. 'Hot isostatic densification' of titanium    |
|      | 2. 循環時間;          | 之`熱均壓緻密化´:        | 4. Pressure;                      | alloys, aluminium alloys or "superalloys":      |
|      | d. 鈦合金、鋁合金或 "超合金" | 1. 溫度;            | b. "Diffusion bonding" of         | 1. Temperature;                                 |
|      | 之"熱均壓緻密化":        | 2. 壓力;            | "superalloys" or titanium alloys: | 2. Pressure;                                    |

| 修正條目 | 現行內容              | 擬修正/新增內容              | 現行內容英譯                              | 擬修正/新增內容英譯  |
|------|-------------------|-----------------------|-------------------------------------|---|
|      | 1. 温度;            | 3. 循環時間;              | 1. Surface preparation;             | 3. Cycle time;                                    |
|      | 2. 壓力;            | 技術註解:                 | 2. Temperature;                     | Technical Notes:                                  |
|      | 3. 循環時間;          | 1. 直接作用液壓成形 6指一       | 3. Pressure;                        | 1. 'Direct-acting hydraulic pressing' is a        |
|      | c. 為製造機身結構而 "開發"或 | 種變形過程,使用充滿液體之彈性       | c. "Direct-acting hydraulic         | deformation process which uses a fluid-filled     |
|      | "生產"之液壓伸展成型機及模具   | 囊袋直接與工作物件接觸。          | pressing" of aluminium alloys or    | flexible bladder in direct contact with the       |
|      | 之"技術";            | 2. ` 熱均壓緻密化 ´ 係指在密閉   | titanium alloys:                    | workpiece.  |
|      | d. 用存於"數值控制"單元內之  | 腔室中以超過 375K(102 °C)加壓 | 1. Pressure;                        | 2. 'Hot isostatic densification' is a process of  |
|      | 設計資料,以"開發"工具機指令   | 鑄造之過程,利用不同介質(氣        | 2. Cycle time;                      | pressurising a casting at temperatures exceeding  |
|      | (如零件加工程式)產生器之"技   | 體、液體、固態粒子等)在各方向       | d. "Hot isostatic densification"    | 375 K (102 °C) in a closed cavity through various |
|      | 術";               | 產生相同力量,以減少或消除鑄造       | of titanium alloys, aluminium       | media (gas, liquid, solid particles, etc.) to     |
|      |                   | 物之內在空隙。               | alloys or "superalloys":            | create equal force in all directions to reduce    |
|      |                   | c. 為製造機身結構而"開發"或      | 1. Temperature;                     | or eliminate internal voids in the casting        |
|      |                   | "生產"之液壓伸展成型機及模具       | 2. Pressure;                        | c. "Technology" for the "development" or          |
|      |                   | 之"技術";                | 3. Cycle time;                      | "production" of hydraulic stretch-forming         |
|      |                   | d. 刪除;                | c. "Technology" for the             | machines and dies therefor, for the manufacture   |
|      |                   |                       | "development" or "production" of    | of airframe structures;                           |
|      |                   |                       | hydraulic stretch-forming           | d. Not used;                                      |
|      |                   |                       | machines and dies therefor, for the |   |
|      |                   |                       | manufacture of airframe             |   |
|      |                   |                       | structures;                         |   |
|      |                   |                       | d. "Technology" for the             |   |
|      |                   |                       | "development" of generators of      |   |
|      |                   |                       | machine tool instructions (e.g.,    |   |
|      |                   |                       | part programs) from design data     |   |

| 修正條目    | 現行內容                         | 擬修正/新增內容                     | 現行內容英譯                              | 擬修正/新增內容英譯   |
|---------|------------------------------|------------------------------|-------------------------------------|--|
|         |                              |                              | residing inside "numerical          |  |
|         |                              |                              | control" units;                     |  |
| 表-沉積技術  | 無                            | 類鑽碳(17)                      | -                                   | Diamond-like carbon (17)   |
| В3      |                              |                              |                                     |  |
|         | 註解1:3A001或3A002中除            | 註解1:3A001或3A002中除            | Note 1: The control status of       | Note 1: The control status of equipment and                          |
|         | 3A001.a.3.至 3A001.a.10.、     | 3A001.a.3.至 3A001.a.10.、     | equipment and components described  | components described in 3A001 or 3A002, other                        |
|         | 3A001.a.12.或 3A001.a.14.所述以  | 3A001.a.12.至 3A001.a.14.所述以  | in 3A001 or 3A002, other than those | than those described in 3A001.a.3. to                                |
|         | 外之設備與零件管制狀況,專為其              | 外之設備與零件管制狀況,專為其              | described in 3A001.a.3. to          | 3A001.a.10., or 3A001.a.12. to 3A001.a.14.,                          |
|         | 他設備所設計或具有與其他設備               | 他設備所設計或具有與其他設備               | 3A001.a.10., 3A001.a.12. or         | which are specially designed for or which have                       |
|         | 相同功能特徵者,由其他設備之管              | 相同功能特徵者,由其他設備之管              | 3A001.a.14, which are specially     | the same functional characteristics as other                         |
|         | 制狀況所決定。                      | 制狀況所決定。                      | designed for or which have the same | equipment is determined by the control status of $\ensuremath{I}$    |
|         | 註解 2:3A001.a.3.至 3A001.a.9.、 | 註解 2:3A001.a.3.至 3A001.a.9.  | functional characteristics as       | the other equipment.   |
|         | 3A001.a.12.或 3A001.a.14.所述為  | 或 3A001.a.12.至 3A001.a.14.所述 | other equipment is determined by    | Note 2: The control status of integrated circuits                    |
| 3A 註解   | 其他設備之特定功能所作不可變               | 為其他設備之特定功能所作不可               | the control status of the other     | described in 3A001.a.3. to 3A001.a.9., or                            |
| OU BTAT | 更之設定或設計之積體電路管制               | 變更之設定或設計之積體電路管               | equipment.                          | 3A001,a,12. to $3A001,a,14.$ which are unalterably                   |
|         | 狀況,由其他設備之管制狀況所決              | 制狀況,由其他設備之管制狀況所              | Note 2: The control status of       | programmed or designed for a specific function                       |
|         | 定。                           | 決定。                          | integrated circuits described in    | for another equipment is determined by the                           |
|         | 說明:當製造者或申請人不能決定              | 說明:當製造者或申請人不能決定              | 3A001.a.3. to 3A001.a.9.,           | control status of the other equipment.                               |
|         | 其他設備之管制狀況時,其積體電              | 其他設備之管制狀況時,其積體電              | 3A001.a.12. or 3A001.a.14 which     | $\ensuremath{\text{N.B.}}$ When the manufacturer or applicant cannot |
|         | 路的管制狀況由 3A001.a.3.至          | 路的管制狀況由 3A001.a.3.至          | are unalterably programmed or       | determine the control status of the other                            |
|         | 3A001.a.9.,3A001.a.12.及      | 3A001.a.9.,以及 3A001.a.12.至   | designed for a specific function    | equipment, the control status of the integrated                      |
|         | 3A001.a.14.所決定。              | 3A001.a.14.所決定。              | for another equipment is            | circuits is determined in 3A001.a.3. to                              |
|         |                              |                              | determined by the control status of | 3A001.a.9., and 3A001.a.12. to 3A001.a.14.                           |
|         |                              |                              | the other equipment.                |  |

| 修正條目        | 現行內容                     | 擬修正/新增內容                        | 現行內容英譯                             | 擬修正/新增內容英譯   |
|-------------|--------------------------|---------------------------------|------------------------------------|--|
|             |                          |                                 | N.B. When the manufacturer or      |  |
|             |                          |                                 | applicant cannot determine the     |  |
|             |                          |                                 | control status of the other        |  |
|             |                          |                                 | equipment, the control status of   |  |
|             |                          |                                 | the integrated circuits is         |  |
|             |                          |                                 | determined in 3A001.a.3. to        |  |
|             |                          |                                 | 3A001. a. 9., 3A001. a. 12 and     |  |
|             |                          |                                 | 3A001. a. 14.                      |  |
|             | 2. "微處理器微電路"、"微電腦        | 2. "微處理器微電路"、"微電腦               | 2. "Microprocessor                 | 2. "Microprocessor microcircuits",                 |
|             | 微電路"、微控制器微電路、由化          | 微電路"、微控制器微電路、由化                 | microcircuits", "microcomputer     | $"microcomputer\ microcircuits",\ microcontroller$ |
|             | 合物半導體所製造之儲存積體電           | 合物半導體所製造之儲存積體電                  | microcircuits", microcontroller    | microcircuits, storage integrated circuits         |
|             | 路、類比—數位轉換器、包含數位          | 路、類比-數位轉換器、包含數位                 | microcircuits, storage integrated  | manufactured from a compound semiconductor,        |
|             | -類比轉換器並可儲存與處理數           | <ul><li>類比轉換器並可儲存與處理數</li></ul> | circuits manufactured from a       | analogue-to-digital converters, integrated         |
|             | 位資料的積體電路、數位-類比轉          | 位資料的積體電路、數位一類比轉                 | compound semiconductor,            | circuits that contain analogue-to-digital          |
|             | 換器、為"訊號處理"所設計之光          | 换器、為"訊號處理"所設計之光                 | analogue-to-digital converters,    | converters and store or process the digitised      |
| 3A001. a. 2 | 電或 "光學積體電路"、現場可程         | 電或 "光學積體電路"、現場可程                | integrated circuits that contain   | data, digital-to-analogue converters,              |
| onoo1, a, 2 | 式邏輯元件、客戶訂製之積體電路          | 式邏輯元件、客戶訂製之積體電路                 | analogue-to-digital converters     | electro-optical or "optical integrated             |
|             | 之功能未知或使用該積體電路之           | 之功能未知或使用該積體電路之                  | and store or process the digitised | circuits" designed for "signal processing",        |
|             | 設備之控制狀況不明、快速傅立葉          | 設備之控制狀況不明、快速傅立葉                 | data, digital-to-analogue          | field programmable logic devices, custom           |
|             | 轉換(FFT)處理器、電抹除式可編        | 轉換(FFT)處理器或`非揮發性記               | converters, electro-optical or     | integrated circuits for which either the           |
|             | 程唯讀記憶體 (EEPROMs)、快閃      | 憶體´,具下列任一特性:                    | "optical integrated circuits"      | function is unknown or the control status of the   |
|             | 記憶體或靜態隨機存取記憶體            | a. 被評定為可於 398 K (125 °C)        | designed for "signal processing",  | equipment in which the integrated circuit will     |
|             | (SRAMs) ,具下列任一特性:        | 以上之環境溫度下操作;                     | field programmable logic devices,  | be used is unknown, Fast Fourier Transform (FFT)   |
|             | a. 被評定為可於 398 K (125 °C) | b. 被評定為可於 218 K (-55 °C)        | custom integrated circuits for     | processors, Static Random-Access Memories          |

| 修正條目 | 現行內容                     | 擬修正/新增內容                 | 現行內容英譯                             | 擬修正/新增內容英譯   |
|------|--------------------------|--------------------------|------------------------------------|--|
|      | 以上之環境溫度下操作;              | 以下之環境溫度下操作;或             | which either the function is       | (SRAMs), or 'non-volatile memories', having any                |
|      | b. 被評定為可於 218 K (-55 °C) | c. 評定為可於 218 K (-55 °C)至 | unknown or the control status of   | of the following:  |
|      | 以下之環境溫度下操作;或             | 398 K (125 °C)整個環境溫度範圍   | the equipment in which the         | a. Rated for operation at an ambient temperature               |
|      | c. 評定為可於 218 K (-55°C)至  | 內操作者;                    | integrated circuit will be used is | above 398 K (125 °C);  |
|      | 398 K (125 °C)整個環境溫度範圍   | 註解:3A.001.a.2.不管制民用汽車    | unknown, Fast Fourier Transform    | b. Rated for operation at an ambient temperature               |
|      | 內操作者;                    | 或火車應用之積體電路。              | (FFT) processors, Electrical       | below 218 K (- 55 °C); or                                      |
|      | 註解:3A.001.a.2.不管制民用汽車    | 技術註解:                    | Erasable Programmable Read-Only    | c. Rated for operation over the entire ambient                 |
|      | 或火車應用之積體電路。              | `非揮發性記憶體´為電源關閉           | Memories (EEPROMs), flash          | temperature range from 218 K ( - 55 $^{\circ}\text{C})$ to 398 |
|      |                          | 後儲存的資料在一陣時間內不會           | memories, Static Random-Access     | K (125 °C);  |
|      |                          | 消失者的記憶體。                 | Memories (SRAMs), or Magnetic      | Note: 3A001.a.2. does not control integrated                   |
|      |                          |                          | Random Access Memories (MRAMs),    | circuits for civil automobiles or railway train                |
|      |                          |                          | having any of the following:       | applications.  |
|      |                          |                          | a. Rated for operation at an       | Technical Note:  |
|      |                          |                          | ambient temperature above 398 K    | 'Non-volatile memories' are memories with data                 |
|      |                          |                          | (125 °C);                          | retention over a period of time after a power                  |
|      |                          |                          | b. Rated for operation at an       | shutdown. EN 14.12.2018 Official Journal of the                |
|      |                          |                          | ambient temperature below 218 K    | European Union L 319/105                                       |
|      |                          |                          | (-55 °C); or                       |  |
|      |                          |                          | c. Rated for operation over the    |  |
|      |                          |                          | entire ambient temperature range   |  |
|      |                          |                          | from 218 K (-55 °C) to 398 K (125  |  |
|      |                          |                          | °C);                               |  |
|      |                          |                          | Note: 3A001.a.2. does not control  |  |
|      |                          |                          | integrated circuits for civil      |  |

| 修正條目        | 現行內容                | 擬修正/新增內容             | 現行內容英譯                               | 擬修正/新增內容英譯   |
|-------------|---------------------|----------------------|--------------------------------------|--|
|             |                     |                      | automobiles or railway train         |  |
|             |                     |                      | applications.                        |  |
|             | 5. 類比一數位轉換器(ADC)及數  | 5. 類比一數位轉換器(ADC)及數   | 5. Analogue-to-Digital Converter     | 5. Analogue-to-Digital Converter (ADC) and         |
|             | 位-類比轉換器(DAC)積體電     | 位-類比轉換器(DAC)積體電      | (ADC) and Digital-to-Analogue        | Digital-to-Analogue Converter (DAC) integrated     |
|             | 路,如下:               | 路,如下:                | Converter (DAC) integrated           | circuits, as follows:                              |
|             | a. 具下列任一特性之類比—數位    | a. 具下列任一特性之類比—數位     | circuits, as follows:                | a. ADCs having any of the following:               |
|             | 轉換器:                | 轉換器:                 | a. ADCs having any of the            | N. B. SEE ALSO 3A101                               |
|             | 說明:參照 3A101。        | 說明:參照 3A101。         | following:                           | 1. A resolution of 8 bit or more, but less than    |
|             | 1. 解析度為8位元或以上,但小    | 1. 解析度為8位元或以上,但小     | N. B. SEE ALSO 3A101                 | 10 bit, with a "sample rate" greater than 1,3 Giga |
|             | 於10位元,輸出率大於每秒1.3    | 於10位元,"取樣率"大於每秒      | 1. A resolution of 8 bit or more,    | Samples Per Second (GSPS);                         |
|             | 十億次取樣(GSPS);        | 1.3 十億次取樣(GSPS);     | but less than 10 bit, with an output | 2. A resolution of 10 bit or more, but less than   |
|             | 2. 解析度為 10 位元或以上,但小 | 2. 解析度為 10 位元或以上,但小  | rate greater than 1.3 giga samples   | 12 bit, with a "sample rate" greater than 600 Mega |
| 3A001. a. 5 | 於12位元,輸出率大於每秒600    | 於12位元,"取樣率"大於每秒      | per second (GSPS);                   | Samples Per Second (MSPS);                         |
| JA001. a. J | 百萬次取樣(MSPS);        | 600 百萬次取樣(MSPS);     | 2. A resolution of 10 bit or more,   | 3. A resolution of 12 bit or more, but less than   |
|             | 3. 解析度為 12 位元或以上,但小 | 3. 解析度為 12 位元或以上,但小  | but less than 12 bit, with an output | 14 bit, with a "sample rate" greater than 400      |
|             | 於 14 位元,輸出率大於每秒 400 | 於14位元,"取樣率"大於每秒      | rate greater than 600 mega samples   | MSPS;  |
|             | 百萬次取樣(MSPS);        | 400 百萬次取樣(MSPS);     | per second (MSPS);                   | 4. A resolution of 14 bit or more, but less than   |
|             | 4. 解析度為 14 位元或以上,但小 | 4. 解析度為 14 位元或以上,但小  | 3. A resolution of 12 bit or more,   | 16 bit, with a "sample rate" greater than 250      |
|             | 於或等於 16 位元,輸出率大於每   | 於或等於16位元, "取樣率"大     | but less than 14 bit, with an output | MSPS; or   |
|             | 秒 250 百萬次取樣(MSPS);或 | 於每秒 250 百萬次取樣(MSPS); | rate greater than 400 mega samples   | 5. A resolution of 16 bit or more with a "sample   |
|             | 5. 解析度為 16 位元或以上,輸出 | 或                    | per second (MSPS);                   | rate" greater than 65 MSPS;                        |
|             | 率大於每秒 65 百萬次取樣      | 5. 解析度為 16 位元或以上,"取  | 4. A resolution of 14 bit or more,   | N.B. For integrated circuits that contain          |
|             | (MSPS);             | 樣率"大於每秒65百萬次取樣       | but less than 16 bit, with an output | analogue-to-digital converters and store or        |
|             | 說明:包含數位-類比轉換器並可     | (MSPS);              | rate greater than 250 mega samples   | process the digitized data, see 3A001.a.14.        |

| 修正條目 | 現行內容                  | 擬修正/新增內容              | 現行內容英譯                              | 擬修正/新增內容英譯   |
|------|-----------------------|-----------------------|-------------------------------------|--|
|      | 儲存與處理數位資料的積體電         | 說明:包含數位-類比轉換器並可       | per second (MSPS); or               | Technical Notes:                                   |
|      | 路,參考 3A001.a.14.。     | 儲存與處理數位資料的積體電         | 5. A resolution of 16 bit or more   | 1. A resolution of n bit corresponds to a          |
|      | 技術註解:                 | 路,參考 3A001.a.14.。     | with an output rate greater than 65 | quantisation of 2 n levels.                        |
|      | 1.n 位元之解析度係對應於一個      | 技術註解:                 | mega samples per second (MSPS);     | 2. The resolution of the ADC is the number of bits |
|      | 量子化的 2n 種狀態。          | 1.n 位元之解析度係對應於一個      | N.B. For integrated circuits that   | of the digital output that represents the          |
|      | 3A001 (續)             | 量子化的 2n 種狀態。          | contain analogue-to-digital         | measured analogue input. Effective Number of       |
|      | 2. 輸出字的位元數相等於數位—      | 2. 輸出字的位元數相等於數位—      | converters and store or process the | Bits (ENOB) is not used to determine the           |
|      | 類比轉換器之解析度。            | 類比轉換器之解析度,有效位元數       | digitized data, see 3A001.a.14.     | resolution of the ADC.                             |
|      | 3. 輸出率即為轉換器的最大輸出      | (ENOB)不用於判讀 ADC 之解析   | Technical Notes:                    | 3. For "multiple channel ADCs", the "sample rate"  |
|      | 速率,不論其結構為何或是否超取       | 度。                    | 1. A resolution of n bit            | is not aggregated and the "sample rate" is the     |
|      | 樣。亦有廠商以取樣率、轉換率或       | 3. 對於`多頻道 ADCs´而言,    | corresponds to a quantisation of 2  | maximum rate of any single channel.                |
|      | 產出率稱之。其單位為百萬赫         | "取樣率"非為匯總結果,且"取       | n levels.                           | 4. For "interleaved ADCs" or for "multiple         |
|      | (MHz)或每秒百萬取樣(MSPS)。   | 樣率"是指任何單一頻道之最大輸       | 2. The number of bits in the output | channel ADCs" that are specified to have an        |
|      | 4. 對於 `多頻道 ADCs ´而言,輸 | 出率。                   | word is equal to the resolution of  | interleaved mode of operation, the "sample         |
|      | 出率非為加總,且輸出率是指任何       | 4. 對於`交錯式 ADCs´或`多    | the ADC.                            | rates" are aggregated and the "sample rate" is     |
|      | 單一頻道之最大輸出率。           | 頻道 ADCs´而言,"取樣率"為     | 3. The output rate is the maximum   | the maximum combined total rate of all of the      |
|      | 5. 對於`交錯式 ADCs´或`多    | 匯總結果,"取樣率"為所有交錯       | output rate of the converter,       | interleaved channels.                              |
|      | 頻道 ADCs ´而言,指運作時有一    | 頻道之最大輸出率組合。           | regardless of the architecture or   | b. Digital-to-Analogue Converters (DAC) having     |
|      | 交錯模式,其輸出將匯總,其輸出       | b. 具下列任一特性之數位—類比      | oversampling.                       | any of the following:                              |
|      | 率為結合全部輸出之最大組合。        | 轉換器:                  | 4. For 'multiple channel ADCs', the | 1. A resolution of 10 bit or more with an          |
|      | 6. 供應商可能標示輸出率為取樣      | 1. 解析度至少為 10 位元或以上,   | outputs are not aggregated and the  | 'adjusted update rate' of greater than 3 500       |
|      | 率、轉換率或生產率,其常以兆赫       | 且 ] 調整更新速率 / 大於 3,500 | output rate is the maximum output   | MSPS; or   |
|      | (MHz)或每秒百萬次取樣(MSPS)   | 每秒百萬次取樣(MSPS);或       | rate of any single channel.         | 2. A resolution of 12 bit or more with an          |
|      | 標示。                   | 2. 解析度至少為 12 位元或以上,   | 5. For 'interleaved ADCs' or for    | 'adjusted update rate' of greater than 1 250 MSPS  |

| 修正條目 | 現行內容                  | 擬修正/新增內容              | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|------|-----------------------|-----------------------|-------------------------------------|--|
|      | 7. 測量輸出率時,每秒一次取樣      | `調整更新速率´等於或大於         | 'multiple channel ADCs' that are    | and having any of the following:                 |
|      | 相當於1赫 (Hz)或每秒輸出1個     | 1,250 每秒百萬次取樣(MSPS),且 | specified to have an interleaved    | a. A settling time less than 9 ns to arrive at   |
|      | 字。                    | 具下列任一種特性:             | mode of operation, the outputs are  | or within 0,024% of full scale from a full scale |
|      | 8. `多頻道 ADCs `被定義為整   | a. 從全尺度大小到達全尺度大小      | aggregated and the output rate is   | step; or   |
|      | 合超過一個 ADC 的裝置,設計為     | 之 0.024 %或之內所需要的穩定時   | the maximum combined total output   |  |
|      | 每個 ADC 具有獨立之類比輸入。     | 間小於9ns;或              | rate of all of the outputs.         |  |
|      | 9. `交錯式 ADCs ´被定義為多   |                       | 6. Vendors may also refer to the    |  |
|      | 個 ADC 單元其對於同一個類比輸     |                       | output rate as sampling rate,       |  |
|      | 入在不同時間進行取樣,當輸出匯       |                       | conversion rate or throughput       |  |
|      | 總時,類比輸入已得到有效率的取       |                       | rate. It is often specified in      |  |
|      | 樣與轉換成一個更高的取樣率。        |                       | megahertz (MHz), mega words per     |  |
|      | b. 具下列任一特性之數位-類比      |                       | second or mega samples per second   |  |
|      | 轉換器:                  |                       | (MSPS).                             |  |
|      | 1. 解析度至少為 10 位元或以上,   |                       | 7. For the purpose of measuring     |  |
|      | 且、調整更新速率 / 大於 3,500   |                       | output rate, one sample per second  |  |
|      | 每秒百萬次取樣(MSPS);或       |                       | is equivalent to one Hertz or one   |  |
|      | 2. 解析度至少為 12 位元或以上,   |                       | output word per second.             |  |
|      | `調整更新速率´等於或大於         |                       | 8. 'Multiple channel ADCs' are      |  |
|      | 1,250 每秒百萬次取樣(MSPS),且 |                       | defined as devices which integrate  |  |
|      | 具下列任一種特性:             |                       | more than one ADC, designed so that |  |
|      | a. 從全尺度大小到全尺度大小之      |                       | each ADC has a separate analogue    |  |
|      | 0.024%所需要的穩定時間,小於     |                       | input.                              |  |
|      | 9 ns;或                |                       | 9. 'Interleaved ADCs' are defined   |  |
|      |                       |                       | as devices which have multiple ADC  |  |

| 修正條目       | 現行內容              | 擬修正/新增內容         | 現行內容英譯                              | 擬修正/新增內容英譯   |
|------------|-------------------|------------------|-------------------------------------|--|
|            |                   |                  | units that sample the same analogue |  |
|            |                   |                  | input at different times such that  |  |
|            |                   |                  | when the outputs are aggregated,    |  |
|            |                   |                  | the analogue input has been         |  |
|            |                   |                  | effectively sampled and converted   |  |
|            |                   |                  | at a higher sampling rate.          |  |
|            |                   |                  | b. Digital-to-Analogue Converters   |  |
|            |                   |                  | (DAC) having any of the following:  |  |
|            |                   |                  | 1. A resolution of 10 bit or more   |  |
|            |                   |                  | with an 'adjusted update rate' of   |  |
|            |                   |                  | greater than 3 500 MSPS; or         |  |
|            |                   |                  | 2. A resolution of 12 bit or more   |  |
|            |                   |                  | with an 'adjusted update rate' of   |  |
|            |                   |                  | greater than 1 250 MSPS and having  |  |
|            |                   |                  | any of the following:               |  |
|            |                   |                  | a. A settling time less than 9 ns   |  |
|            |                   |                  | to 0,024% of full scale from a full |  |
|            |                   |                  | scale step; or                      |  |
|            | 14. 積體電路執行下列所有特性: | 14. 積體電路執行或可程式化執 | 14. Integrated circuits that        | 14. Integrated circuits that perform or are        |
| 3A001.a.14 | a. 類比-數位轉換器具下列任一  | 行下列所有特性:         | perform all of the following:       | programmable to perform all of the following:      |
|            | 特性:               | a. 類比-數位轉換器具下列任一 | a. Analogue-to-digital              | a. Analogue-to-digital conversions meeting any     |
|            | 1. 解析度為8位元或以上,但小  | 特性:              | conversions meeting any of the      | of the following:                                  |
|            | 於 10 位元,取樣輸入率大於每秒 | 1. 解析度為8位元或以上,但小 | following:                          | 1. A resolution of 8 bit or more, but less than    |
|            | 1.3 十億次取樣(GSPS);  | 於10位元,"取樣率"大於每秒  | 1. A resolution of 8 bit or more,   | 10 bit, with a "sample rate" greater than 1,3 Giga |

| 修正條目 | 現行內容                  | 擬修正/新增內容            | 現行內容英譯                              | 擬修正/新增內容英譯   |
|------|-----------------------|---------------------|-------------------------------------|--|
|      | 2. 解析度為 10 位元或以上,但小   | 1.3 十億次取樣(GSPS);    | but less than 10 bit, with an input | Samples Per Second (GSPS);                         |
|      | 於12位元,取樣輸入率大於每秒       | 2. 解析度為 10 位元或以上,但小 | sample rate greater than 1,3 giga   | 2. A resolution of 10 bit or more, but less than   |
|      | 1.0 十億次取樣(GSPS);      | 於12位元,"取樣率"大於每秒     | samples per second (GSPS);          | 12 bit, with a "sample rate" greater than 1,0      |
|      | 3. 解析度為 12 位元或以上,但小   | 1.0 十億次取樣(GSPS);    | 2. A resolution of 10 bit or more,  | GSPS;  |
|      | 於14位元,取樣輸入率大於每秒       | 3. 解析度為 12 位元或以上,但小 | but less than 12 bit, with an input | 3. A resolution of 12 bit or more, but less than   |
|      | 1.0 十億次取樣(GSPS);      | 於14位元,"取樣率"大於每秒     | sample rate greater than 1,0 giga   | 14 bit, with a "sample rate" greater than 1,0      |
|      | 4. 解析度為 14 位元或以上,但小   | 1.0 十億次取樣(GSPS);    | samples per second (GSPS);          | GSPS;  |
|      | 於16位元,取樣輸入率大於每秒       | 4. 解析度為 14 位元或以上,但小 | 3. A resolution of 12 bit or more,  | 4. A resolution of 14 bit or more, but less than   |
|      | 400 百萬次取樣(MSPS);或     | 於16位元, "取樣率" 大於每秒   | but less than 14 bit, with an input | 16 bit, with a "sample rate" greater than 400 Mega |
|      | 5. 解析度為 16 位元或以上,取樣   | 400 百萬次取樣(MSPS);或   | sample rate greater than 1,0 giga   | Samples Per Second (MSPS); or                      |
|      | 輸入率大於每秒 180 百萬次取樣     | 5. 解析度為 16 位元或以上,"取 | samples per second (GSPS);          | 5. A resolution of 16 bit or more with a "sample   |
|      | (MSPS);及              | 樣率"大於每秒180百萬次取樣     | 4. A resolution of 14 bit or more,  | rate" greater than 180 MSPS; and                   |
|      | b.具下列任一特性者:           | (MSPS);及            | but less than 16 bit, with an input | b. Any of the following:                           |
|      | 1. 儲存數位化資料;或          | b.具下列任一特性者:         | sample rate greater than 400 mega   | 1. Storage of digitised data; or                   |
|      | 2. 處理數位化資料;           | 1. 儲存數位化資料;或        | samples per second (MSPS); or       | 2. Processing of digitised data;                   |
|      | 說明1:類比-數位轉換器積體電       | 2. 處理數位化資料;         | 5. A resolution of 16 bit or more   | N.B.1. For analogue-to-digital converter           |
|      | 路,參考 3A001.a.5.a.。    | 說明1:類比-數位轉換器積體電     | with an input sample rate greater   | integrated circuits see 3A001.a.5.a.               |
|      | 說明2:現場可程式邏輯元件,參       | 路,參考 3A001.a.5.a.。  | than 180 mega samples per second    | N.B.2. For field programmable logic devices see    |
|      | 考 3A001.a.7.。         | 說明2:現場可程式邏輯元件,參     | (MSPS); and                         | 3A001. a. 7.                                       |
|      | b. 微波或毫米波項目,如下:       | 考 3A001.a.7.。       | b. Any of the following:            | Technicals Notes:                                  |
|      | 技術註解:                 | 技術註解:               | 1. Storage of digitised data; or    | 1. A resolution of n bit corresponds to a          |
|      | 1. 就 3A001.b.目的,飽和參數峰 | 1.n 位元之解析度係對應於一個    | 2. Processing of digitised data;    | quantisation of 2 n levels.                        |
|      | 值輸出功率亦可以為產品數據表        | 量子化的 2n 種狀態。        | N.B.1. For analogue-to-digital      | 2. The resolution of the ADC is the number of bits |
|      | 中所提及之輸出功率、飽和輸出功       | 2. 輸出字的位元數相等於數位—    | converter integrated circuits see   | of the digital output of the ADC that represents   |

| 修正條目 | 現行內容                     | 擬修正/新增內容             | 現行內容英譯                             | 擬修正/新增內容英譯  |
|------|--------------------------|----------------------|------------------------------------|---|
|      | 率、最大輸出功率、峰值輸出功           | 類比轉換器之解析度,有效位元數      | 3A001. a. 5. a.                    | the measured analogue input. Effective Number of  |
|      | 率,或包絡線峰值輸出功率。            | (ENOB)不用於判讀 ADC 之解析  | N.B.2. For field programmable      | Bits (ENOB) is not used to determine the          |
|      | 2. 就 3A001.b.1 目的, `真空電子 | 度。                   | logic devices see 3A001.a.7.       | resolution of the ADC.                            |
|      | 元件~為基於電子束與電磁波在           | 3. 對於積體電路具非交錯式 "多    | b. Microwave or millimetre wave    | 3. For integrated circuits with non-interleaving  |
|      | 真空電路中傳遞的相互作用,或與          | 頻道 ADCs" 而言, "取樣率" 非 | items as follows:                  | "multiple channel ADCs", the "sample rate" is not |
|      | 無線電頻率真空空腔共振器的相           | 匯總結果,且"取樣率"是指任何      | Technical Notes:                   | aggregated and the "sample rate" is the maximum   |
|      | 互作用。`真空電子設備´包括調          | 單一頻道之最大輸出率。          | 1. For purposes of 3A001.b., the   | rate of any single channel.                       |
|      | 速管、行波管及其衍生物。             | 4. 對於積體電路具 "交錯式      | parameter peak saturated power     | 4. For integrated circuits with "interleaved      |
|      |                          | ADCs″或"多頻道 ADCs″其操   | output may also be referred to on  | ADCs "or with "multiple channel ADCs" that are    |
|      |                          | 作具有交錯模式者,"取樣率"為      | product data sheets as output      | specified to have an interleaved mode of          |
|      |                          | 匯總結果,"取樣率"為所有交錯      | power, saturated power output,     | operation, the "sample rates" are aggregated and  |
|      |                          | 頻道之最大輸出率組合。          | maximum power output, peak power   | the "sample rate" is the maximum combined total   |
|      |                          |                      | output, or peak envelope power     | rate of all of the interleaved channels.          |
|      |                          |                      | output.                            |   |
|      |                          |                      | 2. For purposes of 3A001.b.1.,     |   |
|      |                          |                      | 'vacuum electronic devices' are    |   |
|      |                          |                      | electronic devices based on the    |   |
|      |                          |                      | interaction of an electron beam    |   |
|      |                          |                      | with an electromagnetic wave       |   |
|      |                          |                      | propagating in a vacuum circuit or |   |
|      |                          |                      | interacting with radio- frequency  |   |
|      |                          |                      | vacuum cavity resonators. 'Vacuum  |   |
|      |                          |                      | electronic devices' include        |   |
|      |                          |                      | klystrons, travelling-wave tubes,  |   |

| 修正條目        | 現行內容                      | 擬修正/新增內容                | 現行內容英譯                                | 擬修正/新增內容英譯                                       |
|-------------|---------------------------|-------------------------|---------------------------------------|--|
|             |                           |                         | and their derivatives.                |  |
|             | 註解2:額定操作頻率範圍橫跨一           | 註解2:額定操作頻率範圍橫跨一         | Note 2: The control status of the     | Note 2: The control status of the "MMIC" whose   |
|             | 個以上 3A001.b.2.a.至         | 個以上 3A001.b.2.a.至       | MMIC whose rated operating            | rated operating frequency includes frequencies   |
|             | 3A001.b.2.h.所定義頻率範圍之單     | 3A001.b.2.h.所定義頻率範圍之單   | frequency includes frequencies        | listed in more than one frequency range, as      |
|             | 晶微波積體電路(MMIC),其管制         | 晶微波積體電路("MMIC"),其       | listed in more than one frequency     | defined by 3A001.b.2.a. to 3A001.b.2.h., is      |
|             | 狀況是根據其最低飽和峰值輸出            | 管制狀況是根據其最低飽和峰值          | range, as defined by 3A001.b.2.a.     | determined by the lowest peak saturated power    |
|             | 功率之管制標準所決定。               | 輸出功率之管制標準所決定。           | to 3A001.b.2.h., is determined by     | output threshold.                                |
| 3A001. b. 2 | 註解3:根據第3類A部分之註解           | 註解3:根據第3類A部分之註解         | the lowest peak saturated power       | Note 3: Notes 1 and 2 in 3A mean that 3A001.b.2. |
| 註解          | 1 與註解 2,指 3A001.b.2.不管制   | 1 與註解 2,指 3A001.b.2.不管制 | output threshold.                     | does not control "MMICs" if they are specially   |
|             | 專為其它用途(如電信、雷達、汽           | 專為其它用途(如電信、雷達、汽         | Note 3: Notes 1 and 2 in 3A mean that | designed for other applications, e.g.,           |
|             | 車)所設計之微波單晶積體電路。           | 車)所設計之微波單晶積體電路          | 3A001.b.2. does not control MMICs     | telecommunications, radar, automobiles.          |
|             |                           | ( "MMIC" ) °            | if they are specially designed for    |  |
|             |                           |                         | other applications, e.g.,             |  |
|             |                           |                         | telecommunications, radar,            |  |
|             |                           |                         | automobiles.                          |  |
|             | 說明1:單晶微波積體電路              | 說明1:單晶微波積體電路            | N.B.1. MMIC amplifiers see            | N.B.1. For "MMIC" amplifiers see 3A001.b.2.      |
|             | (MMIC)放大器, 參考 3A001.b.2.。 | ( "MMIC" )放大器,参考        | 3A001. b. 2.                          | N.B.2. For 'transmit/receive modules' and        |
|             | 說明2: `傳輸/接收模組´與`傳         | 3A001.b.2. °            | N.B.2. For 'transmit/receive          | 'transmit modules' see 3A001.b.12.               |
| 3A001. b. 4 | 輸模組´,參考 3A001.b.12.。      | 說明2: `傳輸/接收模組´與`傳       | modules' and 'transmit modules'       | N.B.3. For converters and harmonic mixers,       |
| i 注解        |                           | 輸模組´,參考 3A001.b.12.。    | see 3A001. b. 12.                     | designed to extend the operating or frequency    |
| 红件          |                           | 說明3:用於轉換器與諧波混合          |                                       | range of signal analysers, signal generators,    |
|             |                           | 器,設計用於延伸訊號分析儀、訊         |                                       | network analysers or microwave test receivers,   |
|             |                           | 號產生器、延伸網路分析儀、微波         |                                       | see 3A001. b. 7.                                 |
|             |                           | 測試接收器等之操作或頻率範           |                                       |  |

| 修正條目       | 現行內容                         | 擬修正/新增內容                | 現行內容英譯                              | 擬修正/新增內容英譯  |
|------------|------------------------------|-------------------------|-------------------------------------|---|
|            |                              | 圍,參考 3A001.b.7.。        |                                     |   |
|            | 11. "頻率合成器" "電子組裝"           | 11. `頻率合成器´ "電子組裝"      | 11. "Frequency synthesiser"         | 11. 'Frequency synthesiser' "electronic                     |
|            | 其具"頻率切換時間"如下任一所              | 其具"頻率切換時間"如下任一所         | "electronic assemblies" having a    | assemblies" having a "frequency switching time"             |
|            | 述:                           | 述:                      | "frequency switching time" as       | as specified by any of the following:                       |
|            | a. 低於 143 ps;                | a.低於 143 ps;            | specified by any of the following:  | a. Less than 143 ps;  |
|            | b. 任何頻率變動超過 2.2 GHz, 合       | b.任何頻率變動超過 2.2 GHz,合    | a. Less than 143 ps;                | b. Less than 100 $\mu  \mathrm{s}$ for any frequency change |
|            | 成頻率範圍超過 4.8 GHz 但未超          | 成頻率範圍超過 4.8 GHz 但未超     | b. Less than 100 $\mu$ s for any    | exceeding 2,2 GHz within the synthesised                    |
|            | 過 31.8 GHz 時,低於 100 μs;      | 過 31.8 GHz 時,低於 100 μs; | frequency change exceeding 2, 2 GHz | frequency range exceeding 4,8 GHz but not                   |
|            | c. 刪除;                       | c.刪除;                   | within the synthesised frequency    | exceeding 31,8 GHz;   |
|            | d. 任何頻率變動超過 550 MHz,         | d.任何頻率變動超過 550 MHz, 合   | range exceeding 4,8 GHz but not     | c. Not used;  |
|            | 合成頻率範圍超過 31.8 GHz 但未         | 成頻率範圍超過 31.8 GHz 但未超    | exceeding 31,8 GHz;                 | d. Less than 500 $\mu$ s for any frequency change           |
|            | 超過 43.5 GHz 時,低於 500 μs;     | 過 43.5 GHz 時,低於 500 μs; | c. Not used;                        | exceeding 550 MHz within the synthesised                    |
| 3A001.b.11 | e. 任何頻率變動超過 2.2 GHz, 合       | e.任何頻率變動超過 2.2 GHz, 合   | d. Less than 500 $\mu$ s for any    | frequency range exceeding 31,8 GHz but not                  |
|            | 成頻率範圍超過37 GHz 但未超過           | 成頻率範圍超過37 GHz 但未超過      | frequency change exceeding 550 MHz  | exceeding 37 GHz;   |
|            | 90 GHz 時,低於 100 μs;          | 90 GHz 時,低於 100 μs;     | within the synthesised frequency    | e. Less than 100 $\mu$ s for any frequency change           |
|            | f. 刪除;或                      | f. 刪除;或                 | range exceeding 31,8 GHz but not    | exceeding 2,2 GHz within the synthesised                    |
|            | g. 合成頻率範圍超過 90 GHz           | g. 合成頻率範圍超過 90 GHz      | exceeding 37 GHz;                   | frequency range exceeding 37 GHz but not                    |
|            | 時,低於1ms;                     | 時,低於1ms;                | e. Less than 100 $\mu$ s for any    | exceeding 90 GHz; or  |
|            | 說明:關於一般用途之"訊號分析              | 技術註解:                   | frequency change exceeding 2, 2 GHz | f. Not used;  |
|            | 儀"、訊號產生器、網路分析儀和              | "頻率合成器"係指任何種類頻率         | within the synthesised frequency    | g. Less than 1 ms within the synthesized                    |
|            | 微波測試接收器之定義,分別參見              | 來源不論實際使用之技術,能由多         | range exceeding 37 GHz but not      | frequency range exceeding 90 GHz;                           |
|            | 3A002.c.、3A002.d.、 3A002.e.和 | 個輸出提供多個同步或交替之輸          | exceeding 90 GHz;                   | Technical Note:   |
|            | 3A002.f. °                   | 出頻率,而該等頻率由較少數之標         | f. Not used; or                     | A'frequency synthesiser' is any kind of                     |
|            |                              | 準(或主要)頻率所控制、產生或規        | g. Less than 1 ms within the        | frequency source, regardless of the actual                  |

| 修正條目        | 現行內容                    | 擬修正/新增內容                 | 現行內容英譯                             | 擬修正/新增內容英譯  |
|-------------|-------------------------|--------------------------|------------------------------------|---|
|             |                         | 範。                       | synthesized frequency range        | technique used, providing a multiplicity of       |
|             |                         |                          | exceeding 90 GHz;                  | simultaneous or alternative output frequencies,   |
|             |                         |                          |                                    | from one or more outputs, controlled by, derived  |
|             |                         |                          |                                    | from or disciplined by a lesser number of         |
|             |                         |                          |                                    | standard (or master) frequencies.                 |
|             | e. 如下之高能量元件:            | e. 如下之高能量元件:             | e. High energy devices as follows: | e. High energy devices as follows:                |
|             | 1. 如下之`電池芯´;            | 1. `電池芯´,如下:             | 1. 'Cells' as follows:             | 1. 'Cells' as follows:                            |
|             | a. 在20°C下`能量密度´超過       | a. `一次電池芯´在20℃時具下        | a. 'Primary cells' having an       | a. 'Primary cells' having any of the following    |
|             | 550 Wh/kg 之 ` 一次電池芯 ´ ; | 列任一特性;                   | 'energy density' exceeding 550     | at 20 °C;   |
| 3A001. e. 1 | b. 在20°C下`能量密度´超過       | 1. `能量密度 ´超過 550 Wh/kg 及 | Wh/kg at 20 °C;                    | 1. 'Energy density' exceeding 550 Wh/kg and a     |
| 5A001. e. 1 | 350 Wh/kg 之 ` 二次電池芯 ´。  | `連續功率密度´超過50             | b. 'Secondary cells' having an     | 'continuous power density' exceeding 50 W/kg; or  |
|             |                         | W/kg;或                   | 'energy density' exceeding 350     | 2. 'Energy density' exceeding 50 Wh/kg and a      |
|             |                         | 2. `能量密度 ´超過 50 Wh/kg 及  | Wh/kg at 20 °C;                    | 'continuous power density' exceeding 350 W/kg;    |
|             |                         | `連續功率密度´超過350            |                                    | or  |
|             |                         | W/kg;或                   |                                    |   |
|             | 無                       | 5. 3A001.e.1.a.所述之`連續功率  | -                                  | 5. For the purpose of 3A001.e.1.a., 'continuous   |
|             |                         | 密度´(W/kg),其計算方式是以額       |                                    | power density' (W/kg) is calculated from the      |
| 3A001. e. 1 |                         | 定電壓(伏特)乘以指定之最大連          |                                    | nominal voltage multiplied by the specified       |
|             |                         | 續放電電流(安培)除以重量(公          |                                    | maximum continuous discharge current in ampere    |
| 技術註解        |                         | 斤)。`連續功率密度´也稱為比          |                                    | (A) divided by the mass in kilograms. 'Continuous |
|             |                         | 功率。                      |                                    | power density' is also referred to as specific    |
|             |                         |                          |                                    | power.  |
| 3A001. i    | 無                       | i. 強度,振幅或相位電光調變器,        | _                                  | i. Intensity, amplitude, or phase electro-optic   |
| JAUUI. I    |                         | 設計用於類比訊號,具下列任一特          |                                    | modulators, designed for analogue signals and     |

| 修正條目 | 現行內容 | 擬修正/新增內容              | 現行內容英譯 | 擬修正/新增內容英譯  |
|------|------|-----------------------|--------|---|
|      |      | 性者:                   |        | having any of the following:                        |
|      |      | 1. 最大操作頻率超過 10 GHz 但  |        | 1. A maximum operating frequency of more than 10    |
|      |      | 未超過20GHz,光學介入損失等      |        | GHz but less than 20 GHz, an optical insertion      |
|      |      | 於或小於3dB,且具下列任一特       |        | loss equal to or less than 3 dB and having any      |
|      |      | 性:                    |        | of the following:                                   |
|      |      | a. ` 半波電壓´(`Vπ´)在頻    |        | a. A 'half-wave voltage' ('V $\pi$ ') less than 2,7 |
|      |      | 率 1 GHz 或以下時測量小於 2.7  |        | V when measured at a frequency of 1 GHz or below;   |
|      |      | V;或                   |        | or  |
|      |      | b. ` 半波電壓´(`Vπ´)在頻    |        | b. A'V $\pi$ ' of less than 4 V when measured at a  |
|      |      | 率 1 GHz 或以上時測量小於 4 V; |        | frequency of more than 1 GHz; or                    |
|      |      | 或                     |        | 2. A maximum operating frequency equal to or        |
|      |      | 2. 最大操作頻率等於或超過 20     |        | greater than 20 GHz, an optical insertion loss      |
|      |      | GHz,光學介入損失等於或小於3      |        | equal to or less than 3 dB and having any of the    |
|      |      | dB,且具下列任一特性:          |        | following:  |
|      |      | a. ` 半波電壓 ´( ˙Vπ ´)在頻 |        | a. A'V $\pi$ ' less than 3,3 V when measured at a   |
|      |      | 率 1 GHz 或以下時測量小於 3.3  |        | frequency of 1 GHz or below; or                     |
|      |      | V;或                   |        | b. A'V $\pi$ ' less than 5 V when measured at a     |
|      |      | b. ` 半波電壓´(`Vπ´)在頻    |        | frequency of more than 1 GHz.                       |
|      |      | 率 1 GHz 或以上時測量小於 5 V。 |        | Note: 3A001.i. includes electro-optic               |
|      |      | 註解: 3A001.i.包括具有光學輸入  |        | modulators having optical input and output          |
|      |      | 及輸出連接器的電光調變器(例        |        | connectors (e.g., fibre-optic pigtails).            |
|      |      | 如:光纖引線)。              |        | Technical Note:                                     |
|      |      | 技術註解:                 |        | For the purposes of 3A001.i., a 'half-wave          |
|      |      | 3A001.i.所述之` 半波電壓´    |        | voltage' ('V $\pi$ ') is the applied voltage        |

| 修正條目    | 現行內容                    | 擬修正/新增內容               | 現行內容英譯                               | 擬修正/新增內容英譯  |
|---------|-------------------------|------------------------|--------------------------------------|---|
|         |                         | (`Vπ´),指光通過光調變器時       |                                      | necessary to make a phase change of 180 degrees   |
|         |                         | 光波長產生 180 度相位改變所需      |                                      | in the wavelength of light propagating through    |
|         |                         | 要施加的電壓。                |                                      | the optical modulator.                            |
|         | c. 如下之"訊號分析儀":          | c. 如下之"訊號分析儀":         | c. "Signal analysers" as follows:    | c. "Signal analysers" as follows:                 |
|         | 1. "訊號分析儀" 在任何地方超       | 1. "訊號分析儀" 在任何地方超      | 1. "Signal analysers" having a 3 dB  | 1. "Signal analysers" having a 3 dB resolution    |
|         | 過 10 MHz 且具有 3 dB 解析頻寬  | 過 40 MHz 且具有 3 dB 解析頻寬 | resolution bandwidth (RBW)           | bandwidth (RBW) exceeding 40 MHz anywhere within  |
|         | (RBW), 其頻率超過 31.8 GHz,  | (RBW), 其頻率超過 31.8 GHz, | exceeding 10 MHz anywhere within     | the frequency range exceeding 31,8 GHz but not    |
|         | 但不超過 37 GHz;            | 但不超過 37 GHz;           | the frequency range exceeding 31, 8  | exceeding 37 GHz;                                 |
|         | 2. "訊號分析儀"具有平均顯示        | 2. "訊號分析儀"具有平均顯示       | GHz but not exceeding 37 GHz;        | 2. "Signal analysers" having Displayed Average    |
|         | 雜訊位準(DNAL)在任何地方低於       | 雜訊位準(DNAL)在任何地方低於      | 2. "Signal analysers" having         | Noise Level (DANL) less (better) than -150 dBm/Hz |
|         | (優於)-150 dBm/Hz,其頻率超過   | (優於)-150 dBm/Hz,其頻率超過  | Displayed Average Noise Level        | anywhere within the frequency range exceeding     |
|         | 43.5 GHz 但不超過 90 GHz;   | 43.5 GHz 但不超過 90 GHz;  | (DANL) less (better) than -150       | 43,5 GHz but not exceeding 90 GHz;                |
|         | 3. "訊號分析儀"頻率超過90        | 3. "訊號分析儀"頻率超過90       | dBm/Hz anywhere within the           | 3. "Signal analysers" having a frequency          |
| 3A002.c | GHz ;                   | GHz;                   | frequency range exceeding 43, 5 GHz  | exceeding 90 GHz;                                 |
|         | 4. "訊號分析儀"具有下列所有        | 4. "訊號分析儀"具有下列所有       | but not exceeding 90 GHz;            | 4. "Signal analysers" having all of the           |
|         | 特性:                     | 特性:                    | 3. "Signal analysers" having a       | following:  |
|         | a. "即時頻寬" 超過 170 MHz; 及 | a. `即時頻寬 ´超過 170 MHz;  | frequency exceeding 90 GHz;          | a. 'Real-time bandwidth' exceeding 170 MHz; and   |
|         | b. 具下列任一特性:             | 及                      | 4. "Signal analysers" having all of  | b. Having any of the following:                   |
|         | 1. 具 100%的發現率,於間隙或訊     | b. 具下列任一特性:            | the following:                       | 1. 100 % probability of discovery with less than  |
|         | 號的開窗效應持續時間為15 µs        | 1. 具 100%的發現率,於間隙或訊    | a. "Real-time bandwidth" exceeding   | a 3 dB reduction from full amplitude due to gaps  |
|         | 或以下,全振幅降低小於3dB;         | 號的開窗效應持續時間為15 μs       | 170 MHz; and                         | or windowing effects of signals having a duration |
|         | 2. 具有"頻率遮罩觸發"功能,        | 或以下,全振幅降低小於3dB;        | b. Having any of the following;      | of 15 $\mu$ s or less; or                         |
|         | 其 100 %觸發(捕獲)訊號機率之持     | 2. 具有 海率遮罩觸發 功能,       | 1. 100 % probability of discovery    | 2. A' frequency mask trigger' function with 100   |
|         | 續時間為15 μs或以下;           | 其 100 %觸發(捕獲)訊號機率之持    | with less than a 3 dB reduction from | % probability of trigger (capture) for signals    |

| 修正條目 | 現行內容                       | 擬修正/新增內容                   | 現行內容英譯                                   | 擬修正/新增內容英譯  |
|------|----------------------------|----------------------------|--|---|
|      | 技術註解:                      | 續時間為15 μs或以下;              | full amplitude due to gaps or            | having a duration of 15 $\mu$ s or less;          |
|      | 1.3A002.c.4.b.1.中之發現率也被    | 技術註解:                      | windowing effects of signals             | Technical Notes:                                  |
|      | 稱為攔截率或捕獲率。                 | 1. `即時頻寬`指分析儀可持續           | having a duration of 15 $\mu$ s or less; | 1. 'Real-time bandwidth' is the widest frequency  |
|      | 2.就 3A002.c.4.b.1.目的,100%發 | 傳送時域數據轉換為頻域結果之             | or                                       | range for which the analyser can continuously     |
|      | 現率的持續時間,即指定量測不確            | 最大頻寬範圍,利用傅立葉或其他            | 2. A "frequency mask trigger"            | transform time-domain data entirely into          |
|      | 定度所需之最低訊號持續時間。             | 離散時間轉換,其處理每一個輸入            | function with 100 % probability of       | frequency-domain results, using a Fourier or      |
|      | 註解:3A002.c.4.不管制僅使用固       | 時間點,無因間隙或窗口效應,使            | trigger (capture) for signals            | other discrete time transform that processes      |
|      | 定比例頻寬濾波器(又稱倍頻或分            | 測量振幅低於實際訊號振幅超過             | having a duration of 15 $\mu$ s or less; | every incoming time point, without a reduction    |
|      | 倍頻濾波器)之"訊號分析儀"。            | 3dB ∘                      | Technical Notes:                         | of measured amplitude of more than 3 dB below the |
|      |                            | 2.3A002.c.4.b.1.中之發現率也被    | 1. Probability of discovery in           | actual signal amplitude caused by gaps or         |
|      |                            | 稱為攔截率或捕獲率。                 | 3A002.c.4.b.1. is also referred to       | windowing effects, while outputting or            |
|      |                            | 3.就 3A002.c.4.b.1.目的,100%發 | as probability of intercept or           | displaying the transformed data.                  |
|      |                            | 現率的持續時間,即指定量測不確            | probability of capture.                  | 2. Probability of discovery in 3A002.c.4.b.1. is  |
|      |                            | 定度所需之最低訊號持續時間。             | 2. For the purposes of                   | also referred to as probability of intercept or   |
|      |                            | 4. `頻率遮罩觸發´指訊號分            | 3A002.c.4.b.1., the duration for         | probability of capture.                           |
|      |                            | 析儀之一個機制,其觸發功能可選            | 100 % probability of discovery is        | 3. For the purposes of 3A002.c.4.b.1., the        |
|      |                            | 擇一個頻率範圍作為擷取頻寬的             | equivalent to the minimum signal         | duration for 100 % probability of discovery is    |
|      |                            | 一個子集,而可忽略其他可能在同            | duration necessary for the               | equivalent to the minimum signal duration         |
|      |                            | 一擷取頻寬內之信號。一個`頻率            | specified level measurement              | necessary for the specified level measurement     |
|      |                            | 遮罩觸發 可能有多於一個獨立             | uncertainty.                             | uncertainty.                                      |
|      |                            | 限制的設置。                     |  | 4. A 'frequency mask trigger' is a mechanism      |
|      |                            |                            |  | where the trigger function is able to select a    |
|      |                            |                            |  | frequency range to be triggered on as a subset    |
|      |                            |                            |  | of the acquisition bandwidth while ignoring       |

| 修正條目      | 現行內容                 | 擬修正/新增內容             | 現行內容英譯                              | 擬修正/新增內容英譯  |
|-----------|----------------------|----------------------|-------------------------------------|---|
|           |                      |                      |                                     | other signals that may also be present within the   |
|           |                      |                      |                                     | same acquisition bandwidth. A' frequency mask       |
|           |                      |                      |                                     | trigger' may contain more than one independent      |
|           |                      |                      |                                     | set of limits.                                      |
|           | h. "電子組裝"、模組或設備,     | h. "電子組裝"、模組或設備,     | h. "Electronic assemblies",         | h. "Electronic assemblies", modules, or             |
|           | 特別為執行下列所有特性者:        | 特別為執行下列所有特性者:        | modules, or equipment, specified    | equipment, specified to perform all of the          |
|           | 1. 類比-數位轉換符合下列任一     | 1. 類比—數位轉換符合下列任一     | to perform all of the following:    | following:  |
|           | 者:                   | 者:                   | 1. Analogue-to-digital              | 1. Analogue-to-digital conversions meeting any      |
|           | a. 解析度為 8 位元或以上,但小   | a. 解析度為 8 位元或以上,但小   | conversions meeting any of the      | of the following:                                   |
|           | 於10位元,輸入率大於每秒1,300   | 於10位元,"取樣率"大於每秒      | following:                          | a. A resolution of 8 bit or more, but less than     |
|           | 百萬字;                 | 1.3 十億次取樣(GSPS);     | a. A resolution of 8 bit or more,   | 10 bit, with a "sample rate" greater than 1, 3 Giga |
|           | b. 解析度為 10 位元或以上,但小  | b. 解析度為 10 位元或以上,但小  | but less than 10 bit, with an input | Samples Per Second (GSPS);                          |
|           | 於12位元,輸入率大於每秒1,000   | 於12位元,"取樣率"大於每秒      | sample rate greater than 1 300      | b. A resolution of 10 bit or more, but less than    |
| 3A002. h  | 百萬字;                 | 1.0 十億次取樣(GSPS);     | million samples per second;         | 12 bit, with a "sample rate" greater than 1,0       |
| JA002, II | c. 解析度為 12 位元或以上,但小  | c. 解析度為 12 位元或以上,但小  | b. A resolution of 10 bit or more,  | GSPS;   |
|           | 於14位元,輸入率大於每秒1,000   | 於14位元,"取樣率"大於每秒      | but less than 12 bit, with an input | c. A resolution of 12 bit or more, but less than    |
|           | 百萬字;                 | 1.0 十億次取樣(GSPS);     | sample rate greater than 1 000      | 14 bit, with a "sample rate" greater than 1,0       |
|           | d. 解析度大於 14 位元, 但小於或 | d. 解析度大於 14 位元,但小於或  | million samples per second;         | GSPS;   |
|           | 等於16位元,輸入率大於每秒400    | 等於 16 位元,"取樣率"大於每    | c. A resolution of 12 bit or more,  | d. A resolution of 14 bit or more but less than     |
|           | 百萬字;或                | 秒 400 百萬次取樣(MSPS);或  | but less than 14 bit, with an input | 16 bit, with a "sample rate" greater than 400 Mega  |
|           | e. 解析度大於 16 位元,輸入率大  | e. 解析度大於 16 位元,"取樣率" | sample rate greater than 1 000      | Samples Per Second (MSPS); or                       |
|           | 於每秒 180 百萬字;及        | 大於每秒 180 百萬次取樣       | million samples per second;         | e. A resolution of 16 bit or more with a "sample    |
|           |                      | (MSPS);及             | d. A resolution of 14 bit or more   | rate" greater than 180 MSPS; andEN                  |
|           |                      |                      | but less than 16 bit, with an input |   |

| 修正條目      | 現行內容            | 擬修正/新增內容            | 現行內容英譯                              | 擬修正/新增內容英譯   |
|-----------|-----------------|---------------------|-------------------------------------|--|
|           |                 |                     | sample rate greater than 400        |  |
|           |                 |                     | million samples per second; or      |  |
|           |                 |                     | e. A resolution of 16 bit or more   |  |
|           |                 |                     | with an input sample rate greater   |  |
|           |                 |                     | than 180 million samples per        |  |
|           |                 |                     | second; and                         |  |
|           | 技術註解:           | 技術註解:               | Technical Note:                     | Technical Notes:                                   |
|           | 多頻道"電子組裝"或模組之管制 | 1.n 位元之解析度係對應於一個    | For multiple-channel "electronic    | 1. A resolution of n bit corresponds to a          |
|           | 狀態由單一頻道最高性能決定。  | 量子化的 2n 種狀態。        | assemblies" or modules, control     | quantisation of 2 n levels.                        |
|           |                 | 2. 輸出字的位元數相等於數位—    | status is determined by the highest | 2. The resolution of the ADC is the number of bits |
|           |                 | 類比轉換器之解析度,有效位元數     | single-channel specified            | of the digital output of the ADC that represents   |
|           |                 | (ENOB)不用於判讀 ADC 之解析 | performance.                        | the measured analogue input. Effective Number of   |
|           |                 | 度。                  |                                     | Bits (ENOB) is not used to determine the           |
|           |                 | 3. 對於非交錯式多頻道 "電子組   |                                     | resolution of the ADC.                             |
| 3A002.h 技 |                 | 裝"、模組或設備而言,"取樣率"    |                                     | 3. For non-interleaved multiple-channel            |
| 術註解       |                 | 非匯總結果,且"取樣率"是指任     |                                     | "electronic assemblies", modules, or equipment,    |
|           |                 | 何單一頻道之最大輸出率。        |                                     | the "sample rate" is not aggregated and the        |
|           |                 | 4. 對於交錯式多頻道 "電子組    |                                     | "sample rate" is the maximum rate of any           |
|           |                 | 裝"、模組或設備而言,"取樣率"    |                                     | single-channel.                                    |
|           |                 | 為匯總結果,"取樣率"為所有交     |                                     | 4. For interleaved channels on multiple-channel    |
|           |                 | 錯頻道之最大輸出率組合。        |                                     | "electronic assemblies", modules, or equipment,    |
|           |                 |                     |                                     | the "sample rates" are aggregated and the "sample  |
|           |                 |                     |                                     | rate" is the maximum combined total rate of all    |
|           |                 |                     |                                     | the interleaved channels.                          |

| 修正條目  | 現行內容                   | 擬修正/新增內容               | 現行內容英譯                              | 擬修正/新增內容英譯  |
|-------|------------------------|------------------------|-------------------------------------|---|
|       | 3A233 除 0B002.g.所述以外之如 | 3A233 除 0B002.g.所述以外之如 | 3A233 Mass spectrometers, other     | 3A233 Mass spectrometers, other than those        |
|       | 下質譜儀,能夠量測230原子質量       | 下質譜儀,能夠量測 230 u 或以上    | than those specified in OBO02.g.,   | specified in OBOO2.g., capable of measuring ions  |
|       | 單位或以上之離子,且其解析度優        | 之離子,且其解析度優於2/230,      | capable of measuring ions of 230    | of 230 u or greater and having a resolution of    |
| 3A233 | 於 2/230, 及其離子源:        | 及其離子源:                 | atomic mass units or greater and    | better than 2 parts in 230, as follows, and ion   |
|       |                        |                        | having a resolution of better than  | sources therefor:                                 |
|       |                        |                        | 2 parts in 230, as follows, and ion |   |
|       |                        |                        | sources therefor:                   |   |
|       | h. 具相位移層之多層光罩,未由       | h. 具相位移層之多層光罩,未在       | h. Multi-layer masks with a phase   | h. Multi-layer masks with a phase shift layer not |
|       | 3B001.g.規範且具有下列任一特     | 3B001.g.中規範且具下列任一特     | shift layer not specified by        | specified in 3B001.g. and having any of the       |
|       | 性:                     | 性:                     | 3B001.g. and having any of the      | following:  |
|       | 1. 以玻璃光罩 "空白基板" 製成     | 1. 以玻璃光罩 "空白基板" 製成     | following:                          | 1. Made on a mask "substrate blank" from glass    |
|       | 其雙折射小於7nm/cm;或         | 其雙折射小於7nm/cm;或         | 1. Made on a mask "substrate blank" | specified as having less than 7 nm/cm             |
|       | 2. 設計用於微影製程設備其光源       | 2. 設計用於微影製程設備其光源       | from glass specified as having less | birefringence; or                                 |
|       | 波長小於 245 nm;           | 波長小於 245 nm;           | than 7 nm/cm birefringence; or      | 2. Designed to be used by lithography equipment   |
|       | 註解:3B001.h.不管制為製造不受    | 註解:3B001.h.不管制為製造不受    | 2. Designed to be used by           | having a light source wavelength less than 245    |
| 3B001 | 3A001 所管制之記憶體元件而設      | 3A001 所管制之記憶體元件而設      | lithography equipment having a      | nm;   |
|       | 計具相位移層之多層光罩。           | 計具相位移層之多層光罩。           | light source wavelength less than   | Note: 3B001.h. does not control multi-layer       |
|       | i. 設計用於 3A001 所述之積體電   | i. 設計用於 3A001 所述之積體電   | 245 nm;                             | masks with a phase shift layer designed for the   |
|       | 路之壓模微影模板。              | 路之壓模微影模板;              | Note: 3B001.h. does not control     | fabrication of memory devices not specified in    |
|       |                        | j. 光罩 "毛坯基板" 具由鉬與矽製    | multi-layer masks with a phase      | 3A001.  |
|       |                        | 成的多層反射結構,且具下列所有        | shift layer designed for the        | i. Imprint lithography templates designed for     |
|       |                        | 特性:                    | fabrication of memory devices not   | integrated circuits specified in 3A001.           |
|       |                        | 1. 特別設計為 極紫外線          | controlled by 3A001.                | j. Mask "substrate blanks" with multilayer        |
|       |                        | (EUV) ´微影製程;及          | i. Imprint lithography templates    | reflector structure consisting of molybdenum and  |

| 修正條目     | 現行內容                   | 擬修正/新增內容                | 現行內容英譯                             | 擬修正/新增內容英譯                                       |
|----------|------------------------|-------------------------|------------------------------------|--|
|          |                        | 2. 符合 SEMI 之 P37 標準。    | designed for integrated circuits   | silicon, and having all of the following:        |
|          |                        | 技術註解:                   | specified in 3A001.                | 1. Specially designed for 'Extreme Ultraviolet'  |
|          |                        | ~極紫外線(EUV) ~指大於 5 nm    |                                    | ('EUV') lithography; and                         |
|          |                        | 而小於 124 nm 的電磁譜波長。      |                                    | 2. Compliant with SEMI Standard P37.             |
|          |                        |                         |                                    | Technical Note:                                  |
|          |                        |                         |                                    | 'Extreme Ultraviolet' ('EUV') refers to          |
|          |                        |                         |                                    | electromagnetic spectrum wavelengths greater     |
|          |                        |                         |                                    | than 5 nm and less than 124 nm.                  |
|          | a. 為測試頻率超過 31.8 GHz 電晶 | a. 為測試 3A001.b.3 所述項目之  | a. For testing S-parameters of     | a. For testing S-parameters of items specified   |
|          | 體元件之 S-參數者;            | S-參數者;                  | transistor devices at frequencies  | in 3A001.b.3.;                                   |
|          | b. 刪除;                 | b. 刪除;                  | exceeding 31,8 GHz;                | b. Not used;                                     |
| 3B002    | c. 為測試 3A001.b.2.所述之微波 | c. 為測試 3A001.b.2.所述項目者。 | b. Not used;                       | c. For testing items specified in 3A001.b.2.     |
|          | 積體電路者。                 |                         | c. For testing microwave           |  |
|          |                        |                         | integrated circuits specified in   |  |
|          |                        |                         | 3A001. b. 2.                       |  |
|          | 1. 特別調整(最佳化)之正光阻,其     | 1. 特別調整(最佳化)之正光阻,其      | 1. Positive resists adjusted       | 1. Positive resists adjusted (optimised) for use |
| 3C002. a | 使適用於波長小於 245 nm,但等     | 使適用於波長小於 193 nm,但等      | (optimised) for use at wavelengths | at wavelengths less than 193 nm but equal to or  |
| 30002. a | 於或大於 15 nm;            | 於或大於 15 nm;             | less than 245 nm but equal to or   | greater than 15 nm;                              |
|          |                        |                         | greater than 15 nm;                |  |
|          | 3C005 碳化矽晶圓(SiC)、氮化鎵   | 3C005 高電阻材料,如下:         | 3C005 Silicon carbide (SiC),       | 3C005 High resistivity materials as follows:     |
|          | (GaN)、氮化鋁(AlN)或氮化鋁鎵    | a. 碳化矽晶圓(SiC)、氮化鎵       | gallium nitride (GaN), aluminium   | a. Silicon carbide (SiC), gallium nitride (GaN), |
| 3C005    | (AlGaN)之半導體"基板",或錠、    | (GaN)、氮化鋁(AlN)或氮化鋁鎵     | nitride (AlN) or aluminium gallium | aluminium nitride (AlN) or aluminium gallium     |
|          | 圓柱狀、其它型態之上述材料,在        | (AlGaN)之半導體"基板",或錠、     | nitride (AlGaN) semiconductor      | nitride (AlGaN) semiconductor "substrates", or   |
|          | 20 °C 時電阻率大於 10,000    | 圓柱狀、其它型態之上述材料,在         | "substrates", or ingots, boules,   | ingots, boules, or other preforms of those       |

| 修正條目       | 現行內容                 | 擬修正/新增內容                | 現行內容英譯                               | 擬修正/新增內容英譯                                       |
|------------|----------------------|-------------------------|--------------------------------------|--|
|            | ohm-cm 者。            | 20 °C 時電阻率大於 10,000     | or other preforms of those           | materials, having resistivities greater than 10  |
|            |                      | ohm-cm 者;               | materials, having resistivities      | 000 ohm-cm at 20 °C;                             |
|            |                      | b. 多晶"基板"或多晶陶瓷"基        | greater than 10 000 ohm-cm at 20 °C. | b. Polycrystalline "substrates" or               |
|            |                      | 板",在20°C時電阻率大於          |                                      | polycrystalline ceramic "substrates", having     |
|            |                      | 10,000 ohm-cm,且"基板"表面   |                                      | resistivities greater than 10 000 ohm-cm at 20   |
|            |                      | 具至少一層矽(Si)、碳化矽晶圓        |                                      | °C and having at least one non-epitaxial         |
|            |                      | (SiC)、氮化鎵(GaN)、氮化鋁(AlN) |                                      | single-crystal layer of silicon (Si), silicon    |
|            |                      | 或氮化鋁鎵(AlGaN)的非外延單晶      |                                      | carbide (SiC), gallium nitride (GaN), aluminium  |
|            |                      | 層。                      |                                      | nitride (AlN), or aluminium gallium nitride      |
|            |                      |                         |                                      | (A1GaN) on the surface of the "substrate".       |
|            | 3C006 3C005 所述"基板",至 | 3C006 未在 3C001 中所述之材    | 3C006 "Substrates" specified in      | 3C006 Materials, not specified in 3C001,         |
|            | 少有一個磊晶層為碳化矽,氮化       | 料,含有 3C005 所述"基板",      | 3C005 with at least one epitaxial    | consisting of a "substrate" specified in 3C005   |
| 3C006      | 鎵, 氮化鋁或氮化鋁鎵。         | 至少有一個磊晶層為碳化矽,氮化         | layer of silicon carbide, gallium    | with at least one epitaxial layer of silicon     |
|            |                      | 鎵,氮化鋁或氮化鋁鎵。             | nitride, aluminium nitride or        | carbide, gallium nitride, aluminium nitride or   |
|            |                      |                         | aluminium gallium nitride.           | aluminium gallium nitride.                       |
|            | 無                    | 註解3:3E001不管制`製程設計       | _                                    | Note 3: 3E001 does not control 'Process Design   |
| 3E001 註解   |                      | 套件´(`PDKs´) 除非其包括可      |                                      | Kits' ('PDKs') unless they include libraries     |
| OEUUI EEAF |                      | 實現 3A001 所述項目之功能或技      |                                      | implementing functions or technologies for items |
|            |                      | 術者。                     |                                      | specified in 3A001.                              |
|            | 無                    | 技術註解:                   | _                                    | Technical Note:                                  |
| 3E001 技術   |                      | `製程設計套件´(`PDKs´)為       |                                      | A'Process Design Kit' ('PDK') is a software tool |
| 註解         |                      | 半導體製造商所提供之軟體工           |                                      | provided by a semiconductor manufacturer to      |
| <b>叶</b>   |                      | 具,用以確保必要的設計作法與規         |                                      | ensure that the required design practices and    |
|            |                      | 則,以能在特定半導體製程中根據         |                                      | rules are taken into account in order to         |

| 修正條目          | 現行內容                            | 擬修正/新增內容                        | 現行內容英譯                             | 擬修正/新增內容英譯                                       |
|---------------|---------------------------------|---------------------------------|------------------------------------|--|
|               |                                 | 技術和製造限制,成功的生產積體                 |                                    | successfully produce a specific integrated       |
|               |                                 | 電路(每個半導體製程都有其特定                 |                                    | circuit design in a specific semiconductor       |
|               |                                 | 的 PDK )。                        |                                    | process, in accordance with technological and    |
|               |                                 |                                 |                                    | manufacturing constraints (each semiconductor    |
|               |                                 |                                 |                                    | manufacturing process has its particular 'PDK'). |
|               | 註解2:直接與中央處理器之匯流                 | 註解2:直接與中央處理器之匯流                 | Note 2: Control units which        | Note 2: Control units which directly             |
|               | 排或通道、"主儲存體"或磁碟控                 | 排或通道、`主儲存體´或磁碟控                 | directly interconnect the buses or | interconnect the buses or channels of central    |
|               | 制器連結之控制單元,不被視為第                 | 制器連結之控制單元,不被視為第                 | channels of central processing     | processing units, 'main storage' or disk         |
| 4A 註解         | 5 類第 1 部分(電信)所述之電信設             | 5 類第 1 部分(電信)所述之電信設             | units, "main storage" or disk      | controllers are not regarded as                  |
| 4A 註胖         | 備。                              | 備。                              | controllers are not regarded as    | telecommunications equipment described in        |
|               |                                 |                                 | telecommunications equipment       | Category 5, Part 1 (Telecommunications).         |
|               |                                 |                                 | described in Category 5, Part 1    |  |
|               |                                 |                                 | (Telecommunications).              |  |
|               | 無                               | 技術註解:                           | -                                  | Technical Note:                                  |
|               |                                 | `主儲存體´指由中央處理器快                  |                                    | 'Main storage' is the primary storage for data   |
|               |                                 | 速存取之主要資料或指令儲存裝                  |                                    | or instructions for rapid access by a central    |
| 11 1+ U=++ A7 |                                 | 置。其由"數位電腦"內部儲存裝                 |                                    | processing unit. It consists of the internal     |
| 4A 技術註解       |                                 | 置及其分級延伸部分所組成,如高                 |                                    | storage of a "digital computer" and any          |
|               |                                 | 速緩衝儲存裝置或非序列存取延                  |                                    | hierarchical extension thereto, such as cache    |
|               |                                 | 伸儲存裝置。                          |                                    | storage or non-sequentially accessed extended    |
|               |                                 |                                 |                                    | storage.   |
|               | b. "數位電腦" 具有"調整尖峰               | b. "數位電腦" 具有"調整尖峰               | b. "Digital computers" having an   | b. "Digital computers" having an "Adjusted Peak  |
| 4A003. b      | 效能" ( "APP")超過每秒 16 加           | 效能"("APP")超過每秒 29 加             | "Adjusted Peak Performance"        | Performance" ("APP") exceeding 29 Weighted       |
|               | 權兆(10 <sup>12</sup> )浮點運算(WT)者; | 權兆(10 <sup>12</sup> )浮點運算(WT)者; | ("APP") exceeding 16 Weighted      | TeraFLOPS (WT);                                  |

| 修正條目  | 現行內容             | 擬修正/新增內容         | 現行內容英譯                         | 擬修正/新增內容英譯  |
|-------|------------------|------------------|--------------------------------|---|
|       |                  |                  | TeraFLOPS (WT);                |   |
|       | 4A004 電腦及特別設計之相關 | 4A004 電腦及特別設計之相關 | 4A004 Computers as follows and | 4A004 Computers as follows and specially          |
|       | 設備、"電子組件"及其零件如下: | 設備、"電子組件"及其零件如下: | specially designed related     | designed related equipment, "electronic           |
|       | a. "脈動陣列電腦";     | a. `脈動陣列電腦´;     | equipment, "electronic         | assemblies" and components therefor:              |
|       | b. "類神經電腦";      | b. `類神經電腦´;      | assemblies" and components     | a. 'Systolic array computers';                    |
|       | c. "光學電腦"。       | c. `光學電腦´。       | therefor:                      | b. 'Neural computers';                            |
|       |                  | 技術註解:            | a. "Systolic array computers"; | c. 'Optical computers'.                           |
|       |                  | 1. `脈動陣列電腦´指可由使用 | b. "Neural computers";         | Technical Notes:                                  |
|       |                  | 者在邏輯閘層次機動控制資料流   | c. "Optical computers".        | 1. 'Systolic array computers' are computers       |
|       |                  | 通與修改之電腦。         |                                | where the flow and modification of the data is    |
|       |                  | 2. `類神經電腦´指設計或修改 |                                | dynamically controllable at the logic gate level  |
|       |                  | 以模仿神經細胞或一群神經細胞   |                                | by the user.                                      |
| 4A004 |                  | 之行為之計算裝置,即此計算裝置  |                                | 2. 'Neural computers' are computational devices   |
|       |                  | 以其硬體性能區別其特色,而此硬  |                                | designed or modified to mimic the behaviour of    |
|       |                  | 體可依據以往資料調整多重計算   |                                | a neuron or a collection of neurons, i.e.,        |
|       |                  | 組件之重量與其互連數目。     |                                | computational devices which are distinguished by  |
|       |                  | 3. `光學電腦´指設計或修改以 |                                | their hardware capability to modulate the         |
|       |                  | 使用光呈現資料之電腦,其邏輯運  |                                | weights and numbers of the interconnections of    |
|       |                  | 算元件以直接耦合光學裝置為基   |                                | a multiplicity of computational components based  |
|       |                  | 礎。               |                                | on previous data.                                 |
|       |                  |                  |                                | 3. 'Optical computers' are computers designed or  |
|       |                  |                  |                                | modified to use light to represent data and whose |
|       |                  |                  |                                | computational logic elements are based on         |
|       |                  |                  |                                | directly coupled optical devices.                 |

| 修正條目        | 現行內容                | 擬修正/新增內容                | 現行內容英譯                           | 擬修正/新增內容英譯                                       |
|-------------|---------------------|-------------------------|----------------------------------|--|
|             | 1. "數位電腦" 具有"調整尖峰   | 1. "數位電腦" 具有"調整尖峰       | 1. "Digital computers" having an | 1. "Digital computers" having an "Adjusted Peak  |
| 4D001. b. 1 | 效能"("APP")超過8.0 加權兆 | 效能"("APP")超過 15 加權兆浮    | "Adjusted Peak Performance"      | Performance" ("APP") exceeding 15 Weighted       |
|             | 浮點運算(WT)者;          | 點運算(WT)者;               | ("APP") exceeding 8,0 Weighted   | TeraFLOPS (WT);                                  |
|             |                     |                         | TeraFLOPS (WT);                  |  |
|             | 無                   | 註解: 4D004 不管制特別設計僅      | -                                | Note: 4D004 does not control "software"          |
|             |                     | 限於提供"軟體"更新或升級之"軟        |                                  | specially designed and limited to provide        |
|             |                     | 體",具下列所有特性:             |                                  | "software" updates or upgrades meeting all the   |
|             |                     | a. 更新與升級操作僅在系統所         |                                  | following:                                       |
|             |                     | 有者或管理員授權下進行; 及          |                                  | a. The update or upgrade operates only with the  |
| 4D004 註解    |                     | b. 在更新與升級後, "軟體"之       |                                  | authorisation of the owner or administrator of   |
|             |                     | 更新或升級不具下列任一特性:          |                                  | the system receiving it; and                     |
|             |                     | 1.4D004 所述之"軟體",或       |                                  | b. After the update or upgrade, the "software"   |
|             |                     | 2. "入侵軟體"               |                                  | updated or upgraded is not any of the following: |
|             |                     |                         |                                  | 1. "Software" specified in 4D004; or             |
|             |                     |                         |                                  | 2. "Intrusion software".                         |
|             | 1. "數位電腦"具有"調整尖峰    | 1. "數位電腦"具有"調整尖峰        | 1. "Digital computers" having an | 1. "Digital computers" having an "Adjusted Peak  |
| 4E001. b. 1 | 效能"("APP")超過8.0 加權兆 | 效能"("APP")超過 15 加權兆浮    | "Adjusted Peak Performance"      | Performance" ("APP") exceeding 15 Weighted       |
| 46001.0.1   | 浮點運算(WT)者;          | 點運算(WT)者;               | ("APP") exceeding 8,0 Weighted   | TeraFLOPS (WT);                                  |
|             |                     |                         | TeraFLOPS (WT);                  |  |
|             | 無                   | 註解1:4E001.a.與4E001.c.不管 | -                                | Note 1: 4E001.a. and 4E001.c. do not control     |
|             |                     | 制、弱點公開、或、網路事件應          |                                  | 'vulnerability disclosure' or 'cyber incident    |
| 4E001 註解    |                     | 變~。                     |                                  | response'.                                       |
|             |                     | 註解2:註解1不會減損會員國主         |                                  | Note 2: Note 1 does not diminish the rights of   |
|             |                     | 管機關之權利,出口商應確立符合         |                                  | the competent authority of the Member State in   |

| 修正條目           | 現行內容                        | 擬修正/新增內容                    | 現行內容英譯                                 | 擬修正/新增內容英譯   |
|----------------|-----------------------------|-----------------------------|--|--|
|                |                             | 4E001.a.與 4E001.c.規範。       |  | which the exporter is established to ascertain         |
|                |                             |                             |  | compliance with 4E001.a. and 4E001.c.                  |
|                | 無                           | 技術註解:                       | -                                      | Technical Notes:                                       |
|                |                             | 1. 、弱點公開、指以解決漏洞為            |  | 1. 'Vulnerability disclosure' means the process        |
|                |                             | 目的,由負責處理的個人或組織或             |  | of identifying, reporting, or communicating a          |
|                |                             | 協同處者進行識別,報告或傳播漏             |  | vulnerability to, or analysing a vulnerability         |
|                |                             | 洞或分析漏洞的過程。                  |  | with, individuals or organizations responsible         |
| 4E001 技術       |                             | 2. `網路事件應變´指解決網路            |  | for conducting or coordinating remediation for         |
| 4EUUI 技術<br>註解 |                             | 安全事件時,由負責處理的個人或             |  | the purpose of resolving the vulnerability.            |
| <u>計工 州牛</u>   |                             | 組織或協同處者在網路安全事件              |  | 2. 'Cyber incident response' means the process         |
|                |                             | 上交換必要訊息的過程。                 |  | of exchanging necessary information on a cyber         |
|                |                             |                             |  | security incident with individuals or                  |
|                |                             |                             |  | organizations responsible for conducting or            |
|                |                             |                             |  | coordinating remediation to address the cyber          |
|                |                             |                             |  | security incident.                                     |
|                | 3. 為在溫度 218 K (-55 °C)至 397 | 3. 為在溫度低於 218 K (-55 °C)    | 3. Specially designed to operate       | 3. Specially designed to operate below 218 K ( -       |
|                | K (124°C)範圍之外操作而特別          | 操作而特別設計者;或                  | outside the temperature range from     | 55 °C); or   |
|                | 設計者。                        | 4. 為在溫度高於 397 K (124 °C)    | 218 K ( - 55 °C) to 397 K (124 °C);    | 4. Specially designed to operate above 397 K (124      |
|                | 註解:5A001.a.2.及 5A001.a.3.不管 | 操作而特別設計者;                   | Note: 5A001.a.3. applies only to       | °C);   |
| 5A001          | 制為衛星上使用而設計或修改之              | 註解 1:5A001.a.3.與 5A001.a.4. | electronic equipment.                  | Note 1: 5A001.a.3. and 5A001.a.4. control only         |
|                | 設備。                         | 僅管制電子設備。                    | Note: 5A001. a. 2. and 5A001. a. 3. do | electronic equipment.                                  |
|                |                             | 註解 2:5A001.a.2.、5A001.a.3.及 | not control equipment designed or      | Note 2: 5A001. a. 2., 5A001. a. 3. and 5A001. a. 4. do |
|                |                             | 5A001.a.4.不管制設計或改裝用於        | modified for use on board              | not control equipment designed or modified for         |
|                |                             | 衛星上使用之設備。                   | satellites.                            | use on board satellites.                               |

| 修正條目      | 現行內容                | 擬修正/新增內容                  | 現行內容英譯                             | 擬修正/新增內容英譯                                       |
|-----------|---------------------|---------------------------|------------------------------------|--|
| E4001 4   | d. "電子操控相位陣列天線",    | d. `電子操控相位陣列天線´,          | d. "Electronically steerable       | d. 'Electronically steerable phased array        |
| 5A001.d   | 如下:                 | 如下:                       | phased array antennae" as follows: | antennae' as follows:                            |
|           | 註解:5A001.d.不管制包含微波著 | 註解1:5A001.d.不管制包含微波       | Note: 5A001.d. does not control    | Note 1: 5A001.d. does not control                |
|           | 陸系統(MLS),符合ICAO標準之  | 著陸系統(MLS),符合 ICAO 標準      | "electronically steerable phased   | 'electronically steerable phased array           |
|           | 儀器的著陸系統用"電子操控相位     | 之儀器的著陸系統用`電子操控            | array antennae" for landing        | antennae' for landing systems with instruments   |
|           | 陣列天線"。              | 相位陣列天線~。                  | systems with instruments meeting   | meeting ICAO standards covering Microwave        |
|           |                     | 註解 2:5A001.d.不管制天線,其      | ICAO standards covering Microwave  | Landing Systems (MLS).                           |
| 5A001.d 註 |                     | 特別設計為下列任一者:               | Landing Systems (MLS).             | Note 2: 5A001.d. does not control antennae       |
| 解         |                     | a. 民用蜂巢式或WLAN無線電通         |                                    | specially designed for any of the following:     |
|           |                     | 信系統;                      |                                    | a. Civil cellular or WLAN radio-communications   |
|           |                     | b. IEEE 802.15 或無線 HDMI;或 |                                    | systems;   |
|           |                     | c.商業民用電信用固定或移動式           |                                    | b. IEEE 802.15 or wireless HDMI; or              |
|           |                     | 衛星地面接收站。                  |                                    | c. Fixed or mobile satellite earth stations for  |
|           |                     |                           |                                    | commercial civil telecommunications.             |
|           | 無                   | 技術註解:                     | _                                  | Technical Note:                                  |
|           |                     | 就 5A001.d. 而言, `電子操控相     |                                    | For the purposes of 5A001.d. 'electronically     |
|           |                     | 位陣列天線「指以相位耦合方式            |                                    | steerable phased array antenna' is an antenna    |
|           |                     | 形成波束之天線,例如波束方向由           |                                    | which forms a beam by means of phase coupling,   |
| 5A001.d 技 |                     | 輻射元件之複雜激發係數控制,且           |                                    | (i.e., the beam direction is controlled by the   |
| 術註解       |                     | 應用電子訊號之傳輸與接收,波束           |                                    | complex excitation coefficients of the radiating |
|           |                     | 方向之方位或高度,或二者均可改           |                                    | elements) and the direction of that beam can be  |
|           |                     | 變。                        |                                    | varied (both in transmission and reception) in   |
|           |                     |                           |                                    | azimuth or in elevation, or both, by application |
|           |                     |                           |                                    | of an electrical signal.                         |

| 修正條目     | 現行內容                | 擬修正/新增內容                 | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|----------|---------------------|--------------------------|-------------------------------------|--|
|          | a. 設計或修改用於 資料機密性    | a. 設計或修改用於 資料機密性         | a. Designed or modified to use      | a. Designed or modified to use cryptography for  |
|          | 密碼學 , 其具等於或超過 56 位  | 密碼學 7 ,其具等於或超過 56 位      | 'cryptography for data              | data confidentiality' having 'in excess of 56    |
|          | 元對稱金鑰長度,其密碼能夠在不     | 元對稱金鑰長度,其密碼功能能夠          | confidentiality' having' in excess  | bits of symmetric key length, or equivalent,     |
|          | 需"密碼啟用"下使用或已經被啟     | 以不使用安全機制的"密碼啟用"          | of 56 bits of symmetric key length, | where that cryptographic capability is usable,   |
| 5A002.a  | 用,如下:               | 進行使用、已經啟用或能夠啟用,          | or equivalent', where that          | has been activated, or can be activated by means |
|          |                     | 如下:                      | cryptographic capability is usable  | of "cryptographic activation" not employing a    |
|          |                     |                          | without "cryptographic              | secure mechanism, as follows:                    |
|          |                     |                          | activation" or has been activated,  |  |
|          |                     |                          | as follows:                         |  |
|          | b. 透過 "密碼啟用"設計或改裝,  | b. 透過"密碼啟用"設計或改裝         | b. Designed or modified to enable,  | b. Designed or modified for converting, by means |
|          | 使原本未達到 5A002.a.所述之項 | 用於轉換者,未由第5類第2部分          | by means of "cryptographic          | of "cryptographic activation", an item not       |
|          | 目能夠超過管制之性能水準。       | 所述之項目,至 5A002.a.或        | activation" an item to achieve or   | specified in Category 5 - Part 2 into an item    |
|          |                     | 5D002.c.1.所述之項目,且非由密     | exceed the controlled performance   | specified in 5A002.a. or 5D002.c.1., and not     |
| 5A002. b |                     | 碼註解所發布者(第5類第2部分          | levels for functionality specified  | released by the Cryptography Note (Note 3 in     |
|          |                     | 註解 3),或是透過 "密碼啟用"        | in 5A002.a. that would not          | Category 5 - Part 2), or for enabling, by means  |
|          |                     | 附加功能進行啟動,其由 5A002.a.     | otherwise be enabled.               | of "cryptographic activation", additional        |
|          |                     | 所述之項目,已在第5類第2部分          |                                     | functionality specified in 5A002.a. of an item   |
|          |                     | 中所述。                     |                                     | already specified in Category 5 - Part 2;        |
|          | b. 設計或改裝之 "軟體" 由 "密 | b. 透過"密碼啟用"設計或改裝         | b. "Software" designed or modified  | b. "Software" designed or modified for           |
|          | 碼啟用″所啟動,項目符合        | 用於轉換之"軟體",其未由第5          | to enable, by means of              | converting, by means of "cryptographic           |
| 5D002. b | 5A002.a.所管制之功能性規範,否 | 類第2部分所述之項目,至             | "cryptographic activation", an      | activation", an item not specified in Category   |
| JUUU4. D | 則無法運作;              | 5A002.a.或 5D002.c.1.所述之項 | item to meet the criteria for       | 5 - Part 2 into an item specified in 5A002.a.    |
|          |                     | 目,且非由密碼註解所發布者(第          | functionality specified by          | or 5D002.c.1., and not released by the           |
|          |                     | 5類第2部分註解3),或是透過"密        | 5A002.a., that would not otherwise  | Cryptography Note (Note 3 in Category 5 - Part   |

| 修正條目     | 現行內容              | 擬修正/新增內容             | 現行內容英譯                              | 擬修正/新增內容英譯                                       |
|----------|-------------------|----------------------|-------------------------------------|--|
|          |                   | 碼啟用"附加功能進行啟動,其由      | be met;                             | 2), or for enabling, by means of "cryptographic  |
|          |                   | 5A002.a.所述之項目,已在第5類  |                                     | activation", additional functionality specified  |
|          |                   | 第2部分中所述。             |                                     | in 5A002.a. of an item already specified in      |
|          |                   |                      |                                     | Category 5 - Part 2;                             |
|          | b. 透過"密碼啟用"設計或改裝  | b. 透過"密碼啟用"用於轉換之     | b. "Technology" to enable, by means | b. "Technology" for converting, by means of      |
|          | 之"技術",使原本無法達到     | "技術",其未由第5類第2部分      | of "cryptographic activation", an   | "cryptographic activation", an item not          |
|          | 5A002.a.所述之功能標準的項 | 所述之項目,至 5A002.a.或    | item to meet the criteria for       | specified in Category 5 - Part 2 into an item    |
|          | 目,能夠達到管制的標準。      | 5D002.c.1.所述之項目,且非由密 | functionality specified by          | specified in 5A002.a. or 5D002.c.1., and not     |
| 5E002. b |                   | 碼註解所發布者(第5類第2部分      | 5A002.a., that would not otherwise  | released by the Cryptography Note (Note 3 in     |
|          |                   | 註解 3),或是透過 "密碼啟用"    | be met.                             | Category 5 - Part 2), or for enabling, by means  |
|          |                   | 附加功能進行啟動,其由 5A002.a. |                                     | of "cryptographic activation", additional        |
|          |                   | 所述之項目,已在第5類第2部分      |                                     | functionality specified in 5A002.a. of an item   |
|          |                   | 中所述。                 |                                     | already specified in Category 5 - Part 2;        |
|          | 無                 | f. `讀出積體電路´(`ROIC´)  | -                                   | f. 'Read-out integrated circuits' ('ROIC')       |
|          |                   | 特別設計用於 6A002.a.3.所述之 |                                     | specially designed for "focal plane arrays"      |
|          |                   | "焦面陣列"。              |                                     | specified in 6A002.a.3.                          |
|          |                   | 註解:6A002.f.不管制特別設計為  |                                     | Note: 6A002.f. does not control 'read-out        |
|          |                   | 民用汽車應用的 `讀出積體電       |                                     | integrated circuits' specially designed for      |
| 6A002. f |                   | 路′者。                 |                                     | civil automotive applications.                   |
|          |                   | 技術註解:                |                                     | Technical Note:                                  |
|          |                   | `讀出積體電路´(`ROIC´)指    |                                     | A'Read-Out Integrated Circuit' ('ROIC') is an    |
|          |                   | 積體電路設計用於支持或結合"焦      |                                     | integrated circuit designed to underlie or be    |
|          |                   | 面陣列"("FPA"),其使用於讀    |                                     | bonded to a "focal plane array" ("FPA") and used |
|          |                   | 出(即擷取與暫存)探測元件所產      |                                     | to read-out (i.e., extract and register) signals |

| 修正條目      | 現行內容                        | 擬修正/新增內容                   | 現行內容英譯                             | 擬修正/新增內容英譯  |
|-----------|-----------------------------|----------------------------|------------------------------------|---|
|           |                             | 生的訊號,最低限度的 ROIC (          |                                    | produced by the detector elements. At a minimum   |
|           |                             | 能透過擷取方式由探測元件讀取             |                                    | the 'ROIC' reads the charge from the detector     |
|           |                             | 電荷,與應用多工功能方式維持探            |                                    | elements by extracting the charge and applying    |
|           |                             | 測元件中相對空間位置與方向資             |                                    | a multiplexing function in a manner that retains  |
|           |                             | 訊,以利在 ROIC 內部或外部           |                                    | the relative spatial position and orientation     |
|           |                             | 進行處理。                      |                                    | information of the detector elements for          |
|           |                             |                            |                                    | processing inside or outside the 'ROIC'.          |
|           | a. 儀器用照相機及其特別設計之            | a. 儀器用照相機及其特別設計之           | a. Instrumentation cameras and     | a. Instrumentation cameras and specially          |
|           | 零件,如下:                      | 零件,如下:                     | specially designed components      | designed components therefor, as follows:         |
|           | 註解: 6A003.a.3.至 6A003.a.5.所 | 註解:6A003.a.3.至 6A003.a.5.所 | therefor, as follows:              | Note: Instrumentation cameras, specified in       |
|           | 述,具有模組構造之儀器用照相              | 述,具有模組構造之儀器用照相             | Note: Instrumentation cameras,     | 6A003.a.3. to 6A003.a.5., with modular            |
|           | 機,需根據該照相機製造商之產品             | 機,需根據該照相機製造商之產品            | specified in 6A003.a.3. to         | structures should be evaluated by their maximum   |
| 6A003.a   | 規格,以外接物件所提供之最大功             | 規格,以外接物件所提供之最大功            | 6A003.a.5., with modular           | capability, using plug-ins available according    |
|           | 能來評量。                       | 能來評量。                      | structures should be evaluated by  | to the camera manufacturer's specifications.      |
|           |                             | 1. 刪除;                     | their maximum capability, using    | 1. Not used;                                      |
|           |                             | 2. 刪除;                     | plug-ins available according to    | 2. Not used;                                      |
|           |                             | 3. 電子式高速掃描攝影機時間解           | the camera manufacturer's          | 3. Electronic streak cameras having temporal      |
|           |                             | 析度優於 50 ns;                | specifications.                    | resolution better than 50 ns;                     |
|           | 1. "可變形鏡面"主動光學孔徑            | 1. `可變形鏡面´主動光學孔徑           | 1. "Deformable mirrors" having an  | 1. 'Deformable mirrors' having an active optical  |
|           | 大於 10 mm 及具下列任一特性           | 大於 10 mm 及具下列任一特性          | active optical aperture greater    | aperture greater than 10 mm and having any of the |
| 6A004.a.1 | 者,以及為其特別設計之零件:              | 者,以及為其特別設計之零件:             | than 10 mm and having any of the   | following, and specially designed components      |
|           |                             |                            | following,, and specially designed | therefor,   |
|           |                             |                            | components therefor,               |   |
| 6A004.a.1 | 無                           | 技術註解:                      | -                                  | Technical Note:                                   |

| 修正條目     | 現行內容 | 擬修正/新增內容            | 現行內容英譯 | 擬修正/新增內容英譯  |
|----------|------|---------------------|--------|---|
| 技術註解     |      | `可變形鏡面´為鏡片具下列任      |        | 'Deformable mirrors' are mirrors having any of    |
|          |      | 一特性者:               |        | the following:                                    |
|          |      | a. 對單一連續光反射表面施加個    |        | a. A single continuous optical reflecting         |
|          |      | 別扭力或力,產生動態變形,以補     |        | surface which is dynamically deformed by the      |
|          |      | 償因光波投射於鏡面所引起之變      |        | application of individual torques or forces to    |
|          |      | 形;或                 |        | compensate for distortions in the optical         |
|          |      | b. 具有多重光反射元件,經由施    |        | waveform incident upon the mirror; or             |
|          |      | 加扭力或力,可單獨且機動地重新     |        | b. Multiple optical reflecting elements that can  |
|          |      | 定位,以補償因光波投射於鏡面所     |        | be individually and dynamically repositioned by   |
|          |      | 引起之變形。              |        | the application of torques or forces to           |
|          |      | `可變形鏡面´亦稱為自動補償      |        | compensate for distortions in the optical         |
|          |      | 光學鏡面。               |        | waveform incident upon the mirror.                |
|          |      |                     |        | 'Deformable mirrors' are also known as adaptive   |
|          |      |                     |        | optic mirrors.                                    |
|          | 無    | f. 動態波前測量設備,具下列所有   | _      | f. Dynamic wavefront measuring equipment having   |
|          |      | 特性:                 |        | all of the following:                             |
|          |      | 1. `成幀速率´等於或大於1     |        | 1. 'Frame rates' equal to or more than 1 kHz; and |
|          |      | KHz;及               |        | 2. A wavefront accuracy equal to or less (better) |
| 6A004. f |      | 2. 在設計波長處波前準確度等或    |        | than $\lambda/20$ at the designed wavelength.     |
| 0A004. 1 |      | 小(優)於 λ/20。         |        | Technical Note:                                   |
|          |      | 技術註解:               |        | For the purposes of 6A004.f., 'frame rate' is a   |
|          |      | 6A004.f.所述之`成幀速率´為在 |        | frequency at which all "active pixels" in the     |
|          |      | "焦面陣列"中整合所有"主動像     |        | "focal plane array" are integrated for recording  |
|          |      | 素",由波前光學感知器投射以錄     |        | images projected by the wavefront sensor optics.  |

| 修正條目           | 現行內容                   | 擬修正/新增內容               | 現行內容英譯                            | 擬修正/新增內容英譯                                       |
|----------------|------------------------|------------------------|-----------------------------------|--|
|                |                        | 製影像的頻率。                |                                   |  |
|                | 註解1:6A005.a.6.b.不管制多横向 | 註解1:6A005.a.6.b.不管制多横向 | Note 1: 6A005. a. 6. b. does not  | Note 1: 6A005.a.6.b. does not control multiple   |
|                | 模式、輸出功率超過2kW,但不        | 模式、輸出功率超過2kW,但不        | control multiple transverse mode, | transverse mode, industrial "lasers" with output |
|                | 超過6kW,且總質量大於1,200kg    | 超過6kW,且總質量大於1,200kg    | industrial "lasers" with output   | power exceeding 2 kW and not exceeding 6 kW with |
|                | 之工業用"雷射"。就此註解之目        | 之工業用"雷射"。就此註解之目        | power exceeding 2 kW and not      | a total mass greater than 1 200 kg. For the      |
|                | 的而言,總質量包括操作"雷射"        | 的而言,總質量包括操作"雷射"        | exceeding 6 kW with a total mass  | purpose of this note, total mass includes all    |
| 6A005, a. 6. b | 所需所有之零件,例如"雷射"、        | 所需所有之零件,例如"雷射"、        | greater than 1 200 kg. For the    | components required to operate the "laser",      |
| . 2 註解         | 電源供應器、熱交換器,但不包括        | 電源供應器、熱交換器,但不包括        | purpose of this note, total mass  | e.g., "laser", power supply, heat exchanger, but |
| . 4 註件         | 光束調整及/或傳送之外接光學儀        | 光束調整或傳送之外接光學儀器。        | includes all components required  | excludes external optics for beam conditioning   |
|                | 器。                     |                        | to operate the "laser", e.g.,     | or delivery.                                     |
|                |                        |                        | "laser", power supply, heat       |  |
|                |                        |                        | exchanger, but excludes external  |  |
|                |                        |                        | optics for beam conditioning      |  |
|                |                        |                        | and/or delivery.                  |  |
|                | c. "移轉雷射",如下:          | c. `移轉雷射´,如下:          | c. "Transfer lasers" as follows:  | c. 'Transfer lasers' as follows:                 |
|                | 1. 氧-碘(O2-I) "雷射";     | 1. 氧-碘(O2-I) "雷射";     | 1. Oxygen Iodine (02-I) "lasers"; | 1. Oxygen Iodine (0 2 -I) "lasers";              |
|                | 2. 氟化氘-二氧化碳(DF-CO2) "雷 | 2. 氟化氘-二氧化碳(DF-CO2) "雷 | 2. Deuterium Fluoride-Carbon      | 2. Deuterium Fluoride-Carbon dioxide (DF-C0 2)   |
|                | 射";                    | 射";                    | dioxide (DF-CO 2 ) "lasers";      | "lasers";  |
| 6A005. d. 5. c |                        | 技術註解:                  |                                   | Technical Note:                                  |
|                |                        | `移轉雷射´指具雷射發光性能         |                                   | 'Transfer lasers' are "lasers" in which the      |
|                |                        | 之原子或分子碰撞不具雷射發光         |                                   | lasing species are excited through the transfer  |
|                |                        | 性能之原子或分子,產生之能量移        |                                   | of energy by collision of a non-lasing atom or   |
|                |                        | 轉而激發的一種"雷射"。           |                                   | molecule with a lasing atom or molecule species. |
| 6A005. f       | f. 光學設備,如下:            | f. 光學設備,如下:            | f. Optical equipment as follows:  | f. Optical equipment as follows:                 |

| 修正條目 | 現行內容                  | 擬修正/新增內容              | 現行內容英譯                               | 擬修正/新增內容英譯   |
|------|-----------------------|-----------------------|--------------------------------------|--|
|      | 說明:可操作於"超高功率雷射"       | 說明:可操作於"超高功率雷射"       | N.B. For shared aperture optical     | N.B. For shared aperture optical elements,               |
|      | ("SHPL")之應用的共用孔徑光     | ( "SHPL")之應用的共用孔徑光    | elements, capable of operating in    | capable of operating in "Super-High Power Laser"         |
|      | 學元件,參照軍用貨品管制。         | 學元件,參照軍用貨品管制。         | "Super-High Power Laser" ("SHPL")    | ("SHPL") applications, see the Military Goods            |
|      | 1. 能在光束波前映射至少50個位     | 1. 刪除;                | applications, see the Military       | Controls.  |
|      | 置之動態波前(相位)測量設備,具      | 2. "雷射"診斷設備,特別設計      | Goods Controls.                      | 1. Not used;   |
|      | 有以下任一特性:              | 為動態測量 "SHPL" 系統之角向    | 1. Dynamic wavefront (phase)         | 2. "Laser" diagnostic equipment specially                |
|      | a. 成幀速率等於或大於 100 Hz,  | 光束操縱誤差值,且測量 "準確度      | measuring equipment capable of       | designed for dynamic measurement of "SHPL"               |
|      | 且相位區分至少為光束波長的5        | (或稱"精度")"等於或小於(優於)    | mapping at least 50 positions on a   | system angular beam steering errors and having           |
|      | %;或                   | 10 μrad (微弧度);        | beam wavefront and any of the        | an angular "accuracy" of 10 $\mu$ rad (microradians)     |
|      | b. 成幀速率等於或大於 1,000    | 3. 光學設備及零件,特別設計為      | following:                           | or less (better);  |
|      | Hz,且相位區分至少為光束波長       | 相位陣列 "SHPL" 系統之同調光    | a. Frame rates equal to or more than | 3. Optical equipment and components, specially           |
|      | 的 20 % ;              | 束組合,且具下列任一特性:         | 100 Hz and phase discrimination of   | designed for coherent beam combination in a              |
|      | 2. "雷射"診斷設備,能測量       | a. 波長大於1 μm時,其 "準確    | at least 5 % of the beam's           | phased-array "SHPL" system and having any of the         |
|      | "SHPL"系統之角向光束操縱誤      | 度(或稱 "精度")" 等於或小於 0.1 | wavelength; or                       | following:   |
|      | 差值等於或小於 10 μrad;      | $\mu$ m ;             | b. Frame rates equal to or more than | a. An "accuracy" of 0,1 $\mu$ m or less, for             |
|      | 3. 特別設計為相位陣列 "SHPL"   | b. 波長等於小於1 μm 時,在設    | 1 000 Hz and phase discrimination    | wavelengths greater than 1 $\mu$ m; or                   |
|      | 系統之光學設備及零件,在特定波       | 計波長下,其 "準確度(或稱 "精     | of at least 20 % of the beam's       | b. An "accuracy" of $\lambda/10$ or less (better) at the |
|      | 長下,其同調光束組合之"準確度       | 度")"等於或小於(優於) λ/10;   | wavelength;                          | designed wavelength, for wavelengths equal to or         |
|      | (或稱 "精度")" 為 1/10 波長或 |                       | 2. "Laser" diagnostic equipment      | less than 1 $\mu$ m;                                     |
|      | 0.1 μm 兩者之較小值者;       |                       | capable of measuring "SHPL" system   |  |
|      | 4. 為與 "SHPL" 系統共同使用而  |                       | angular beam steering errors of      |  |
|      | 特別設計之投影式望遠鏡。          |                       | equal to or less than 10 $\mu$ rad;  |  |
|      |                       |                       | 3. Optical equipment and             |  |
|      |                       |                       | components, specially designed for   |  |

| 修正條目        | 現行內容                  | 擬修正/新増內容               | 現行內容英譯                                     | 擬修正/新增內容英譯  |
|-------------|-----------------------|------------------------|--|---|
|             |                       |                        | a phased-array "SHPL" system for           |   |
|             |                       |                        | coherent beam combination to an            |   |
|             |                       |                        | "accuracy" of $\lambda/10$ at the designed |   |
|             |                       |                        | wavelength, or 0,1 $\mu$ m, whichever      |   |
|             |                       |                        | is the smaller;                            |   |
|             |                       |                        | 4. Projection telescopes specially         |   |
|             |                       |                        | designed for use with "SHPL"               |   |
|             |                       |                        | systems;                                   |   |
|             | 2. 作業(操作中) "準確度(或稱    | 2. 作業(操作中) "準確度(或稱     | 2. An in-service (operational)             | 2. An in-service (operational) "accuracy" of      |
|             | "精度")"小於(優於)0.7 mGal, | "精度")"小於(優於) 0.7 mGal, | "accuracy" of less (better) than           | less (better) than 0,7 mGal having a              |
|             | 在伴隨矯正補償及移動影響之任        | 在伴隨矯正補償及移動影響之任         | 0,7 mGal having a'time-to-steady-          | "time-to-steady- state registration" of less      |
|             | 何組合下,其到達`穩定狀態時        | 何組合下,其到達"穩定狀態時間"       | state registration' of less than 2         | than 2 minutes under any combination of attendant |
|             | 間´小於2分鐘;              | 小於2分鐘;                 | minutes under any combination of           | corrective compensations and motional             |
|             |                       |                        | attendant corrective                       | influences;                                       |
|             |                       |                        | compensations and motional                 |   |
| 6A007. b. 2 |                       |                        | influences;                                |   |
| 0A001. D. Z |                       |                        | Technical Note:                            |   |
|             |                       |                        | For the purposes of 6A007.b.,              |   |
|             |                       |                        | 'time-to-steady-state                      |   |
|             |                       |                        | registration' (also referred to as         |   |
|             |                       |                        | the gravimeter's response time)            |   |
|             |                       |                        | is the time over which the                 |   |
|             |                       |                        | disturbing effects of platform             |   |
|             |                       |                        | induced accelerations (high                |   |

| 修正條目     | 現行內容                    | 擬修正/新增內容             | 現行內容英譯                            | 擬修正/新增內容英譯  |
|----------|-------------------------|----------------------|-----------------------------------|---|
|          |                         |                      | frequency noise) are reduced.     |   |
|          | e. 含有電子操控陣列天線;          | e. 含有電子掃描陣列天線;       | e. Incorporating electronically   | e. Incorporating electronically scanned array     |
|          |                         | 技術註解:                | steerable array antennae;         | antennae;   |
| 6A008. e |                         | 電子掃描陣列天線亦稱為電子操       |                                   | Technical Note:                                   |
| 0A000. e |                         | 控陣列天線。               |                                   | Electronically scanned array antennae are also    |
|          |                         |                      |                                   | known as electronically steerable array           |
|          |                         |                      |                                   | antennae.   |
|          | 1. 具有下列任一特性之資料處理        | 1. 具有下列任一特性之資料處理     | 1. Having data processing         | 1. Having data processing sub-systems and having  |
|          | 子系統:                    | 子系統:                 | sub-systems and having any of the | any of the following:                             |
|          | 1. 在任何天線旋轉下,具有"自        | 1. 在任何天線旋轉下,具有`自     | following:                        | 1. 'Automatic target tracking' providing, at any  |
|          | 動目標追蹤"能力,且其預測目標         | 動目標追蹤 ´能力,且其預測目標     | 1. "Automatic target tracking"    | antenna rotation, the predicted target position   |
|          | 位置超越下一天線光束途徑出現          | 位置超越下一天線光束途徑出現       | providing, at any antenna         | beyond the time of the next antenna beam passage; |
|          | 時間;或                    | 時間;或                 | rotation, the predicted target    | or  |
|          | 註解:6A008.1.1.不管制飛航交通    | 註解:6A008.1.1.不管制飛航交通 | position beyond the time of the   | Note: 6A008.1.1. does not control conflict alert  |
|          | 管制(ATC)系統之衝突警報能         | 管制(ATC)系統之衝突警報能      | next antenna beam passage; or     | capability in ATC systems, or 'marine radar'.     |
| 6A008. 1 | 力、或`船用雷達´。              | 力、或`船用雷達´。           | Note: 6A008.1.1. does not control | Technical Note:                                   |
|          | 2. 刪除;                  | 技術註解:                | conflict alert capability in ATC  | 'Automatic target tracking' is a processing       |
|          | 3. 删除;                  | "自動目標追蹤" 乃一種處理技      | systems, or 'marine radar'.       | technique that automatically determines and       |
|          | 4. 在6秒鐘之內,可由2個或以        | 術,可自動決定並提供目標最可能      | 2. Not used;                      | provides as output an extrapolated value of the   |
|          | 上"地理分散"雷達感測器提供重         | 的即時位置之推測值。           | 3. Not used;                      | most probable position of the target in real      |
|          | 疊與關聯建立,或融合目標資料之         | 2. 刪除;               | 4. Configured to provide          | time.   |
|          | 組態設定,使其感測器能提升整體         | 3. 刪除;               | superposition and correlation, or | 2. Not used;                                      |
|          | 性能,超過6A008.f.或6A008.i.所 | 4. 在6秒鐘之內,可由2個或以     | fusion, of target data within six | 3. Not used;                                      |
|          | 述之單一感測器性能。              | 上`地理分散´雷達感測器提供       | seconds from two or more          | 4. Configured to provide superposition and        |

| 修正條目                 | 現行內容                      | 擬修正/新增內容                  | 現行內容英譯                              | 擬修正/新增內容英譯  |
|----------------------|---------------------------|---------------------------|-------------------------------------|---|
|                      | 說明:參照軍用貨品管制。              | 重疊與關聯建立,或融合目標資料           | "geographically dispersed" radar    | correlation, or fusion, of target data within six |
|                      | 註解:6A008.1.4.不管制用於`船      | 之組態設定,使其感測器能提升整           | sensors to improve the aggregate    | seconds from two or more 'geographically          |
|                      | 舶交通服務 之系統、設備及零            | 體性能,超過6A008.f.或6A008.i.   | performance beyond that of any      | dispersed radar sensors to improve the            |
|                      | 件。                        | 中所述之單一感測器性能。              | single sensor specified by          | aggregate performance beyond that of any single   |
|                      |                           | 技術註解:                     | 6A008.f. or 6A008.i.                | sensor specified in 6A008.f. or 6A008.i.          |
|                      |                           | "地理分散"指感應器相對位置在           | N.B. See also Military Goods        | Technical Note:                                   |
|                      |                           | 任一方向之距離均大於過1,500公         | Controls.                           | Sensors are considered 'geographically            |
|                      |                           | 尺。活動式感應器通常被視為"地           | Note: 6A008.1.4. does not control   | dispersed when each location is distant from any  |
|                      |                           | 理分散"。                     | systems, equipment and assemblies   | other more than 1 500 m in any direction. Mobile  |
|                      |                           |                           | used for 'vessel traffic service'.  | sensors are always considered 'geographically     |
|                      |                           |                           |                                     | dispersed'.                                       |
|                      | 註解: 6A108.a.包括下列各項:       | 註解: 6A108.a.包括下列各項:       | Note: 6A108.a. includes the         | Note: 6A108.a. includes the following:            |
|                      | a. 地形等高線繪圖設備;             | a. 地形等高線繪圖設備;             | following:                          | a. Terrain contour mapping equipment;             |
|                      | b. 影像感應設備;                | b. 景象繪圖及關聯比對(數位及類         | a. Terrain contour mapping          | b. Scene mapping and correlation (both digital    |
|                      | c. 景象繪圖及關聯比對(數位及類         | 比)設備;                     | equipment;                          | and analogue) equipment;                          |
| 6A108 註解             | 比)設備;                     | c. 都卜勒導航雷達設備;             | b. Imaging sensor equipment;        | c. Doppler navigation radar equipment;            |
| UN100 <del>江</del> 件 | d. 都卜勒導航雷達設備。             | d. 被動干涉儀設備;               | c. Scene mapping and correlation    | d. Passive interferometer equipment;              |
|                      |                           | e. 影像感應設備(主動式及被動          | (both digital and analogue)         | e. Imaging sensor equipment (both active and      |
|                      |                           | 式)。                       | equipment;                          | passive).   |
|                      |                           |                           | d. Doppler navigation radar         |   |
|                      |                           |                           | equipment.                          |   |
|                      | 註解: 6A203.a.至 6A203.c.不管制 | 註解: 6A203.a.至 6A203.c.不管制 | Note: 6A203.a. to 6A203.c. does not | Note: 6A203.a. to 6A203.c. does not control       |
| 6A203 註解             | 控制照相機或影像元件,其硬體、           | 控制照相機或影像元件,其硬體、           | control cameras or imaging devices  | cameras or imaging devices if they have hardware, |
|                      | "軟體"或"技術"限制其性能低           | "軟體"或"技術"限制其性能低           | if they have hardware, "software"   | "software" or "technology" constraints that       |

| 修正條目     | 現行內容                   | 擬修正/新增內容                        | 現行內容英譯                             | 擬修正/新增內容英譯  |
|----------|------------------------|---------------------------------|------------------------------------|---|
|          | 於上述規範,符合下列任一特性:        | 於如後規範,符合下列任一特性:                 | or "technology" constraints that   | limit the performance to less than that specified |
|          |                        |                                 | limit the performance to less than | below, provided they meet any of the following:   |
|          |                        |                                 | that specified above, provided     |   |
|          |                        |                                 | they meet any of the following:    |   |
|          | d. 脈衝二氧化碳 "雷射器",具      | d. 脈衝二氧化碳(CO <sub>2</sub> ) "雷射 | d. Pulsed carbon dioxide "lasers"  | d. Pulsed carbon dioxide (CO 2) "lasers" having   |
| 6A205. d | 有下列所有特性:               | 器",具有下列所有特性:                    | having all of the following        | all of the following characteristics:             |
|          |                        |                                 | characteristics:                   |   |
|          | g. 未由 6A005.d.2.規範之一氧化 | g. 未由 6A005.d.2.規範之一氧化          | g. Pulsed carbon monoxide lasers,  | g. Pulsed carbon monoxide (CO) "lasers", other    |
| 6A205. g | 碳雷射,具下列所有特性:           | 碳(CO)雷射,具下列所有特性:                | other than those specified in      | than those specified in 6A005.d.2., having all    |
| 0AZ05. g |                        |                                 | 6A005.d.2., having all of the      | of the following:                                 |
|          |                        |                                 | following:                         |   |
|          | 2. 為設計或"生產"天線罩之"軟      | 2. 為設計或"生產"天線罩之"軟               | 2. "Software" for the design or    | 2. "Software" for the design or "production" of   |
|          | 體",具有下列所有特性:           | 體"具有下列所有特性:                     | "production" of radomes and having | radomes having all of the following:              |
|          | a. 特別設計為保護 6A008.e.所述  | a. 特別設計為保護 6A008.e.所述           | all of the following:              | a. Specially designed to protect the              |
| 6D003. h | 之"電子操控相位陣列天線";及        | 之電子操控相位陣列天線;及                   | a. Specially designed to protect   | electronically scanned array antennae specified   |
|          |                        |                                 | the "electronically steerable      | in 6A008.e.; and                                  |
|          |                        |                                 | phased array antennae" specified   |   |
|          |                        |                                 | in 6A008.e.; and                   |   |
|          | 7A006 工作頻率為 4.2 至 4.4  | 7A006 工作頻率為 4.2 至 4.4           | 7A006 Airborne altimeters          | 7A006 Airborne altimeters operating at            |
|          | GHz(含)以外操作之航空高度計,      | GHz(含)以外操作之航空高度計,               | operating at frequencies other     | frequencies other than 4,2 to 4,4 GHz inclusive   |
| 7A006    | 具下列任一特性:               | 具下列任一特性:                        | than 4,2 to 4,4 GHz inclusive and  | and having any of the following:                  |
| IAUUU    | 說明:參照 7A106。           | 說明:參照 7A106。                    | having any of the following:       | N. B. SEE ALSO 7A106.                             |
|          | a. "功率管理";或            | a. `功率管理´;或                     | N. B. SEE ALSO 7A106.              | a. 'Power management'; or                         |
|          | b. 使用相位偏移調變。           | b. 使用相位偏移調變。                    | a. "Power management"; or          | b. Using phase shift key modulation.              |

| 修正條目     | 現行內容                     | 擬修正/新增內容                  | 現行內容英譯                             | 擬修正/新增內容英譯  |
|----------|--------------------------|---------------------------|------------------------------------|---|
| <u> </u> |                          | 技術註解:                     | b. Using phase shift key           | Technical Note:                                   |
| <u> </u> |                          | "功率管理"指改變高度計訊號之           | modulation.                        | 'Power management' is changing the transmitted    |
| <u> </u> |                          | 傳輸功率,以致使"航空器"高度           |                                    | power of the altimeter signal so that received    |
| <u> </u> |                          | 之接收功率總是在決定高度之最            |                                    | power at the "aircraft" altitude is always at the |
|          |                          | 小需求。                      |                                    | minimum necessary to determine the altitude.      |
| <u> </u> | 7A105 除 7A005 所述外之全球     | 7A105 除7A005所述外之`衛        | 7A105 Receiving equipment for      | 7A105 Receiving equipment for 'navigation         |
| <u> </u> | 衛星導航系統(GNSS,例如:          | 星導航系統 一接收設備, 具下列任         | Global Navigation Satellite        | satellite systems', other than those specified    |
| <u> </u> | GPS、GLONASS 或 Galileo)接收 | 一特性,及特別設計之零件:             | Systems (GNSS; e.g. GPS, GLONASS,  | in 7A005, having any of the following             |
| <u> </u> | 設備,具下列任一特性,及特別設          | a. 設計或修改為用於 9A004 所述      | or Galileo), other than those      | characteristics, and specially designed           |
| <u> </u> | 計之零件:                    | 之太空發射載具、9A104 所述之探        | specified in 7A005, having any of  | components therefor:                              |
| <u> </u> | a. 設計或修改為用於 9A004 所述     | 空火箭或 9A012 或 9A112.a.所述   | the following characteristics, and | a. Designed or modified for use in space launch   |
| <u> </u> | 之太空發射載具、9A104 所述之探       | 之無人飛行載具;或                 | specially designed components      | vehicles specified in 9A004, sounding rockets     |
| <u> </u> | 空火箭或 9A012 或 9A112.a.所述  | b. 設計或修改為航空應用,且具          | therefor:                          | specified in 9A104 or unmanned aerial vehicles    |
| <u> </u> | 之無人飛行載具;或                | 下列任一特性:                   | a. Designed or modified for use in | specified in 9A012 or 9A112.a; or                 |
| 7A105    | b. 設計或修改為航空應用,且具         | 1. 可於速度超過 600 m/s 下提供     | space launch vehicles specified in | b. Designed or modified for airborne              |
| <u> </u> | 下列任一特性:                  | 導航資訊;                     | 9A004, sounding rockets specified  | applications and having any of the following:     |
| <u> </u> | 1. 可於速度超過 600 m/s 下提供    | 2. 使用為軍事或政府用而設計或          | in 9A104 or unmanned aerial        | 1. Capable of providing navigation information    |
| <u> </u> | 導航資訊;                    | 修改之解密技術,以取得`衛星導           | vehicles specified in 9A012 or     | at speeds in excess of 600 m/s;                   |
| <u> </u> | 2. 使用為軍事或政府用而設計或         | 航系統 保密訊號/資料;或             | 9A112.a; or                        | 2. Employing decryption, designed or modified     |
| <u> </u> | 修改之解密技術,以取得 GNSS         | 3. 特別設計使用反干擾裝置(例如         | b. Designed or modified for        | for military or governmental services, to gain    |
| <u> </u> | 保密訊號/資料;或                | 零向調轉(零點可控)天線或電子           | airborne applications and having   | access to a 'navigation satellite system'         |
|          | 3. 特別設計使用反干擾裝置(例如        | 式操縱方向性天線)於主動或被動           | any of the following:              | secured signal/data; or                           |
| ļ        | 零向調轉(零點可控)天線或電子          | 反制環境下運作。                  | 1. Capable of providing navigation | 3. Being specially designed to employ anti-jam    |
|          | 式操縱方向性天線)於主動或被動          | 註解:7A105.b.2.及7A105.b.3.不 | information at speeds in excess of | features (e.g. null steering antenna or           |

| 修正條目     | 現行內容                       | 擬修正/新增內容               | 現行內容英譯                                 | 擬修正/新增內容英譯   |
|----------|----------------------------|------------------------|--|--|
|          | 反制環境下運作。                   | 管制為商業、民用或`人命安全´        | 600 m/s;                               | electronically steerable antenna) to function in   |
|          | 註解:7A105.b.2.及 7A105.b.3.不 | (例如資料完整性、飛行安全)用途       | 2. Employing decryption, designed      | an environment of active or passive                |
|          | 管制為商業、民用或`人命安全´            | 之`衛星導航系統′服務而設計         | or modified for military or            | countermeasures.                                   |
|          | (例如資料完整性、飛行安全)用途           | 之設備。                   | governmental services, to gain         | Note: 7A105. b. 2. and 7A105. b. 3. do not control |
|          | 之 GNSS 服務而設計之設備。           | 技術註解:                  | access to GNSS secured                 | equipment designed for commercial, civil or        |
|          |                            | 7A105 中之`衛星導航系統´包      | signal/data; or                        | 'Safety of Life' (e.g., data integrity, flight     |
|          |                            | 括全球衛星導航系統(GNSS,例如      | 3. Being specially designed to         | safety)'navigation satellite system' services.     |
|          |                            | GPS、GLONASS、Galileo 或  | employ anti-jam features (e.g.         | Technical Note:                                    |
|          |                            | BeiDou)與區域衛星導航系統       | null steering antenna or               | In 7A105, 'navigation satellite system' includes   |
|          |                            | (RNSS,例如 NavIC、QZSS)。  | electronically steerable antenna)      | Global Navigation Satellite Systems (GNSS; e.g.    |
|          |                            |                        | to function in an environment of       | GPS, GLONASS, Galileo or BeiDou) and Regional      |
|          |                            |                        | active or passive countermeasures.     | Navigation Satellite Systems (RNSS; e.g. NavIC,    |
|          |                            |                        | Note: 7A105. b. 2. and 7A105. b. 3. do | QZSS).   |
|          |                            |                        | not control equipment designed for     |  |
|          |                            |                        | commercial, civil or 'Safety of        |  |
|          |                            |                        | Life' (e.g., data integrity,           |  |
|          |                            |                        | flight safety) GNSS services.          |  |
|          | 註解:7A115 包括下列設備之感應         | 註解:7A105、7A106 與 7A115 | Note: 7A115 includes sensors for       | Note: Equipment specified in 7A105, 7A106, and     |
|          | 哭:                         | 中所述之設備,包括下列設備:         | the following equipment:               | 7A115 includes the following:                      |
|          | a. 地形等高線繪圖設備;              | a. 地形等高線繪圖設備;          | a. Terrain contour mapping             | a. Terrain contour mapping equipment;              |
| 7A115 註解 | b. 影像感應器設備(主動式及被動          | b. 景象繪圖及關聯比對(數位及類      | equipment;                             | b. Scene mapping and correlation (both digital     |
|          | 式);                        | 比)設備;                  | b. Imaging sensor equipment (both      | and analogue) equipment;                           |
|          | c. 被動式干擾儀設備。               | c. 都卜勒導航雷達設備;          | active and passive);                   | c. Doppler navigation radar equipment;             |
|          |                            | d. 被動干涉儀設備;            | c. Passive interferometer              | d. Passive interferometer equipment;               |

| 修正條目     | 現行內容              | 擬修正/新增內容          | 現行內容英譯                            | 擬修正/新增內容英譯                                       |
|----------|-------------------|-------------------|-----------------------------------|--|
|          |                   | e. 影像感應設備(主動式及被動  | equipment.                        | e. Imaging sensor equipment (both active and     |
|          |                   | 式)。               |                                   | passive).  |
|          | 無                 | 註解:針對將載人航空器改裝成為   | _                                 | Note: For conversion of manned aircraft to       |
|          |                   | "飛彈"操作者,7A116 包括系 |                                   | operate as "missiles", 7A116 includes the        |
| 7A116 註解 |                   | 統、設備與閥門設計或改裝,其可   |                                   | systems, equipment and valves designed or        |
|          |                   | 使載人航空器如同無人飛行載具    |                                   | modified to enable operation of manned aircraft  |
|          |                   | 一般運作。             |                                   | as unmanned aerial vehicles.                     |
|          | 5. 特別設計為"主飛行控制"之  | 5. 特別設計為`主飛行控制´之  | 5. Electric actuators (i.e.,      | 5. Electric actuators (i.e., electromechanical,  |
|          | 電力致動器(亦即,電力機械致動   | 電力致動器(亦即,電力機械致動   | electromechanical,                | electrohydrostatic and integrated actuator       |
|          | 器、電力流體靜力致動器與整合致   | 器、電力流體靜力致動器與整合致   | electrohydrostatic and integrated | package) specially designed for 'primary flight  |
|          | 動器包裝);            | 動器包裝);            | actuator package) specially       | control';  |
|          | 6. 特別設計為執行 "主動飛行控 | 技術註解:             | designed for "primary flight      | Technical Note:                                  |
|          | 制系統"之"飛行控制光學感應器   | `主飛行控制´指使用力/力矩產   | control";                         | 'Primary flight control' is "aircraft" stability |
|          | 陣列";              | 生器之"航空器"之穩定或操控,   | 6. "Flight control optical sensor | or manoeuvring control using force/moment        |
|          |                   | 即空氣動力控制表面或推進力向    | array" specially designed for     | generators, i.e. aerodynamic control surfaces or |
| 7E004. a |                   | 里。                | implementing "active flight       | propulsive thrust vectoring.                     |
|          |                   | 6. 特別設計為執行 "主動飛行控 | control systems"; or              | 6. 'Flight control optical sensor array'         |
|          |                   | 制系統"之`飛行控制光學感應器   |                                   | specially designed for implementing "active      |
|          |                   | 陣列´;              |                                   | flight control systems"; or                      |
|          |                   | 技術註解:             |                                   | Technical Note:                                  |
|          |                   | `飛行控制光學感應器陣列´指    |                                   | A 'flight control optical sensor array' is a     |
|          |                   | 由光學感測器分佈而形成之網     |                                   | network of distributed optical sensors, using    |
|          |                   | 路,使用"雷射"光束提供即時飛   |                                   | "laser" beams, to provide real-time flight       |
|          |                   | 行控制資料於機上處理。       |                                   | control data for on-board processing.            |

| 修正條目        | 現行內容                     | 擬修正/新增內容          | 現行內容英譯                               | 擬修正/新增內容英譯                                       |
|-------------|--------------------------|-------------------|--------------------------------------|--|
|             | 註解:7E004.b.5.不管制:        | 註解:7E004.b.5.不管制: | Note: 7E004. b. 5. does not control: | Note: 7E004.b.5. does not control:               |
|             | a. 將數位飛行控制、導航及推進         | a. 將數位飛行控制、導航及推進  | a. "Technology" for integration of   | a. "Technology" for integration of digital       |
| 7E004. b. 5 | 控制資料整合成一 "最佳飛行路          | 控制資料整合成一`飛行路徑最    | digital flight control, navigation   | flight control, navigation and propulsion        |
| 註解          | 徑"的數位飛行管理系統之"技           | 佳化´的數位飛行管理系統之"技   | and propulsion control data, into    | control data, into a digital flight management   |
|             | 術";                      | 術";               | a digital flight management system   | system for 'flight path optimisation';           |
|             |                          |                   | for "flight path optimisation";      |  |
|             | 無                        | 技術註解:             | _                                    | Technical Note:                                  |
|             |                          | `飛行路徑最佳化´指由4度空    |                                      | 'Flight path optimisation' is a procedure that   |
| 7E004. b. 5 |                          | 間(空間與時間)期望之軌跡達到   |                                      | minimises deviations from a four-dimensional     |
| 技術註解        |                          | 最小偏差,以最大性能或效果完成   |                                      | (space and time) desired trajectory based on     |
|             |                          | 任務的程序。            |                                      | maximising performance or effectiveness for      |
|             |                          |                   |                                      | mission tasks.                                   |
|             | 3. 用於使用個別翼片控制之系          | 3. 用於使用個別翼片控制之系   | 3. Rotor blades incorporating        | 3. Rotor blades incorporating 'variable geometry |
|             | 統,包含"可變幾何機翼"旋翼。          | 統,包含`可變幾何機翼´旋翼。   | "variable geometry airfoils", for    | airfoils', for use in systems using individual   |
|             |                          | 技術註解:             | use in systems using individual      | blade control.                                   |
| 7E004. c. 3 |                          | `可變幾何機翼`指使用後緣襟    | blade control.                       | Technical Note:                                  |
| 12004, C. 0 |                          | 翼或調整片、前緣襟翼或軸鼻翼,   |                                      | 'Variable geometry airfoils' use trailing edge   |
|             |                          | 其位置在飛行中可受控制。      |                                      | flaps or tabs, or leading edge slats or pivoted  |
|             |                          |                   |                                      | nose droop, the position of which can be         |
|             |                          |                   |                                      | controlled in flight.                            |
|             | 9A002 依照 ISO 標準,連續功率     | 9A002 設計使用液態燃料之   | 9A002 'Marine gas turbine engines'   | 9A002 'Marine gas turbine engines' designed to   |
| 9A002       | 額定為 24,245 kW 或以上,在功率    | `船用燃氣渦輪引擎´具下列所    | with an ISO standard continuous      | use liquid fuel and having all of the following, |
| 3/1002      | 範圍為 35 至 100 %時,特定燃料     | 有特性者,及其特別設計之組件及   | power rating of 24 245 kW or more    | and specially designed assemblies and components |
|             | 消耗不超過 0.219 kg/kWh 之 ` 船 | 零件:               | and a specific fuel consumption not  | therefor:  |

| 修正條目     | 現行內容              | 擬修正/新增內容                     | 現行內容英譯                               | 擬修正/新增內容英譯   |
|----------|-------------------|------------------------------|--------------------------------------|--|
|          | 用燃氣渦輪引擎 ,及其特別設計   | a. 依照ISO 3977-2:1997(或等效國    | exceeding 0, 219 kg/kWh in the power | a. Maximum continuous power when operating in  |
|          | 之組件及零件。           | 家標準),在"穩定狀態模式"時              | range from 35 to 100 %, and          | "steady state mode" at standard reference  |
|          | 註解: `船用燃氣渦輪引擎 ´一詞 | 最大連續功率為 24,245 kW 或以         | specially designed assemblies and    | conditions specified by ISO 3977-2:1997 (or  |
|          | 包括為船艦發電或推進而修改之    | 上;或                          | components therefor.                 | national equivalent) of 24 245 kW or more; and   |
|          | 工業用或航空用衍生之燃氣渦輪    | b. 使用液態燃料,在最大連續功             | Note: The term 'marine gas turbine   | b. 'Corrected specific fuel consumption' not   |
|          | 發動機。              | 率的35%時, `修正燃料消耗´             | engines' includes those              | exceeding 0,219 kg/kWh at 35 % of the maximum  |
|          |                   | 不超過 0.219 kg/ kWh。           | industrial, or aero-derivative,      | continuous power when using liquid fuel.   |
|          |                   | 註解: `船用燃氣渦輪引擎 ´一詞            | gas turbine engines adapted for a    | Note: The term 'marine gas turbine engines'  |
|          |                   | 包括為船艦發電或推進而修改之               | ship's electric power generation     | includes those industrial, or aero-derivative,   |
|          |                   | 工業用或航空用衍生之燃氣渦輪               | or propulsion.                       | gas turbine engines adapted for a ship's electric  |
|          |                   | 發動機。                         |                                      | power generation or propulsion.  |
|          |                   | 技術註解:                        |                                      | Technical Note:  |
|          |                   | 9A002 所述之`修正燃料消耗´            |                                      | For the purposes of $9A002$ , 'corrected specific  |
|          |                   | 指引擎校正至海運餾分液態燃                |                                      | fuel consumption is the specific fuel  |
|          |                   | 料,其淨能源熱值(即淨熱值)為              |                                      | consumption of the engine corrected to a marine  |
|          |                   | 42MJ/kg (ISO 3977-2:1997)時之燃 |                                      | distillate liquid fuel having a net specific   |
|          |                   | 料消耗率。                        |                                      | energy (i.e. net heating value) of 42MJ/kg (ISO  |
|          |                   |                              |                                      | 3977-2:1997).  |
|          | f.特別為"太空載具"設計之地面  | f.特別為"太空載具"設計之地面             | f. Terrestrial equipment specially   | f. Terrestrial equipment specially designed for  |
|          | 設備,如下:            | 設備,如下:                       | designed for "spacecraft", as        | "spacecraft", as follows:  |
| 9A004. f | 1.遙測與遙控設備;        | 1. 遙測與遙控設備,特別設計為             | follows:                             | 1. Telemetry and telecommand equipment specially $% \left( 1\right) =\left( 1\right) \left( 1$ |
| JAUU4. I | 2.模擬器。            | 下列任一資料處理功能:                  | 1. Telemetry and telecommand         | designed for any of the following data processing  |
|          |                   | a. 訊框同步與錯誤校正之遙測資             | equipment;                           | functions:   |
|          |                   | 訊處理,用於監控"太空載具本體"             | 2. Simulators.                       | a. Telemetry data processing of frame  |

| 修正條目  | 現行內容                  | 擬修正/新增內容               | 現行內容英譯                             | 擬修正/新增內容英譯                                       |
|-------|-----------------------|------------------------|------------------------------------|--|
|       |                       | 運作狀態(亦稱為健康及安全狀         |                                    | synchronisation and error corrections, for       |
|       |                       | 態);或                   |                                    | monitoring of operational status (also known as  |
|       |                       | b. 為格式化指令資料之資料處        |                                    | health and safe status) of the "spacecraft bus"; |
|       |                       | 理,其被送至"太空載具"以控制        |                                    | or   |
|       |                       | "太空載具本體";              |                                    | b. Command data processing for formatting        |
|       |                       | 2.模擬器特別設計用於"太空載        |                                    | command data being sent to the "spacecraft" to   |
|       |                       | 具"之`驗證操作程序′。           |                                    | control the "spacecraft bus";                    |
|       |                       | 技術註解:                  |                                    | 2. Simulators specially designed for             |
|       |                       | 9A004.f.2.所述之`驗證操作程    |                                    | 'verification of operational procedures' of      |
|       |                       | 序 為下列任一:               |                                    | "spacecraft".                                    |
|       |                       | 1. 確認指令序列;             |                                    | Technical Note:                                  |
|       |                       | 2. 訓練操作;               |                                    | For the purposes of 9A004.f.2., 'verification of |
|       |                       | 3. 操作演練;或              |                                    | operational procedures' is any of the following: |
|       |                       | 4. 操作分析。               |                                    | 1. Command sequence confirmation;                |
|       |                       |                        |                                    | 2. Operational training;                         |
|       |                       |                        |                                    | 3. Operational rehearsals; or                    |
|       |                       |                        |                                    | 4. Operational analysis.                         |
|       | 9A101 除 9A001 所述以外,渦輪 | 9A101 除 9A001 所述以外, 渦輪 | 9A101 Turbojet and turbofan        | 9A101 Turbojet and turbofan engines, other than  |
|       | 噴射發動機及渦輪風扇發動機如        | 噴射發動機及渦輪風扇發動機如         | engines, other than those          | those specified in 9A001, as follows;            |
|       | 下:                    | 下:                     | specified in 9A001, as follows;    | a. Engines having all of the following           |
| 9A101 | a. 具有下列 2 項特性之發動機:    | a. 具有下列所有特性之發動機:       | a. Engines having both of the      | characteristics:                                 |
|       | 1. `最大推力值´大於 400 N(在  | 1. `最大推力值´大於 400 N(在   | following characteristics:         | 1. 'Maximum thrust value' greater than 400 N     |
|       | 無裝配時達到此值),但不包括        | 無裝配時達到此值),但不包括         | 1. 'Maximum thrust value' greater  | (achieved un-installed) excluding civil          |
|       | `最大推力值`大於 8,890 N(在   | `最大推力值`大於 8,890 N(在    | than 400 N (achieved un-installed) | certified engines with a 'maximum thrust value'  |

| 修正條目  | 現行內容                     | 擬修正/新增內容                   | 現行內容英譯                              | 擬修正/新增內容英譯  |
|-------|--------------------------|----------------------------|-------------------------------------|---|
|       | 無裝配時達到此值),且經認證之          | 無裝配時達到此值),且經認證之            | excluding civil certified engines   | greater than 8 890 N (achieved un-installed), and |
|       | 民用發動機;及                  | 民用發動機;及                    | with a 'maximum thrust value'       | 2. Specific fuel consumption of 0,15 kg N -1      |
|       | 2. 燃油消耗比為 0.15 kg/N/h 或以 | 2. 燃油消耗比為 0.15 kg N-1 hr-1 | greater than 8 890 N (achieved      | hr -1 or less (at maximum continuous power at     |
|       | 下(海平面靜止狀態及使用 ICAO        | 或以下(在海平面靜止狀態下使用            | un-installed), and                  | sea level static conditions using the ICAO        |
|       | 標準大氣壓狀況下之最大連續功           | ICAO 標準大氣壓下之最大連續           | 2. Specific fuel consumption of     | standard atmosphere);                             |
|       | 率);                      | 功率);                       | 0,15 kg/N/hr or less (at maximum    | 3. 'Dry weight' less than 750 kg; and             |
|       | 技術註解:                    | 3. `乾重´小於 750 kg;及         | continuous power at sea level       | 4. 'First-stage rotor diameter' less than 1 m;    |
|       | 就 9A101.a.1.目的, `最大推力    | 4. `第一級轉子直徑´小於1m;          | static conditions using the ICAO    | Technical Notes:                                  |
|       | 值~為製造商對未安裝發動機展           | 技術註解:                      | standard atmosphere);               | 1. For the purpose of 9A101.a.1. 'maximum thrust  |
|       | 現之最大推力。民間認證之推力值          | 1.9A101.a.1.所述之 ~ 最大推力     | Technical Note:                     | value' is the manufacturer's demonstrated         |
|       | 將等於或小於製造商所證明之最           | 值~為在海平面靜止狀態下使用             | For the purpose of 9A101.a.1.       | maximum thrust for the engine type un-installed   |
|       | 大推力。                     | ICAO 標準大氣壓情況,製造商對          | 'maximum thrust value' is the       | at sea level static conditions using the ICAO     |
|       | b. 設計或修改用於"飛彈"或          | 未安裝發動機展現之最大推力。民            | manufacturer's demonstrated         | standard atmosphere. The civil type certified     |
|       | 9A012 或 9A112.a.所述之無人飛   | 間認證之推力值將等於或小於製             | maximum thrust for the engine type  | thrust value will be equal to or less than the    |
|       | 行載具之發動機。                 | 造商所證明之最大推力。                | un-installed. The civil type        | manufacturer's demonstrated maximum thrust for    |
|       |                          | 2. `乾重`指發動機不含液體(燃          | certified thrust value will be      | the engine type.                                  |
|       |                          | 料、液壓油、潤滑油等)的重量,            | equal or less than the              | 2. 'Dry weight' is the weight of the engine       |
|       |                          | 且不包括機艙(外殼)。                | manufacturer's demonstrated         | without fluids (fuel, hydraulic fluid, oil,       |
|       |                          | 3. `第一級轉子直徑`指發動機           | maximum thrust for the engine type. | etc.) and does not include the nacelle (housing). |
|       |                          | 第一階轉子的直徑,無論其為風扇            |                                     | 3. 'First-stage rotor diameter' is the diameter   |
|       |                          | 或壓縮機,由葉片尖端前緣處測             |                                     | of the first rotating stage of the engine,        |
|       |                          | 里。                         |                                     | whether a fan or compressor, measured at the      |
|       |                          |                            |                                     | leading edge of the blade tips.                   |
| 9A115 | 9A115 發射支援設備如下:          | 9A115 發射支援設備如下:            | 9A115 Launch support equipment as   | 9All5 Launch support equipment as follows:        |

| 修正條目  | 現行內容                       | 擬修正/新增內容                   | 現行內容英譯                             | 擬修正/新增內容英譯                                      |
|-------|----------------------------|----------------------------|------------------------------------|---|
|       | a. 用於處理、控制、啟動或發射,          | a. 用於處理、控制、啟動或發射,          | follows:                           | a. Apparatus and devices for handling, control, |
|       | 且設計或修改用於 9A004 所述之         | 且設計或修改用於 9A004 所述之         | a. Apparatus and devices for       | activation or launching, designed or modified   |
|       | 太空發射載具、9A104 所述之探空         | 太空發射載具、9A104所述之探空          | handling, control, activation or   | for space launch vehicles specified in 9A004,   |
|       | 火箭之儀器及裝置,或9A012或           | 火箭之儀器及裝置或`飛彈´;             | launching, designed or modified    | sounding rockets specified in 9A104 or          |
|       | 9A112.a.所述之無人飛行載具;         | 技術註解:                      | for space launch vehicles          | 'missiles';                                     |
|       | b. 用於運輸、處理、控制、啟動           | 9A115.a.所述之、飛彈、指射程         | specified in 9A004, sounding       | Technical Note:                                 |
|       | 或發射,且設計或修改用於9A004          | 或航程超過 300 km 之完整火箭系        | rockets specified in 9A104 or      | In 9A115.a. 'missile' means complete rocket     |
|       | 所述之太空發射載具或 9A104 所         | 統及無人飛行載具系統。                | unmanned aerial vehicles specified | systems and unmanned aerial vehicle systems     |
|       | 述之探空火箭之載具;                 | b. 用於運輸、處理、控制、啟動           | in 9A012 or 9A112.a.;              | capable of a range exceeding 300 km.            |
|       |                            | 或發射,且設計或修改用於9A004          | b. Vehicles for transport,         | b. Vehicles for transport, handling, control,   |
|       |                            | 所述之太空發射載具或 9A104 所         | handling, control, activation or   | activation or launching, designed or modified   |
|       |                            | 述之探空火箭之載具或`飛彈´;            | launching, designed or modified    | for space launch vehicles specified in 9A004,   |
|       |                            |                            | for space launch vehicles          | sounding rockets specified in 9A104 or          |
|       |                            |                            | specified in 9A004 or sounding     | "missiles".                                     |
|       |                            |                            | rockets specified in 9A104.        |   |
|       | 9D001 特別設計或修改用於 "開         | 9D001 未由 9D003 或 9D004 所   | 9D001 "Software" specially         | 9D001 "Software", not specified in 9D003 or     |
|       | 發"9A001 至 9A119、9B 或 9E003 | 管制,特別設計或修改用於"開發"           | designed or modified for the       | 9D004, specially designed or modified for the   |
| 9D001 | 所述之設備或"技術"之"軟體"。           | 9A001 至 9A119、9B 或 9E003 所 | "development" of equipment or      | "development" of equipment or "technology",     |
|       |                            | 述之設備或"技術"之"軟體"。            | "technology", specified in 9A001   | specified in 9A001 to 9A119, 9B or 9E003.       |
|       |                            |                            | to 9A119, 9B or 9E003.             |   |
|       | 9D002 特別設計或修改用於"生          | 9D002 未由 9D003 或 9D004 所   | 9D002 "Software" specially         | 9D002 "Software", not specified in 9D003 or     |
| 00000 | 產"9A001至9A119或9B所述之        | 管制,特別設計或修改用於"生產"           | designed or modified for the       | 9D004, specially designed or modified for the   |
| 9D002 | 設備之"軟體"。                   | 9A001至9A119或9B所述之設備        | "production" of equipment          | "production" of equipment specified in 9A001 to |
|       |                            | 之 "軟體"                     | specified in 9A001 to 9A119 or 9B. | 9A119 or 9B.                                    |

| 修正條目  | 現行內容             | 擬修正/新增內容                  | 現行內容英譯                              | 擬修正/新增內容英譯  |
|-------|------------------|---------------------------|-------------------------------------|---|
|       | 9D004 其他"軟體"如下:  | 9D004 其他"軟體"如下:           | 9D004 Other "software" as follows:  | 9D004 Other "software" as follows:                |
|       | a. 用為建立詳細的發動機氣流模 | a. 用為建立詳細的發動機氣流模          | a. 2D or 3D viscous "software",     | a. 2D or 3D viscous "software", validated with    |
|       | 式所需之風洞或飛行測試資料,驗  | 式所需之風洞或飛行測試資料,驗           | validated with wind tunnel or       | wind tunnel or flight test data required for      |
|       | 證之2維或3維黏性流體"軟體"; | 證之2維或3維黏性流體"軟體";          | flight test data required for       | detailed engine flow modelling;                   |
|       | b. 用於測試航空用燃氣渦輪發動 | b. 用於測試航空用燃氣渦輪發動          | detailed engine flow modelling;     | b. "Software" for testing aero gas turbine        |
|       | 機、組件或零件之"軟體",特別  | 機、組件或零件之"軟體",具下           | b. "Software" for testing aero gas  | engines, assemblies or components, having all of  |
|       | 設計為即時收集、簡化及分析資   | 列所有特性:                    | turbine engines, assemblies or      | the following:                                    |
|       | 料,且具回授控制能力,包括在測  | 1. 特別設計為測試下列任一者:          | components, specially designed to   | 1. Specially designed for testing any of the      |
|       | 試進行中,測試物件或測試條件之  | a. 航空用燃氣渦輪發動機、組件          | collect, reduce and analyse data in | following:  |
|       | 動態調整;            | 或零件,其含有 9E003.a.、9E003.h. | real time and capable of feedback   | a. Aero gas turbine engines, assemblies or        |
|       |                  | 或 9E003.i.所述之"技術";或       | control, including the dynamic      | components, incorporating "technology"            |
| 9D004 |                  | b. 為航空用燃氣渦輪發動機特別          | adjustment of test articles or test | specified in 9E003.a., 9E003.h. or 9E003.i.; or   |
| JD004 |                  | 設計之多級壓縮機,提供分流或主           | conditions, as the test is in       | b. Multi-stage compressors providing either       |
|       |                  | 流量,其含有 9E003.a.或 9E003.h. | progress;                           | bypass or core flow, specially designed for aero  |
|       |                  | 所述之"技術";或                 |                                     | gas turbine engines incorporating "technology"    |
|       |                  | 2. 特別設計為下列所有者:            |                                     | specified in 9E003.a. or 9E003.h.; and            |
|       |                  | a. 即時收集與處理資料;及            |                                     | 2. Specially designed for all of the following:   |
|       |                  | b. 在測試進行中具調整測試物件          |                                     | a. Acquisition and processing of data, in real    |
|       |                  | 或測試條件(例如溫度、壓力、流           |                                     | time; and   |
|       |                  | 速)之回授控制能力;                |                                     | b. Feedback control of the test article or test   |
|       |                  | 註解:9D004.b.不管制用於操作測       |                                     | conditions (e.g. temperature, pressure, flow      |
|       |                  | 試設施或操作者安全(例如超速停           |                                     | rate) while the test is in progress;              |
|       |                  | 機、火災偵測與抑制)之軟體,或           |                                     | Note: 9D004.b. does not control software for      |
|       |                  | 生產、維修或維護僅限於確認受測           |                                     | operation of the test facility or operator safety |

| 修正條目           | 現行內容                  | 擬修正/新增內容               | 現行內容英譯                              | 擬修正/新增內容英譯  |
|----------------|-----------------------|------------------------|-------------------------------------|---|
|                |                       | 項目正確組裝或維修之軟體。          |                                     | (e.g. overspeed shutdown, fire detection and      |
|                |                       |                        |                                     | suppression), or production, repair or            |
|                |                       |                        |                                     | maintenance acceptance-testing limited to         |
|                |                       |                        |                                     | determining if the item has been properly         |
|                |                       |                        |                                     | assembled or repaired.                            |
|                | 2. 、燃燒室出口溫度 為,當發      | 2. 、燃燒室出口溫度 ´ 為,當發     | 2. 'Combustor exit temperature' is  | 2. 'Combustor exit temperature' is the bulk       |
|                | 動機在`穩定狀態模式´下運轉        | 動機在"穩定狀態模式"下運轉至        | the bulk average gas path total     | average gas path total (stagnation) temperature   |
|                | 至認證之最大連續操作溫度時,燃       | 認證之最大連續操作溫度時,燃燒        | (stagnation) temperature between    | between the combustor exit plane and the leading  |
|                | 燒室出口平面與渦輪機進氣導向        | 室出口平面與渦輪機進氣導向葉         | the combustor exit plane and the    | edge of the turbine inlet guide vane (i.e.,       |
|                | 葉片尖端(即依照 SAE APR 755A | 片尖端(即依照 SAE APR 755A 所 | leading edge of the turbine inlet   | measured at engine station T40 as defined in SAE  |
| 9E003. a. 2. d | 所定義之 T40 發動機站量測)兩者    | 定義之 T40 發動機站量測)兩者間     | guide vane (i.e., measured at       | ARP 755A) when the engine is running in a "steady |
| 技術註解           | 間之主體平均氣流總(停滯)溫度。      | 之主體平均氣流總(停滯)溫度。        | engine station T40 as defined in    | state mode" of operation at the certificated      |
|                |                       |                        | SAE ARP 755A) when the engine is    | maximum continuous operating temperature.         |
|                |                       |                        | running in a 'steady state mode' of |   |
|                |                       |                        | operation at the certificated       |   |
|                |                       |                        | maximum continuous operating        |   |
|                |                       |                        | temperature.                        |   |
|                | 技術註解:                 | 技術註解:                  | Technical Notes:                    | Technical Note:                                   |
|                | 1. `燃氣路徑溫度` 為當發動      | `燃氣路徑溫度` 為當發動機在        | 1. 'Gas path temperature' is the    | 'Gas path temperature' is the bulk average gas    |
| 00000 0 5      | 機在`穩定狀態模式`下運轉至        | `穩定狀態模式`下運轉至經認         | bulk average gas path total         | path total (stagnation) temperature at the        |
| 9E003. a. 5    | 經認證或指定之最大連續操作溫        | 證或指定之最大連續操作溫度          | (stagnation) temperature at the     | leading edge plane of the turbine component when  |
| 技術註解           | 度時,渦輪機元件前緣平面之主體       | 時,渦輪機元件前緣平面之主體平        | leading edge plane of the turbine   | the engine is running in a "steady state mode"    |
|                | 平均氣流總(停滯)溫度。          | 均氣流總(停滯)溫度。            | component when the engine is        | of operation at the certificated or specified     |
|                | 2. `穩定狀態模式`定義為在發      |                        | running in a 'steady state mode'    | maximum continuous operating temperature.         |

| 修正條目             | 現行內容                 | 擬修正/新増內容             | 現行內容英譯                              | 擬修正/新增內容英譯                                     |
|------------------|----------------------|----------------------|-------------------------------------|--|
|                  | 動機進氣口四周空氣溫度和壓力       |                      | of operation at the certificated or |  |
|                  | 固定,推力/輸出比和每分鐘轉數      |                      | specified maximum continuous        |  |
|                  | 等發動機參數無明顯波動的情況       |                      | operating temperature.              |  |
|                  | 下之發動機操作。             |                      | 2. The term 'steady state mode'     |  |
|                  |                      |                      | defines engine operation            |  |
|                  |                      |                      | conditions, where the engine        |  |
|                  |                      |                      | parameters, such as thrust/power,   |  |
|                  |                      |                      | rpm and others, have no appreciable |  |
|                  |                      |                      | fluctuations, when the ambient air  |  |
|                  |                      |                      | temperature and pressure at the     |  |
|                  |                      |                      | engine inlet are constant.          |  |
|                  | 4. 製造 9E003.c.所述孔洞之技 | 4. 製造 9E003.c.所述孔洞之方 | 4. Techniques for manufacturing     | 4. Methods for manufacturing holes in 9E003.c. |
| 0E002 a #        | 術,包括"雷射"、水刀、電化學      | 法,包括"雷射"光束機械加工、      | holes in 9E003.c include "laser",   | include "laser" beam machining, water jet      |
| 9E003.c 技<br>術註解 | 加工(ECM)或放電加工(EDM)方   | 水刀機械加工、電化學加工(ECM)    | water jet, Electro-Chemical         | machining, Electro-Chemical Machining (ECM) or |
| 114 6土 月午        | 法。                   | 或放電加工(EDM)。          | Machining (ECM) or Electrical       | Electrical Discharge Machining (EDM).          |
|                  |                      |                      | Discharge Machining (EDM) methods.  |  |

## 第二項:一般軍用貨品清單修正對照表

| 修正條目      | 現行內容             | 擬修正/新增內容         | 現行內容英譯                            | 擬修正/新增內容英譯   |
|-----------|------------------|------------------|-----------------------------------|--|
| ML4.a 註解  | b. 飛彈火箭噴嘴及重返大氣層  | b. 飛彈或火箭噴嘴及重返大氣  | b. Missile rocket nozzles and     | b. Missile or rocket nozzles and re-entry vehicle  |
| ML4. a 計件 | 載具之機頭尖端。         | 層載具之機頭尖端。        | re-entry vehicle nosetips.        | nosetips.  |
|           | ML5 為軍事用途而特別設計之  | ML5 為軍事用途而特別設計之  | ML5 Fire control, and related     | ML5 Fire control, surveillance and warning         |
|           | 發射控制及相關之警報與警示設   | 發射控制、監控與警示設備、相   | alerting and warning equipment,   | equipment, and related systems, test and alignment |
|           | 備、相關之系統、測試及校準與   | 關之系統、測試及校準與反制設   | and related systems, test and     | and countermeasure equipment, as follows,          |
|           | 反制設備,如下所列,及為其特   | 備,如下所列,及為其特別設計   | alignment and countermeasure      | specially designed for military use, and specially |
|           | 別設計之零件與配件:       | 之零件與配件:          | equipment, as follows, specially  | designed components and accessories therefor:      |
|           | a. 武器瞄準具、轟炸模擬機、槍 | a. 武器瞄準具、轟炸模擬機、槍 | designed for military use, and    | a. Weapon sights, bombing computers, gun laying    |
|           | 砲鋪設設備及武器控制系統;    | 砲鋪設設備及武器控制系統;    | specially designed components and | equipment and weapon control systems;              |
|           | b. 目標擷取、指定、測距、監視 | b. 其他發射控制、監控與警示設 | accessories therefor:             | b. Other fire control, surveillance and warning    |
| ML5       | 或追蹤系統;偵測、數據結合、   | 備,與其相關之系統,如下:    | a. Weapon sights, bombing         | equipment, and related systems, as follows:        |
| MILO      | 辨識或辨認設備,及感應器集成   | 1. 目標擷取、指定、測距、監視 | computers, gun laying equipment   | 1. Target acquisition, designation,                |
|           | 設備;              | 或追蹤系統;           | and weapon control systems;       | range-finding, surveillance or tracking systems;   |
|           |                  | 2. 偵測、辨識或識別設備;   | b. Target acquisition,            | 2. Detection, recognition or identification        |
|           |                  | 3. 數據結合或感應器集成設備; | designation, range-finding,       | equipment;   |
|           |                  |                  | surveillance or tracking systems; | 3. Data fusion or sensor integration equipment;    |
|           |                  |                  | detection, data                   |  |
|           |                  |                  | fusion, recognition or            |  |
|           |                  |                  | identification equipment; and     |  |
|           |                  |                  | sensor integration equipment;     |  |
| ML6.a 註解  | 無                | 註解 1: ML6.a. 包括: | _                                 | Note 1 ML6.a. includes:                            |
| MLU. a 红胖 |                  | a. 坦克與其他軍用裝甲車輛與軍 |                                   | a. Tanks and other military armed vehicles and     |

| 修正條目      | 現行內容 | 擬修正/新増內容            | 現行內容英譯 | 擬修正/新增內容英譯   |
|-----------|------|---------------------|--------|--|
|           |      | 用車輛裝置有支架,可裝設 ML4    |        | military vehicles fitted with mountings for arms     |
|           |      | 所述用於鋪設或發射彈藥之武器      |        | or equipment for mine laying or the launching of     |
|           |      | 或設備;                |        | munitions specified by ML4;                          |
|           |      | b. 裝甲車輛;            |        | b. Armoured vehicles;                                |
|           |      | c. 兩棲與可涉深水車輛;       |        | c. Amphibious and deep water fording vehicles;       |
|           |      | d. 救援車輛、拖曳或運輸彈藥或    |        | d. Recovery vehicles and vehicles for towing or      |
|           |      | 武器系統及相關裝載處理設備之      |        | transporting ammunition or weapon systems and        |
|           |      | 車輛;                 |        | associated load handling equipment;                  |
|           |      | e. 拖車。              |        | e. Trailers.   |
|           |      | 註解 2:為受 ML6.a.管制之軍事 |        | Note 2 Modification of a ground vehicle for          |
|           |      | 用途而進行之地面車輛改裝,該      |        | military use specified by ML6.a. entails a           |
|           |      | 等改裝必須為結構、電氣或機械      |        | structural, electrical or mechanical change          |
|           |      | 上之改變,且該改變涉及1件或      |        | involving one or more components that are specially  |
|           |      | 以上為軍事用途而特別設計之零      |        | designed for military use. Such components           |
|           |      | 件。該等零件包括:           |        | include:   |
|           |      | a. 專門設計用於防彈用途的充氣    |        | a. Pneumatic tyre casings of a kind specially        |
|           |      | 輪胎外胎;               |        | designed to be bullet-proof;                         |
|           |      | b. 以裝甲保護重要部位 (例如:   |        | b. Armoured protection of vital parts (e.g. fuel     |
|           |      | 油箱或座艙);             |        | tanks or vehicle cabs);                              |
|           |      | c. 為武器之特別強化或裝設;     |        | c. Special reinforcements or mountings for           |
|           |      | d. 遮光照明。            |        | weapons;   |
|           |      |                     |        | d. Black-out lighting.                               |
| ML6.b.2 註 | 無    | 註解1:ML6不管制設計或改裝     | _      | Note 1 ML6 does not apply to civil vehicles designed |
| 解         |      | 用於運鈔或貴重物品之民用車       |        | or modified for transporting money or valuables.     |

| 修正條目           | 現行內容                       | 擬修正/新增內容                   | 現行內容英譯                             | 擬修正/新增內容英譯   |
|----------------|----------------------------|----------------------------|------------------------------------|--|
|                |                            | 輛。                         |                                    | Note 2 ML6. does not apply to vehicles that meet           |
|                |                            | 註解2:ML6不管制符合下列所            |                                    | all of the following;                                      |
|                |                            | 有特性之車輛:                    |                                    | a. Were manufactured before 1946;                          |
|                |                            | a. 於 1946 年之前製造;           |                                    | b. Do not have items specified by the EU Common            |
|                |                            | b. 不具有歐盟一般軍用貨品清單           |                                    | Military List and manufactured after 1945, except          |
|                |                            | 所指之項目及 1945 年後製造者,         |                                    | for reproductions of original components or                |
|                |                            | 除原始零件或配件之複製品以              |                                    | accessories for the vehicle; and                           |
|                |                            | 外;及                        |                                    | c. Do not incorporate weapons specified in ML1.,           |
|                |                            | c. 不包含 ML.1、ML.2 或 ML.4    |                                    | ML2. or ML4. unless they are inoperable and                |
|                |                            | 所述之武器,除非其武器失效及             |                                    | incapable of discharging a projectile.                     |
|                |                            | 卸除彈藥投射物。                   |                                    |  |
|                | 6. DADE(1,1-二胺基-2,2-二硝基    | 6. DADE(1,1-二胺基-2,2-二硝基    | 6. DADE                            | 6. DADE (1,1-diamino-2,2-dinitroethylene, FOX-7)           |
| ML8. a. 6      | 乙烯、FOX7)(CAS 145250-81-3); | 乙烯、FOX-7)(CAS              | (1, 1-diamino-2, 2-dinitroethylen  | (CAS 145250-81-3);   |
|                |                            | 145250-81-3);              | e, F0X7) (CAS 145250-81-3);        |  |
|                | 33. 未列於 ML8.a.之別處列出之       | 33. 未列於 ML8.a.之別處列出之       | 33. Explosives not listed          | 33. "Explosives" not listed elsewhere in ML8.a. and        |
| ML8. a. 33     | 炸藥且具下列任一特性:                | "炸藥"且具下列任一特性:              | elsewhere in ML8.a. and having any | having any of the following:                               |
|                |                            |                            | of the following:                  |  |
| ML8. a. 43     | 無                          | 43. TKX-50 (5,5'-聯四唑-1,1'- | -                                  | 43. TKX-50 (Dihydroxylammonium                             |
| MLO, a, 40     |                            | 羥胺鹽);                      |                                    | 5, 5'-bistetrazole-1, 1'-diolate);                         |
| ML8.c.5 註      | 註解1:ML8.c.5.管制之`爆炸         | 註解1:ML8.c.5.管制之"炸藥"        | Note 1 ML8.c.5. applies to         | Note 1 ML8.c.5. applies to "explosives" and fuels, whether |
|                | 物「與燃料,無論其金屬或合金             | 與燃料,無論其金屬或合金是否             | "explosives" and fuels, whether    | or not the metals or alloys are encapsulated in aluminium, |
| MLO.C.J 註<br>解 | 是否包覆於鋁、鎂、鋯,或鈹。             | 包覆於鋁、鎂、鋯,或鈹。               | or not the metals or alloys are    | magnesium, zirconium, or beryllium.                        |
| <b>丹午</b>      |                            |                            | encapsulated in aluminium,         |  |
|                |                            |                            | magnesium, zirconium, or           |  |

| 修正條目         | 現行內容                    | 擬修正/新増內容                | 現行內容英譯                         | 擬修正/新增內容英譯  |
|--------------|-------------------------|-------------------------|--------------------------------|---|
|              |                         |                         | beryllium.                     |   |
| ML8. c. 12 註 | 無                       | 註解:ML8.c.12.包括鋁熱劑。      | -                              | Note ML8.c.12. includes thermites.                    |
| 解            |                         |                         |                                |   |
| ML9.a 註解     | 無                       | 註解:ML9.a.1 包括特別設計或改     | _                              | Note ML9.a.1. includes vehicles specially designed or |
| ML9. a 計件    |                         | 裝為輸送潛水員之載具。             |                                | modified for the delivery of divers.                  |
|              | 2. ML9. a. 1. 所述以外之水面船  | 2. 未列於 ML9. a. 1. 所述之水面 | 2. Surface vessels, other than | 2. Surface vessels, not specified in                  |
|              | 隻,具下列任一項固定於或納入          | 船隻,在船隻中固定於或納入下          | those specified in ML9.a.1.,   | ML9.a.1., having any of the following, fixed          |
| ML. 9. a. 2  | 船隻中:                    | 列任一項目:                  | having any of the following,   | or integrated into the vessel:                        |
|              |                         |                         | fixed or integrated into the   |   |
|              |                         |                         | vessel:                        |   |
|              | 3. 為軍事用途而特別設計之非         | 3. 柴油引擎具有下列所有特性:        | 3. Non-magnetic diesel engines | 3. Diesel engines having all of the following:        |
|              | 磁性柴油引擎,具有下列所有特          | a. 功率輸出為 37.3 kW(50 馬力) | having all of the following:   | a. Power output of 37,3 kW (50 hp) or more;           |
|              | 性:                      | 或以上;及                   | a. Power output of 37,3 kW (50 | and   |
|              | a. 功率輸出為 37.3 kW(50 馬力) | b. `非磁性成分´超過總重量         | hp) or more; and               | b. 'Non-magnetic' content in excess of 75 %           |
| ML. 9. b. 3  | 或以上;及                   | ≥ 75 %;                 | b. Non-magnetic content in     | of total mass;  |
|              | b. 非磁性成分超過總重量之75        | 技術註解:                   | excess of 75 % of total mass;  | Technical Note  |
|              | <b>%</b> ;              | ML9.b.3之`非磁性成分´指相       |                                | For the purpose of ML9.b.3., 'non-magnetic'           |
|              |                         | 對磁導率小於2。                |                                | means the relative permeability is less than          |
|              |                         |                         |                                | 2.  |
|              | 無                       | h. 海軍用核子設備與相關設備         | _                              | h. Naval nuclear equipment and related                |
|              |                         | 及零件,如下:                 |                                | equipment and components, as follows:                 |
| ML. 9. h     |                         | 1. 核能發電設備或推進設備,特        |                                | 1. Nuclear power generating equipment or              |
|              |                         | 別設計用於 ML. 9. a. 所述之船    |                                | propulsion equipment, specially designed for          |
|              |                         | 隻,與其特別設計或`改裝´用          |                                | vessels specified in ML9.a. and components            |

| 修正條目      | 現行內容                     | 擬修正/新增內容                 | 現行內容英譯                         | 擬修正/新增內容英譯                                     |
|-----------|--------------------------|--------------------------|--------------------------------|--|
|           |                          | 於軍事用途之零件;                |                                | therefor specially designed or 'modified' for  |
|           |                          | 技術註解:                    |                                | military use.                                  |
|           |                          | ML9. h. 1 之 ` 改裝 ´ 為任何結  |                                | Technical Note                                 |
|           |                          | 構、電氣、機械或其他變更,其           |                                | For the purpose of ML9.h.1., 'modified' means  |
|           |                          | 可使非軍事用途之項目具有與特           |                                | any structural, electrical, mechanical, or     |
|           |                          | 別設計用於軍事用途者相同之能           |                                | other change that provides a non-military      |
|           |                          | カ。                       |                                | item with military capabilities equivalent to  |
|           |                          | 註解:ML9.h.1.包括"核子反應       |                                | an item which is specially designed for        |
|           |                          | 器"。                      |                                | military use.                                  |
|           |                          |                          |                                | Note ML9.h.1. includes "nuclear reactors".     |
|           | 註解 5: ML10. a. 不管制 "航空器" | 註解 5: ML10. a. 不管制 "航空器" | Note 5 ML10.a. does not apply  | Note 5 ML10.a. does not apply to "aircraft"    |
| ML10 註解 5 | 具下列所有特性:                 | 或"比空氣輕載具"具下列所有           | to "aircraft" that meet all of | or "lighter-than-air-vehicles" that meet all   |
|           |                          | 特性:                      | the following:                 | of the following:                              |
|           | 無                        | 註解 6:ML10.d.不管制在 1946    | _                              | Note 6 ML10.d. does not apply to propulsion    |
| ML10 註解 6 |                          | 年之前首次製造之航空發動機。           |                                | aero-engines that were first manufactured      |
|           |                          |                          |                                | before 1946.                                   |
|           | b. 全球導航衛星系統(GNSS)之       | b. "衛星導航系統"之干擾設備         | b. Global Navigation Satellite | b. "Satellite navigation system" jamming       |
|           | 干擾設備及特別為其設計之零            | 及特別為其設計之零件;              | Systems (GNSS) jamming         | equipment and specially designed components    |
| ML11.b    | 件;                       |                          | equipment and specially        | therefor;                                      |
|           |                          |                          | designed components            |  |
|           |                          |                          | therefor;                      |  |
|           | 註解 4:ML13. 所述為廢彈處理人      | 註解 4: ML13. c. 所述為廢彈處理   | Note 4 The only helmets        | Note 4 The only helmets specially designed for |
| ML13 註解 4 | 員而特別設計之專用頭盔,特別           | 人員而特別設計之專用頭盔,特           | specially designed for bomb    | bomb disposal personnel that are specified by  |
|           | 設計為軍事用途者。                | 別設計為軍事用途者。               | disposal personnel that are    | ML13.c. are those specially designed for       |

| 修正條目    | 現行內容            | 擬修正/新増內容           | 現行內容英譯                         | 擬修正/新增內容英譯                                    |
|---------|-----------------|--------------------|--------------------------------|---|
|         |                 |                    | specified by ML13. are those   | military use.                                 |
|         |                 |                    | specially designed for         |   |
|         |                 |                    | military use.                  |   |
|         | g. 為軍用而特別設計之核能發 | g. 未於其他處列入,為軍用而特   | g. Nuclear power generating    | g. Nuclear power generating equipment or      |
|         | 電設備或推進設備,包括 被子  | 別設計之核能發電設備或推進設     | equipment or propulsion        | propulsion equipment, not specified           |
|         | 反應器 , 及其為軍用而特別設 | 備,及其為軍用而特別設計或改     | equipment, including "nuclear  | elsewhere, specially designed for military    |
| WI 17   | 計或改裝之零件;        | 裝之零件;              | reactors", specially designed  | use and components therefor specially         |
| ML17. g |                 | 註解:ML17.g. 包括"核子反應 | for military use and           | designed or 'modified' for military use;      |
|         |                 | 器"。                | components therefor specially  | Note ML17.g. includes "nuclear reactors".     |
|         |                 |                    | designed or 'modified' for     |   |
|         |                 |                    | military use;                  |   |
|         | h. 除歐盟一般軍用貨品清單所 | h. 未列於一般軍用貨品清單管    | h. Equipment and material,     | h. Equipment and material, coated or treated  |
|         | 管制項目以外,為訊號抑制之塗  | 制項目,為訊號抑制之塗佈或處     | coated or treated for          | for signature suppression, specially          |
|         | 佈或處理而特別設計之軍用設備  | 理而特別設計之軍用設備與材      | signature suppression,         | designed for military use, not specified      |
| ML17.h  | 與材料;            | 料;                 | specially designed for         | elsewhere in the EU Common Military List;     |
|         |                 |                    | military use, other than those |   |
|         |                 |                    | specified elsewhere in the EU  |   |
|         |                 |                    | Common Military List;          |   |
|         | i. 為軍用`核子反應器´而特 | i. 為軍用"核子反應器"而特別   | i. Simulators specially        | i. Simulators specially designed for military |
| ML17. i | 別設計之模擬器;        | 設計之模擬器;            | designed for military "nuclear | "nuclear reactors";                           |
|         |                 |                    | reactors";                     |   |
|         | m. 除歐盟一般軍用貨品清單以 | m. 未列於一般軍用貨品清單管    | m. Ferries, other than those   | m. Ferries, not specified elsewhere in the EU |
| ML17. m | 外,為軍用而特別設計之渡輪、  | 制項目,為軍用而特別設計之渡     | specified elsewhere in the EU  | Common Military List, bridges and pontoons,   |
|         | 橋樑及浮箱;          | 輪、橋樑及浮箱;           | Common Military List, bridges  | specially designed for military use;          |

| 修正條目   | 現行內容            | 擬修正/新增內容          | 現行內容英譯                       | 擬修正/新增內容英譯                                     |
|--------|-----------------|-------------------|------------------------------|--|
|        |                 |                   | and pontoons, specially      |  |
|        |                 |                   | designed for military use;   |  |
|        | p. 除歐盟一般軍用貨品清單以 | p. 未列於一般軍用貨品清單管   | p. "Fuel cells" other than   | p. "Fuel cells", not specified elsewhere in    |
|        | 外其他`燃料電池´,其為軍事  | 制項目,為軍事用途特別設計或    | those specified elsewhere in | the EU Common Military List, specially         |
| ML17.p | 用途特別設計或改裝者。     | 改裝者之`燃料電池´。       | the EU Common Military List, | designed or 'modified' for military use.       |
|        |                 |                   | specially designed or        |  |
|        |                 |                   | 'modified' for military use. |  |
|        | 無               | `使用者可程式化`係指允許使    | -                            | 'User-accessible programmability' refers to    |
|        |                 | 用者插入、修改或更换"程式"    |                              | the facility allowing a user to insert, modify |
|        |                 | 之設施,不包括下列方法:      |                              | or replace "programs" by means other than:     |
|        |                 | a. 以佈線或互連改變實體;或   |                              | a. A physical change in wiring or              |
|        |                 | b. 功能控制設定,包括輸入參   |                              | interconnections; or                           |
|        |                 | 數。                |                              | b. The setting of function controls including  |
|        |                 |                   |                              | entry of parameters.                           |
| 術語定義   | 無               | ML11 "衛星導航系統"     | _                            | ML11 "Satellite navigation system" A system    |
| 侧品及我   |                 | 由地面站、衛星與接收器組成之    |                              | consisting of ground stations, a               |
|        |                 | 系統,其具有由衛星接收訊號計    |                              | constellation of satellites, and receivers,    |
|        |                 | 算接收器位置之能力。包括全球    |                              | that enables receiver locations to be          |
|        |                 | 衛星導航系統(GNSS)與區域衛星 |                              | calculated on the basis of signals received    |
|        |                 | 導航系統(RNSS)。       |                              | from the satellites. It includes Global        |
|        |                 |                   |                              | Navigation Satellite Systems (GNSS) and        |
|        |                 |                   |                              | Regional Navigation Satellite Systems          |
|        |                 |                   |                              | (RNSS).  |